

# ANALOG 14-Bit, 1 GSPS/820 Wish should make a DEVICES JESD204B, Dual Analog-to-Digital Converter

AD9680 **Data Sheet** 

#### **FEATURES**

JESD204B (Subclass 1) coded serial digital outputs 1.65 W total power per channel at 1 GSPS (default settings) SFDR at 1 GSPS = 85 dBFS at 340 MHz, 80 dBFS at 1 GHz SNR at 1 GSPS = 65.3 dBFS at 340 MHz ( $A_{IN} = -1.0$  dBFS), 60.5 dBFS at 1 GHz ( $A_{IN} = -1.0 dBFS$ )

ENOB = 10.8 bits at 10 MHz

 $DNL = \pm 0.5 LSB$ 

 $INL = \pm 2.5 LSB$ 

Noise density = -154 dBFS/Hz at 1 GSPS

1.25 V, 2.5 V, and 3.3 V dc supply operation

No missing codes

Internal ADC voltage reference

Flexible input range

AD9680-1000 and AD9680-820: 1.46 V p-p to 1.94 V p-p

(1.70 V p-p nominal)

AD9680-500: 1.46 V p-p to 2.06 V p-p (2.06 V p-p nominal)

Programmable termination impedance

400  $\Omega$ , 200  $\Omega$ , 100  $\Omega$ , and 50  $\Omega$  differential

2 GHz usable analog input full power bandwidth

95 dB channel isolation/crosstalk

Amplitude detect bits for efficient AGC implementation

2 integrated wideband digital processors per channel

12-bit NCO, up to 4 cascaded half-band filters

**Differential clock input** 

Integer clock divide by 1, 2, 4, or 8

Flexible JESD204B lane configurations

Small signal dither

#### **APPLICATIONS**

**Communications** 

Diversity multiband, multimode digital receivers

3G/4G, TD-SCDMA, W-CDMA, GSM, LTE

**General-purpose software radios** 

Ultrawideband satellite receivers

Instrumentation

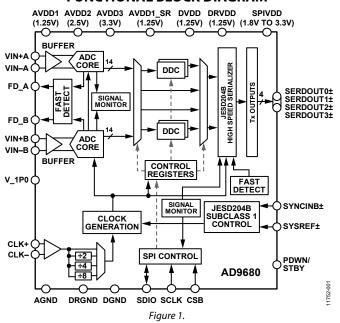
**Radars** 

Signals intelligence (SIGINT)

**DOCSIS 3.0 CMTS upstream receive paths** 

HFC digital reverse path receivers

#### FUNCTIONAL BLOCK DIAGRAM



#### **PRODUCT HIGHLIGHTS**

- Wide full power bandwidth supports IF sampling of signals up to 2 GHz.
- Buffered inputs with programmable input termination eases filter design and implementation.
- Four integrated wideband decimation filters and numerically controlled oscillator (NCO) blocks supporting multiband receivers.
- Flexible serial port interface (SPI) controls various product features and functions to meet specific system requirements.
- Programmable fast overrange detection.
- 9 mm × 9 mm, 64-lead LFCSP.

## AD9680

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#### **REVISION HISTORY**

3/15—Rev. A to Rev. B	
Added AD9680-820Univ	ersal
Changes to Features Section	1
Changes to Table 1	5
Changes to Table 2	6
Changes to Table 3	
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Added Figure 14; Renumbered Sequentially	15
Added AD9680-820 Section and Figure 31 Through Figure 3.	19
Added Figure 37 Through Figure 42	
Added Figure 43 Through Figure 48	
Added Figure 49 Through Figure 54	
Added Figure 55	
Changes to Figure 69 and Figure 70	
Changes to Input Buffer Control Registers (0x018, 0x019, 0x01	
0x935, 0x934, 0x11A) Section, Table 9, and Figure 93	
Added Figure 99 Through Figure 100	
Changes to Table 10	34
Changes to Clock Jitter Considerations Section	37
Added Figure 112	
Changes to Digital Downconverter (DDC) Section	
Changes to Table 17	
Changes to Table 36	
Changes to Ordering Guide	
12/14—Rev. 0 to Rev. A	
Added AD9680-500Univ	ersal
Changes to Features Section and Figure 1	1
Changes to General Description Section	4
Changes to Specifications Section and Table 1	
Changes to AC Specifications Section and Table 2	6
Changes to Digital Specifications Section	8
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Changes to Table 6, Thermal Characteristics Section, and	
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Change to Digital Inputs Description, Table 8	13
Added AD9680-1000 Section, Figure 10, and Figure 11;	
Renumbered Sequentially	14
Changes to Figure 6 to Figure 9	
Added Figure 12 to Figure 14	15
Changes to Figure 15 to Figure 17	
Changes to Figure 18 to Figure 21	
Changes to Figure 25 and Figure 29	

Changes to Figure 3018
Deleted Figure 35, Figure 36, and Figure 3819
Added AD9680-500 Section and Figure 31 to Figure 3619
Added Figure 37 Through 4220
Added Figure 43 Through 4821
Added Figure 49 Through 5422
Changes to Analog Input Considerations Section and
Differential Input Configurations Section25
Added Input Buffer Control Registers (0x018, 0x019, 0x01A,
0x935, 0x934, 0x11A) Section, Figure 66, Figure 68, and Table 9;
Renumbered Sequentially
Changes to Analog Input Buffer Controls and SFDR
Optimization Section and Figure 6726
Added Figure 69 to Figure 7227
Added Figure 73 to Figure 7528
Changes to Table 10
Added Input Clock Divider 1/2 Period Delay Adjust Section and
Clock Fine Delay Adjust Section30
Changes to Figure 83 and Temperature Diode Section31
Added Signal Monitor Section and Figure 86 to Figure 8933 $$
Changes to Table 1139
Changes to Table 12 to Table 1440
Changes to Table 1641
Deleted Figure 65 and Figure 6645
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5/14—Revision 0: Initial Version

#### **GENERAL DESCRIPTION**

The AD9680 is a dual, 14-bit, 1 GSPS/500 MSPS analog-to-digital converter (ADC). The device has an on-chip buffer and sample-and-hold circuit designed for low power, small size, and ease of use. This device is designed for sampling wide bandwidth analog signals of up to 2 GHz. The AD9680 is optimized for wide input bandwidth, high sampling rate, excellent linearity, and low power in a small package.

The dual ADC cores feature a multistage, differential pipelined architecture with integrated output error correction logic. Each ADC features wide bandwidth inputs supporting a variety of user-selectable input ranges. An integrated voltage reference eases design considerations.

The analog input and clock signals are differential inputs. Each ADC data output is internally connected to two digital down-converters (DDCs). Each DDC consists of four cascaded signal processing stages: a 12-bit frequency translator (NCO), and four half-band decimation filters. The DDCs are bypassed by default.

In addition to the DDC blocks, the AD9680 has several functions that simplify the automatic gain control (AGC)

function in the communications receiver. The programmable threshold detector allows monitoring of the incoming signal power using the fast detect output bits of the ADC. If the input signal level exceeds the programmable threshold, the fast detect indicator goes high. Because this threshold indicator has low latency, the user can quickly turn down the system gain to avoid an overrange condition at the ADC input.

Users can configure the Subclass 1 JESD204B-based high speed serialized output in a variety of one-, two-, or four-lane configurations, depending on the DDC configuration and the acceptable lane rate of the receiving logic device. Multiple device synchronization is supported through the SYSREF $\pm$  and SYNCINB $\pm$  input pins.

The AD9680 has flexible power-down options that allow significant power savings when desired. All of these features can be programmed using a 1.8 V to 3.3 V capable 3-wire SPI.

The AD9680 is available in a Pb-free, 64-lead LFCSP and is specified over the  $-40^{\circ}$ C to  $+85^{\circ}$ C industrial temperature range. This product is protected by a U.S. patent.

# **SPECIFICATIONS** DC SPECIFICATIONS

 $AVDD1 = 1.25 \text{ V}, AVDD2 = 2.5 \text{ V}, AVDD3 = 3.3 \text{ V}, AVDD1\_SR = 1.25 \text{ V}, DVDD = 1.25 \text{ V}, DRVDD = 1.25 \text{ V}, SPIVDD = 1.8 \text{ V}, specified maximum sampling rate for each speed grade, } A_{IN} = -1.0 \text{ dBFS}, clock divider = 2, default SPI settings, } T_A = 25^{\circ}\text{C}, unless otherwise noted.}$ 

Table 1.

		-	D9680-	500	A	D9680-8	320	Αľ	<b>09680-1</b>	000	
Parameter	Temperature	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
RESOLUTION	Full	14			14			14			Bits
ACCURACY											
No Missing Codes	Full		Guarante	ed	(	Guarante	ed		Guarante	ed	
Offset Error	Full	-0.3	0	+0.3	-0.3	0	+0.3	-0.31	0	+0.31	% FSR
Offset Matching	Full		0	0.3		0	0.23		0	0.23	% FSR
Gain Error	Full	-6	0	+6	-6	0	+6	-6	0	+6	% FSR
Gain Matching	Full		1	5.1		1	5.5		1	4.5	% FSR
Differential Nonlinearity (DNL)	Full	-0.6	±0.5	+0.7	-0.7	±0.5	+0.8	-0.7	±0.5	+0.8	LSB
Integral Nonlinearity (INL)	Full	-4.5	±2.5	+5.0	-3.3	±2.5	+4.3	-5.7	±2.5	+6.9	LSB
TEMPERATURE DRIFT											
Offset Error	Full		-3			-10			-12		ppm/°C
Gain Error	Full		±25			±54			±13.8		ppm/°C
INTERNAL VOLTAGE REFERENCE											
Voltage	Full		1.0			1.0			1.0		V
INPUT-REFERRED NOISE											
$V_{REF} = 1.0 \text{ V}$	25°C		2.06			2.46			2.63		LSB rms
ANALOG INPUTS											
Differential Input Voltage Range (Programmable)	Full	1.46	2.06	2.06	1.46	1.70	1.94	1.46	1.70	1.94	V p-p
Common-Mode Voltage (V <sub>CM</sub> )	25°C		2.05			2.05			2.05		V
Differential Input Capacitance <sup>1</sup>	25°C		1.5			1.5			1.5		pF
Analog Input Full Power Bandwidth	25°C		2			2			2		GHz
POWER SUPPLY											
AVDD1	Full	1.22	1.25	1.28	1.22	1.25	1.28	1.22	1.25	1.28	V
AVDD1 AVDD2	Full	2.44	2.50		2.44	2.50	2.56		2.50		V
AVDD3	Full	3.2	3.3	2.56 3.4	3.2	3.3	2.56 3.4	2.44 3.2	3.3	2.56 3.4	V
AVDD1_SR	Full	1.22	3.3 1.25	1.28	1.22	3.3 1.25	3. <del>4</del> 1.28	1.22	3.3 1.25	1.28	V
DVDD	Full	1.22	1.25	1.28	1.22	1.25	1.28	1.22	1.25	1.28	V
DRVDD	Full	1.22	1.25		1.22		1.28	1.22	1.25	1.28	V
SPIVDD	Full	1.7	1.25	1.28 3.4	1.7	1.25 1.8	3.4	1.7	1.25	3.4	V
	Full	1.7	1.6 435	3. <del>4</del> 467	1.7	605	5. <del>4</del> 660	1.7	685	3. <del>4</del> 720	mA
lavdd1	Full		433 395	463		490	545		595	680	
l <sub>AVDD2</sub>	Full		395 87	463 101		490 125	545 140		595 125	142	mA mA
IAVDD3	Full		87 15	22		125 15	140 18		125 16	142	mA mA
IAVDD1_SR	Full										
l <sub>DVDD</sub> <sup>2</sup>	Full		145 190	152 237		205 200	246 240		208 200	269 225	mA m A
$I_{DRVDD}^{1}$	Full 25°C			23/		200 N/A <sup>3</sup>	240		200 N/A <sup>3</sup>	225	mA m A
$I_{DRVDD}$ (L = 2 mode)	Full		140	6			6			6	mA m A
SPIVDD	ruli	L	5	6	ļ	5	6	L	5	6	mA

		AD9680-500		AD9680-820			AD9680-1000				
Parameter	Temperature	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
POWER CONSUMPTION											
Total Power Dissipation (Including Output Drivers) <sup>2,4</sup>	Full		2.2			2.9			3.3		W
Total Power Dissipation (L = 2 Mode)	25°C		2.1			N/A³			N/A³		
Power-Down Dissipation	Full		700			820			835		mW
Standby <sup>5</sup>	Full		1.2			1.3			1.4		W

<sup>&</sup>lt;sup>1</sup> All lanes running. Power dissipation on DRVDD changes with lane rate and number of lanes used.

#### **AC SPECIFICATIONS**

AVDD1 = 1.25 V, AVDD2 = 2.5 V, AVDD3 = 3.3 V,  $AVDD1\_SR = 1.25 \text{ V}$ , DVDD = 1.25 V, DRVDD = 1.25 V, SPIVDD = 1.8 V, specified maximum sampling rate for each speed grade,  $A_{IN} = -1.0 \text{ dBFS}$ , clock divider = 2, default SPI settings,  $T_A = 25^{\circ}\text{C}$ , unless otherwise noted.

Table 2.

_		Al	D9680-500	)	A	9680-	320	AD	9680-1	000	
Parameter <sup>1</sup>	Temperature	Min	Тур 1	Иaх	Min	Тур	Max	Min	Тур	Max	Unit
ANALOG INPUT FULL SCALE	Full		2.06			1.7			1.7		V p-p
NOISE DENSITY <sup>2</sup>	Full		-153			-153			-154		dBFS/Hz
SIGNAL-TO-NOISE RATIO (SNR) <sup>3</sup>											
$f_{IN} = 10 MHz$	25°C		69.2			67.2			67.2		dBFS
$f_{IN} = 170 \text{ MHz}$	Full	67.8	69.0		65.6	67.0		65.1	66.6		dBFS
$f_{IN} = 340 \text{ MHz}$	25°C		68.6			66.5			65.3		dBFS
$f_{IN} = 450 \text{ MHz}$	25°C		68.0			65.1			64.0		dBFS
$f_{IN} = 765 \text{ MHz}$	25°C		64.4			64.0			61.5		dBFS
$f_{IN} = 985 \text{ MHz}$	25°C		63.8			63.4			60.5		dBFS
$f_{IN} = 1950 \text{ MHz}$	25°C		60.5			59.7			57.0		dBFS
SNR AND DISTORTION RATIO (SINAD) <sup>3</sup>											
$f_{IN} = 10 \text{ MHz}$	25°C		69.0			67.1			67.1		dBFS
$f_{IN} = 170 \text{ MHz}$	Full	67.6	68.8		65.2	66.8		65.0	66.4		dBFS
$f_{IN} = 340 \text{ MHz}$	25°C		68.4			66.3			65.2		dBFS
$f_{IN} = 450 \text{ MHz}$	25°C		67.9			64.7			63.8		dBFS
$f_{IN} = 765 \text{ MHz}$	25°C		64.2			63.5			62.1		dBFS
$f_{IN} = 985 \text{ MHz}$	25°C		63.6			62.7			61.1		dBFS
$f_{IN} = 1950 MHz$	25°C		60.3			58.7			56.0		dBFS
EFFECTIVE NUMBER OF BITS (ENOB)											
$f_{IN} = 10 \text{ MHz}$	25°C		11.2			10.9			10.8		Bits
$f_{IN} = 170 \text{ MHz}$	Full	10.9	11.1		10.5	10.8		10.5	10.7		Bits
$f_{IN} = 340 \text{ MHz}$	25°C		11.1			10.7			10.5		Bits
$f_{IN} = 450 \text{ MHz}$	25°C		11.0			10.5			10.3		Bits
$f_{IN} = 765 \text{ MHz}$	25°C		10.4			10.3			10.0		Bits
$f_{IN} = 985 MHz$	25°C		10.3			10.1			9.8		Bits
$f_{IN} = 1950 \text{ MHz}$	25°C		9.7			9.5			9.0		Bits

<sup>&</sup>lt;sup>2</sup> Default mode. No DDCs used. L = 4, M = 2, F = 1.

 $<sup>^3</sup>$  N/A means not applicable. At the maximum sample rate, it is not applicable to use L = 2 mode on the JESD204B output interface because this exceeds the maximum lane rate of 12.5 Gbps. L = 2 mode is supported when the equation ((M × N' × (10/8) × f<sub>OUT</sub>)/L) results in a line rate that is  $\leq$ 12.5 Gbps.  $f_{OUT}$  is the output sample rate and is denoted by  $f_S$ /DCM, where DCM is the decimation ratio.

<sup>&</sup>lt;sup>4</sup> Default mode. No DDCs used.

<sup>&</sup>lt;sup>5</sup> Can be controlled by the SPI.

		A	D9680-	500	A	9680-	<b>820</b>	AD	9680-1	000	
Parameter <sup>1</sup>	Temperature	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
SPURIOUS-FREE DYNAMIC RANGE (SFDR) <sup>3</sup>											
$f_{IN} = 10 \text{ MHz}$	25°C		83			91			88		dBFS
$f_{IN} = 170 \text{ MHz}$	Full	80	88		75	83		75	85		dBFS
$f_{IN} = 340 \text{ MHz}$	25°C		83			81			85		dBFS
$f_{IN} = 450 \text{ MHz}$	25°C		81			78			82		dBFS
$f_{IN} = 765 \text{ MHz}$	25°C		80			78			82		dBFS
$f_{IN} = 985 \text{ MHz}$	25°C		75			74			80		dBFS
$f_{IN} = 1950 \text{ MHz}$	25°C		70			70			68		dBFS
WORST HARMONIC, SECOND ORTHIRD <sup>3</sup>											
$f_{IN} = 10 \text{ MHz}$	25°C		-83			-91			-88		dBFS
$f_{IN} = 170 \text{ MHz}$	Full		-88	-80		-83	-75		-85	-75	dBFS
$f_{IN} = 340 \text{ MHz}$	25°C		-83			-81			-85		dBFS
$f_{IN} = 450 \text{ MHz}$	25°C		-81			-78			-82		dBFS
$f_{IN} = 765 \text{ MHz}$	25°C		-80			-78			-82		dBFS
$f_{IN} = 985 \text{ MHz}$	25°C		-75			-74			-80		dBFS
$f_{IN} = 1950 \text{ MHz}$	25°C		-70			-70			-68		dBFS
WORST OTHER, EXCLUDING SECOND OR THIRD HARMONIC <sup>3</sup>											
$f_{IN} = 10 \text{ MHz}$	25°C		-95			-97			-95		dBFS
$f_{IN} = 170 \text{ MHz}$	Full		-95	-82		-93	-80		-94	-81	dBFS
$f_{IN} = 340 \text{ MHz}$	25°C		-93			-91			-88		dBFS
$f_{IN} = 450 \text{ MHz}$	25°C		-93			-90			-86		dBFS
$f_{IN} = 765 \text{ MHz}$	25°C		-88			-83			-81		dBFS
$f_{IN} = 985 \text{ MHz}$	25°C		-89			-84			-82		dBFS
$f_{IN} = 1950 \text{ MHz}$	25°C		-84			-74			-75		dBFS
TWO-TONE INTERMODULATION DISTORTION (IMD), $A_{IN1}$ AND $A_{IN2} = -7$ dBFS											
$f_{IN1} = 185 \text{ MHz}, f_{IN2} = 188 \text{ MHz}$	25°C		-88			-90			-87		dBFS
$f_{IN1} = 338 \text{ MHz}, f_{IN2} = 341 \text{ MHz}$	25°C		-88			-87			-88		dBFS
CROSSTALK <sup>4</sup>	25°C		95			95			95		dB
FULL POWER BANDWIDTH⁵	25°C		2			2			2		GHz
	I -	1			l			l			-

<sup>&</sup>lt;sup>1</sup> See the AN-835 Application Note, *Understanding High Speed ADC Testing and Evaluation*, for definitions and for details on how these tests were completed.

Noise density is measured at a low analog input frequency (30 MHz).
 See Table 10 for the recommended settings for full scale voltage and buffer current settings.
 Crosstalk is measured at 170 MHz with a -1.0 dBFS analog input on one channel and no input on the adjacent channel.

<sup>&</sup>lt;sup>5</sup> Measured with circuit shown in Figure 91.

#### **DIGITAL SPECIFICATIONS**

 $AVDD1 = 1.25 \text{ V}, AVDD2 = 2.5 \text{ V}, AVDD3 = 3.3 \text{ V}, AVDD1\_SR = 1.25 \text{ V}, DVDD = 1.25 \text{ V}, DRVDD = 1.25 \text{ V}, SPIVDD = 1.8 \text{ V}, specified maximum sampling rate for each speed grade, } A_{IN} = -1.0 \text{ dBFS}, clock divider = 2, default SPI settings, } T_A = 25^{\circ}\text{C}, unless otherwise noted.}$ 

Table 3.

Parameter	Temperature	Min	Тур	Max	Unit
CLOCK INPUTS (CLK+, CLK-)					
Logic Compliance	Full		LVDS/LVPECL		
Differential Input Voltage	Full	600	1200	1800	mV p-p
Input Common-Mode Voltage	Full		0.85		٧
Input Resistance (Differential)	Full		35		kΩ
Input Capacitance	Full			2.5	pF
SYSREF INPUTS (SYSREF+, SYSREF-)					
Logic Compliance	Full		LVDS/LVPECL		
Differential Input Voltage	Full	400	1200	1800	mV p-p
Input Common-Mode Voltage	Full	0.6	0.85	2.0	٧
Input Resistance (Differential)	Full		35		kΩ
Input Capacitance (Differential)	Full			2.5	pF
LOGIC INPUTS (SDI, SCLK, CSB, PDWN/STBY)					
Logic Compliance	Full		CMOS		
Logic 1 Voltage	Full	0.8 × SPIVI	DD		٧
Logic 0 Voltage	Full	0		0.5	٧
Input Resistance	Full		30		kΩ
LOGIC OUTPUT (SDIO)					
Logic Compliance	Full		CMOS		
Logic 1 Voltage (I <sub>OH</sub> = 800 μA)	Full	0.8 × SPIVI	OD		٧
Logic 0 Voltage ( $I_{OL} = 50 \mu A$ )	Full	0		0.5	V
SYNCIN INPUT (SYNCINB+/SYNCINB-)					
Logic Compliance	Full		LVDS/LVPECL/CMOS		
Differential Input Voltage	Full	400	1200	1800	mV p-p
Input Common-Mode Voltage	Full	0.6	0.85	2.0	V
Input Resistance (Differential)	Full		35		kΩ
Input Capacitance	Full			2.5	pF
LOGIC OUTPUTS (FD_A, FD_B)					
Logic Compliance	Full		CMOS		
Logic 1 Voltage	Full	0.8 × SPIVI	OD		٧
Logic 0 Voltage	Full	0		0.5	٧
Input Resistance	Full		30		kΩ
DIGITAL OUTPUTS (SERDOUTx±, x = 0 TO 3)					
Logic Compliance	Full		CML		
Differential Output Voltage	Full	360		770	mV p-p
Output Common-Mode Voltage (V <sub>CM</sub> )					
AC-Coupled	25°C	0		1.8	٧
Short-Circuit Current (I <sub>DSHORT</sub> )	25°C	-100		+100	mA
Differential Return Loss (RL <sub>DIFF</sub> ) <sup>1</sup>	25°C	8			dB
Common-Mode Return Loss (RL <sub>CM</sub> ) <sup>1</sup>	25°C	6			dB
Differential Termination Impedance	Full	80	100	120	Ω

 $<sup>^{1}</sup>$  Differential and common-mode return loss are measured from 100 MHz to 0.75  $\times$  baud rate.

#### **SWITCHING SPECIFICATIONS**

AVDD1 = 1.25 V, AVDD2 = 2.5 V, AVDD3 = 3.3 V,  $AVDD1\_SR = 1.25 \text{ V}$ , DVDD = 1.25 V, DRVDD = 1.25 V, SPIVDD = 1.8 V, specified maximum sampling rate for each speed grade,  $A_{IN} = -1.0 \text{ dBFS}$ , default SPI settings,  $T_A = 25^{\circ}\text{C}$ , unless otherwise noted.

Table 4.

		AD	9680-5	00	AD	9680-820	)	AD9	9680-1	000	
Parameter	Temperature	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
CLOCK											
Clock Rate (at CLK+/CLK- Pins)	Full	0.3		4	0.3		4	0.3		4	GHz
Maximum Sample Rate <sup>1</sup>	Full	500			820			1000			MSPS
Minimum Sample Rate <sup>2</sup>	Full	300			300			300			MSPS
Clock Pulse Width High	Full	1000			609.756			500			ps
Clock Pulse Width Low	Full	1000			609.756			500			ps
OUTPUT PARAMETERS											
Unit Interval (UI) <sup>3</sup>	Full	80	200		80	121.95		80	100		ps
Rise Time ( $t_R$ ) (20% to 80% into 100 $\Omega$ Load)	25°C	24	32		24	32		24	32		ps
Fall Time (t <sub>F</sub> ) (20% to 80% into 100 $\Omega$ Load)	25°C	24	32		24	32		24	32		ps
PLL Lock Time	25°C		2			2			2		ms
Data Rate per Channel (NRZ) <sup>4</sup>	25°C	3.125	5	12.5	3.125	8.2	12.5	3.125	10	12.5	Gbps
LATENCY <sup>5</sup>											
Pipeline Latency	Full		55			55			55		Clock
											cycles
Fast Detect Latency	Full			28			28			28	Clock
Wake-Up Time <sup>6</sup>											cycles
Standby	25°C		1			1			1		ms
Power-Down	25°C			4			4			4	ms
APERTURE											
Aperture Delay (t <sub>A</sub> )	Full		530			530			530		ps
Aperture Uncertainty (Jitter, t <sub>i</sub> )	Full		55			55			55		fs rms
Out-of-Range Recovery Time	Full		1			1			1		Clock Cycles

<sup>&</sup>lt;sup>1</sup> The maximum sample rate is the clock rate after the divider.

#### **TIMING SPECIFICATIONS**

Table 5.

Parameter	Test Conditions/Comments	Min	Тур	Max	Unit
CLK+ to SYSREF+ TIMING REQUIREMENTS	See Figure 3				
t <sub>SU_SR</sub>	Device clock to SYSREF+ setup time		117		ps
t <sub>H_SR</sub>	Device clock to SYSREF+ hold time		-96		ps
SPITIMING REQUIREMENTS	See Figure 4				
t <sub>DS</sub>	Setup time between the data and the rising edge of SCLK	2			ns
$t_DH$	Hold time between the data and the rising edge of SCLK	2			ns
t <sub>CLK</sub>	Period of the SCLK	40			ns
$t_S$	Setup time between CSB and SCLK	2			ns
t <sub>H</sub>	Hold time between CSB and SCLK	2			ns
t <sub>HIGH</sub>	Minimum period that SCLK must be in a logic high state	10			ns
t <sub>LOW</sub>	Minimum period that SCLK must be in a logic low state	10			ns
t <sub>en_sdio</sub>	Time required for the SDIO pin to switch from an input to an output relative to the SCLK falling edge (not shown in Figure 4)	10			ns
t <sub>DIS_SDIO</sub>	Time required for the SDIO pin to switch from an output to an input relative to the SCLK rising edge (not shown in Figure 4)	10			ns

 $<sup>^{2}</sup>$  The minimum sample rate operates at 300 MSPS with L = 2 or L = 1.

 $<sup>^{3}</sup>$  Baud rate = 1/UI. A subset of this range can be supported.

 $<sup>^4</sup>$  Default L = 4. This number can be changed based on the sample rate and decimation ratio.

 $<sup>^{5}</sup>$  No DDCs used. L = 4, M = 2, F = 1.

<sup>&</sup>lt;sup>6</sup> Wake-up time is defined as the time required to return to normal operation from power-down mode.

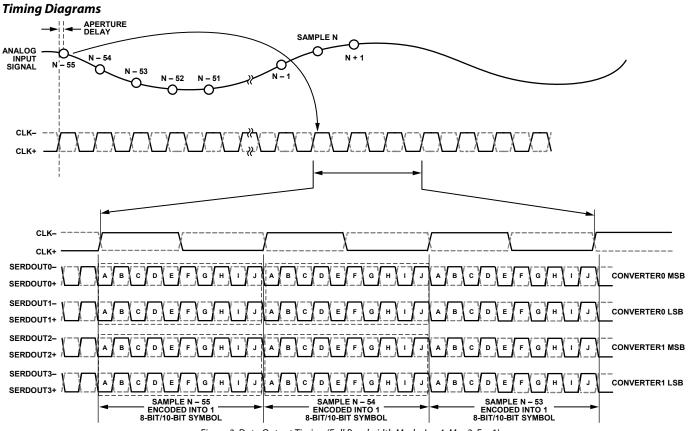


Figure 2. Data Output Timing (Full Bandwidth Mode; L = 4; M = 2; F = 1)

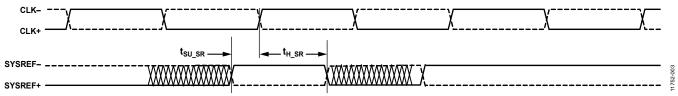


Figure 3. SYSREF± Setup and Hold Timing

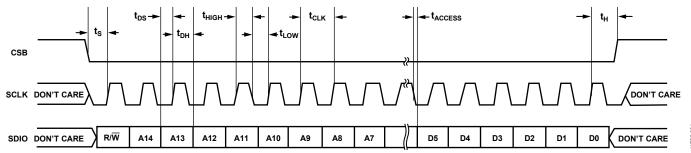


Figure 4. Serial Port Interface Timing Diagram

#### ABSOLUTE MAXIMUM RATINGS

Table 6.

Parameter	Rating
Electrical	
AVDD1 to AGND	1.32 V
AVDD1_SR to AGND	1.32 V
AVDD2 to AGND	2.75 V
AVDD3 to AGND	3.63 V
DVDD to DGND	1.32 V
DRVDD to DRGND	1.32 V
SPIVDD to AGND	3.63 V
AGND to DRGND	-0.3 V to +0.3 V
VIN±x to AGND	3.2 V
SCLK, SDIO, CSB to AGND	-0.3 V to SPIVDD + 0.3 V
PDWN/STBY to AGND	-0.3 V to SPIVDD + 0.3 V
Operating Temperature Range	−40°C to +85°C
Junction Temperature Range	−40°C to +115°C
Storage Temperature Range (Ambient)	−65°C to +150°C

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

#### THERMAL CHARACTERISTICS

Typical  $\theta_{JA}$ ,  $\theta_{JB}$ , and  $\theta_{JC}$  are specified vs. the number of printed circuit board (PCB) layers in different airflow velocities (in m/sec). Airflow increases heat dissipation effectively reducing  $\theta_{JA}$  and  $\theta_{JB}$ . In addition, metal in direct contact with the package leads and exposed pad from metal traces, through holes, ground, and power planes, reduces  $\theta_{JA}$ . Thermal performance for actual applications requires careful inspection of the conditions in an application. The use of appropriate thermal management techniques is recommended to ensure that the maximum junction temperature does not exceed the limits shown in Table 6.

**Table 7. Thermal Resistance Values** 

	PCB Type	Airflow Velocity (m/sec)	θја	$\Psi_{JB}$	Өјс_тор	<b>Ө</b> JС_ВОТ	Unit
	JEDEC	0.0	17.8 <sup>1, 2</sup>	6.3 <sup>1, 3</sup>	4.7 <sup>1, 4</sup>	1.21,4	°C/W
	2s2p Board	1.0	15.6 <sup>1, 2</sup>	5.9 <sup>1, 3</sup>	N/A <sup>5</sup>		°C/W
		2.5	15.0 <sup>1, 2</sup>	5.7 <sup>1, 3</sup>	N/A <sup>5</sup>		°C/W

<sup>&</sup>lt;sup>1</sup> Per JEDEC 51-7, plus JEDEC 51-5 2s2p test board.

#### **ESD CAUTION**



**ESD (electrostatic discharge) sensitive device.**Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

<sup>&</sup>lt;sup>2</sup> Per JEDEC JESD51-2 (still air) or JEDEC JESD51-6 (moving air).

<sup>&</sup>lt;sup>3</sup> Per JEDEC JESD51-8 (still air).

<sup>&</sup>lt;sup>4</sup> Per MIL-STD 883, Method 1012.1.

<sup>&</sup>lt;sup>5</sup> N/A means not applicable.

#### PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

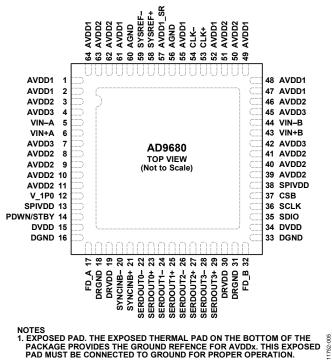


Figure 5. Pin Configuration (Top View)

**Table 8. Pin Function Descriptions** 

Pin No.	Mnemonic	Type	Description			
Power Supplies						
0	EPAD	Ground	Exposed Pad. The exposed thermal pad on the bottom of the package provides the ground reference for AVDDx. This exposed pad must be connected to ground for proper operation.			
1, 2, 47, 48, 49, 52, 55, 61, 64	AVDD1	Supply	Analog Power Supply (1.25 V Nominal).			
3, 8, 9, 10, 11, 39, 40, 41, 46, 50, 51, 62, 63	AVDD2	Supply	Analog Power Supply (2.5 V Nominal).			
4, 7, 42, 45	AVDD3	Supply	Analog Power Supply (3.3 V Nominal).			
13, 38	SPIVDD	Supply	Digital Power Supply for SPI (1.8 V to 3.3 V).			
15, 34	DVDD	Supply	Digital Power Supply (1.25 V Nominal).			
16, 33	DGND	Ground	Ground Reference for DVDD.			
18, 31	DRGND	Ground	Ground Reference for DRVDD.			
19, 30	DRVDD	Supply	Digital Driver Power Supply (1.25 V Nominal).			
56, 60 AGND <sup>1</sup>		Ground	Ground Reference for SYSREF±.			
57	AVDD1_SR <sup>1</sup>	Supply	Analog Power Supply for SYSREF± (1.25 V Nominal).			
Analog						
5, 6	VIN-A, VIN+A	Input	ADC A Analog Input Complement/True.			
12	V_1P0	Input/DNC	1.0 V Reference Voltage Input/Do Not Connect. This pin is configurable through the SPI as a no connect or an input. Do not connect this pin if using the internal reference. Requires a 1.0 V reference voltage input if using an external voltage reference source.			
44, 43	VIN-B, VIN+B	Input	ADC B Analog Input Complement/True.			
53, 54	CLK+, CLK-	Input	Clock Input True/Complement.			

Pin No.	Mnemonic	Туре	Description
CMOS Outputs			
17, 32	FD_A, FD_B	Output	Fast Detect Outputs for Channel A and Channel B.
Digital Inputs			
20, 21	SYNCINB-, SYNCINB+	Input	Active Low JESD204B LVDS Sync Input True/Complement.
58, 59	SYSREF+, SYSREF-	Input	Active High JESD204B LVDS System Reference Input True/Complement.
Data Outputs			
22, 23	SERDOUTO-, SERDOUTO+	Output	Lane 0 Output Data Complement/True.
24, 25 SERDOUT1–, SERDOUT1+		Output	Lane 1 Output Data Complement/True.
26, 27 SERDOUT2+		Output	Lane 2 Output Data Complement/True.
28, 29 SERDOUT3-, SERDOUT3+		Output	Lane 3 Output Data Complement/True.
Device Under Test (DUT) Controls			
14	PDWN/STBY	Input	Power-Down Input (Active High). The operation of this pin depends on the SPI mode and can be configured as powerdown or standby.
35	SDIO	Input/Output	SPI Serial Data Input/Output.
36 SCLK		Input	SPI Serial Clock.
37	CSB	Input	SPI Chip Select (Active Low).

<sup>&</sup>lt;sup>1</sup> To ensure proper ADC operation, connect AVDD1\_SR and AGND separately from the AVDD1 and EPAD connection. For more information, refer to the Applications Information section.

#### TYPICAL PERFORMANCE CHARACTERISTICS

#### AD9680-1000

AVDD1 = 1.25 V, AVDD1\_SR = 1.25 V, AVDD2 = 2.5 V, AVDD3 = 3.3 V, DVDD = 1.25 V, DRVDD = 1.25 V, SPIVDD = 1.8 V, 1.7 V p-p full-scale differential input,  $A_{\rm IN}$  = -1.0 dBFS, default SPI settings, clock divider = 2,  $T_A$  = 25°C, 128k FFT sample, unless otherwise noted. See Table 10 for recommended settings.

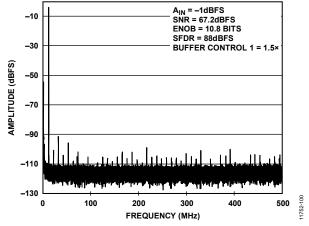


Figure 6. Single-Tone FFT with  $f_{IN} = 10.3 MHz$ 

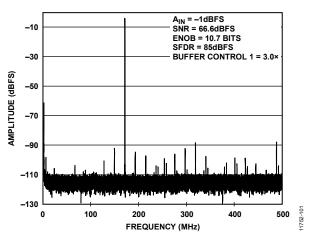


Figure 7. Single-Tone FFT with  $f_{IN} = 170.3 \text{ MHz}$ 

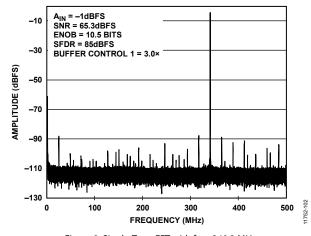


Figure 8. Single-Tone FFT with  $f_{\text{IN}}$  = 340.3 MHz

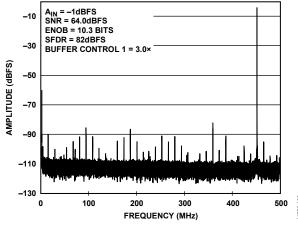


Figure 9. Single-Tone FFT with  $f_{IN} = 450.3 \text{ MHz}$ 

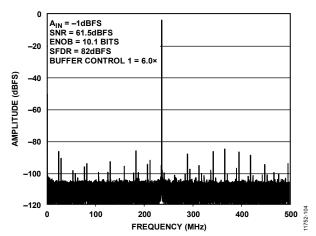


Figure 10. Single-Tone FFT with  $f_{IN} = 765.3 \text{ MHz}$ 

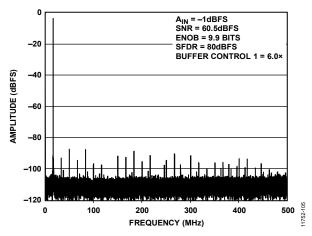


Figure 11. Single-Tone FFT with  $f_{IN} = 985.3 \text{ MHz}$ 

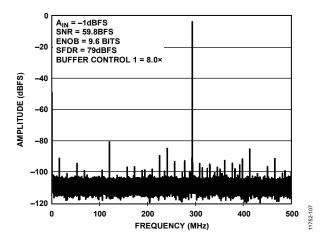


Figure 12. Single-Tone FFT with  $f_{IN} = 1293.3 \text{ MHz}$ 

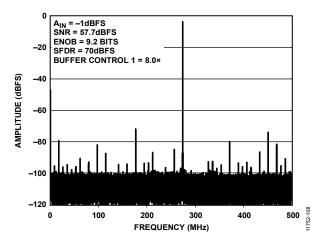


Figure 13. Single-Tone FFT with  $f_{IN} = 1725.3$  MHz

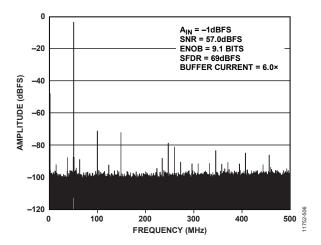


Figure 14. Single-Tone FFT with  $f_{IN} = 1950.3 \text{ MHz}$ 

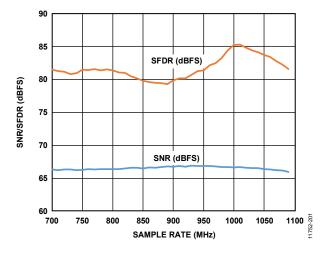


Figure 15. SNR/SFDR vs.  $f_{S}$ ,  $f_{IN}$  = 170.3 MHz; Buffer Control 1 (0x018) = 3.0×

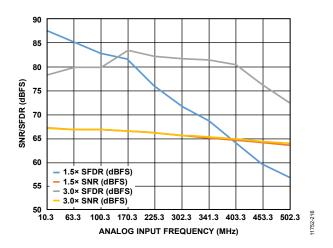


Figure 16. SNR/SFDR vs.  $f_{IN}$ ;  $f_{IN}$  < 500 MHz; Buffer Control 1 (0x018) = 1.5× and 3.0×

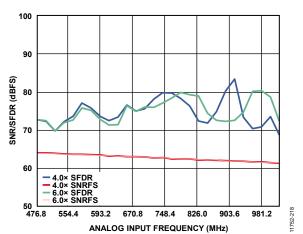


Figure 17. SNR/SFDR vs.  $f_{IN}$ ; 500 MHz <  $f_{IN}$  < 1 GHz; Buffer Control1 (0x018) = 4.0× and 6.0×

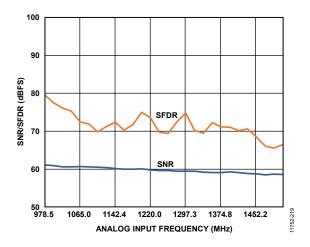


Figure 18. SNR/SFDR vs.  $f_{IN}$ ; 1 GHz <  $f_{IN}$  < 1.5 GHz; Buffer Control 1 (0x018) = 6.0×

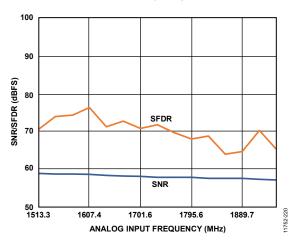


Figure 19. SNR/SFDR vs.  $f_{IN}$ ; 1.5 GHz <  $f_{IN}$  < 2 GHz; Buffer Control 1 (0x018) = 7.5×

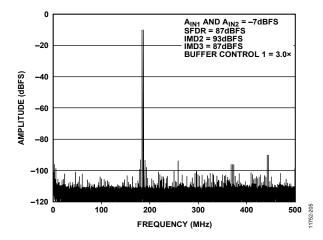


Figure 20. Two-Tone FFT;  $f_{IN1} = 184$  MHz,  $f_{IN2} = 187$  MHz

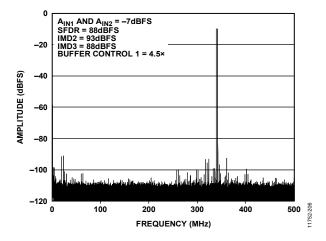


Figure 21. Two-Tone FFT;  $f_{IN1} = 338$  MHz,  $f_{IN2} = 341$  MHz

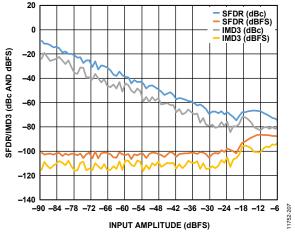


Figure 22. Two-Tone SFDR/IMD3 vs. Input Amplitude ( $A_{IN}$ ) with  $f_{IN1}=184$  MHz and  $f_{IN2}=187$  MHz

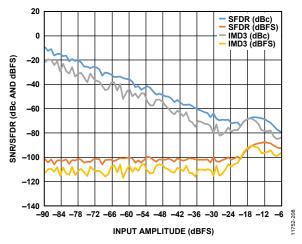


Figure 23. Two-Tone IMD3/SFDR vs. Input Amplitude (A<sub>IN</sub>) with  $f_{\rm IN1}=338$  MHz and  $f_{\rm IN2}=341$  MHz

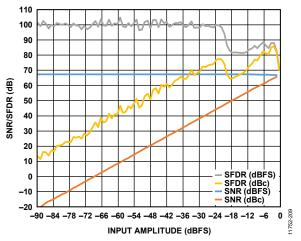


Figure 24. SNR/SFDR vs. Analog Input Level,  $f_{IN} = 170.3 \text{ MHz}$ 

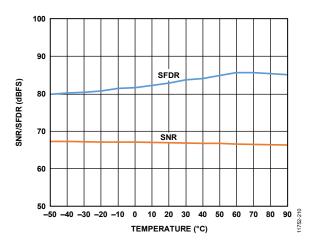
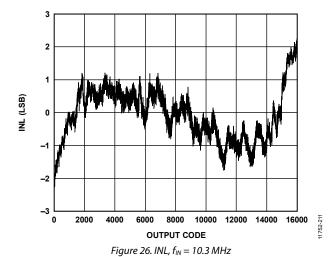


Figure 25. SNR/SFDR vs. Temperature,  $f_{IN} = 170.3 \text{ MHz}$ 



0.6
0.4
0.2
0.0
-0.2
-0.4
-0.6
0 2000 4000 6000 8000 10000 12000 14000 16000
OUTPUT CODE

Figure 27. DNL,  $f_{IN} = 15 MHz$ 

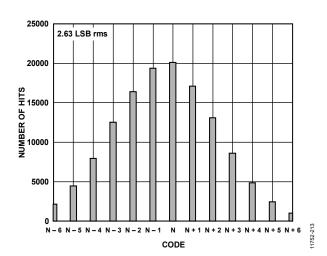


Figure 28. Input-Referred Noise Histogram

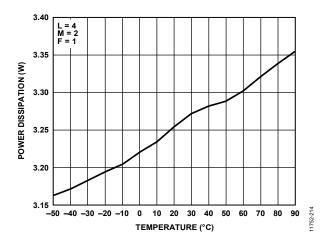


Figure 29. Power Dissipation vs. Temperature

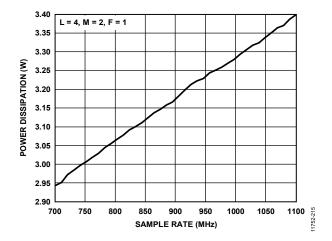


Figure 30. Power Dissipation vs. f<sub>S</sub>

#### AD9680-820

AVDD1 = 1.25 V,  $AVDD1\_SR = 1.25 \text{ V}$ , AVDD2 = 2.5 V, AVDD3 = 3.3 V, DVDD = 1.25 V, DRVDD = 1.25 V, SPIVDD = 1.8 V, 1.7 V p-p full-scale differential input,  $A_{IN} = -1.0 \text{ dBFS}$ , default SPI settings, clock divider = 2,  $T_A = 25^{\circ}\text{C}$ , 128k FFT sample, unless otherwise noted. See Table 10 for recommended settings.

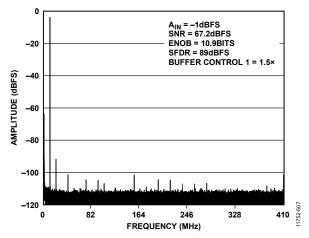


Figure 31. Single-Tone FFT with  $f_{IN} = 10.3 \text{ MHz}$ 

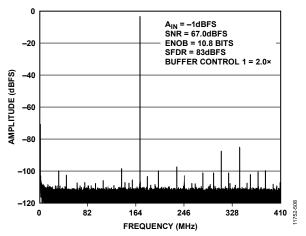


Figure 32. Single-Tone FFT with  $f_{IN} = 170.3 \text{ MHz}$ 

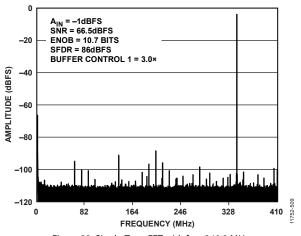


Figure 33. Single-Tone FFT with  $f_{IN} = 340.3 \text{ MHz}$ 

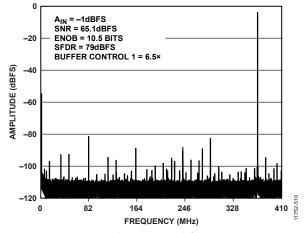


Figure 34. Single-Tone FFT with  $f_{IN} = 450.3 \text{ MHz}$ 

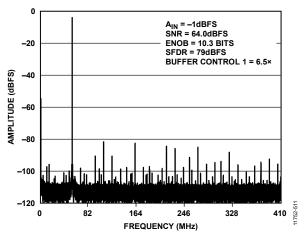


Figure 35. Single-Tone FFT with  $f_{IN} = 765.3$  MHz

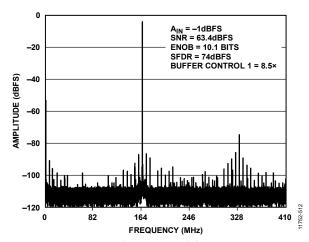


Figure 36. Single-Tone FFT with  $f_{IN} = 985.3$  MHz (Change SFDR to 74dBFS, Buffer Control 1 = 8.5x)

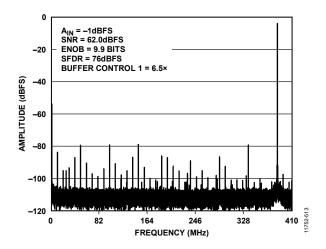


Figure 37. Single-Tone FFT with  $f_{IN} = 1205.3 \text{ MHz}$ 

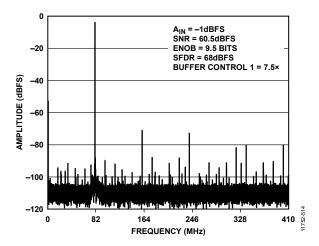


Figure 38. Single-Tone FFT with  $f_{IN} = 1720.3 \text{ MHz}$ 

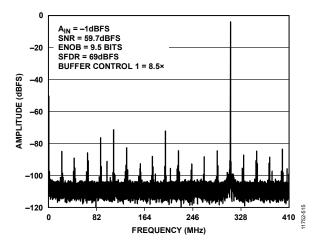


Figure 39. Single-Tone FFT with  $f_{IN} = 1950.3 \text{ MHz}$ 

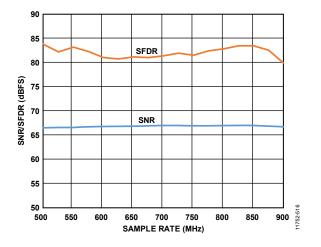


Figure 40. SNR/SFDR vs.  $f_s$ ,  $f_{IN} = 170.3$  MHz; Buffer Control 1 (0x018) = 3.0×

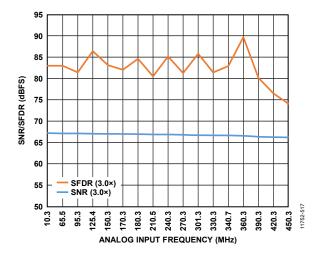


Figure 41. SNR/SFDR vs.  $f_{IN}$ ;  $f_{IN}$  < 450 MHz; Buffer Control 1 (0x018) = 3.0×

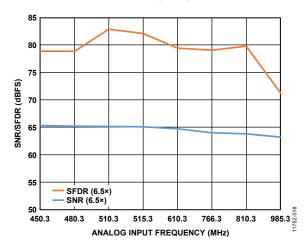


Figure 42. SNR/SFDR vs.  $f_{IN}$ ; 450 MHz <  $f_{IN}$  < 1 GHz; Buffer Control1 (0x018) = 6.5×

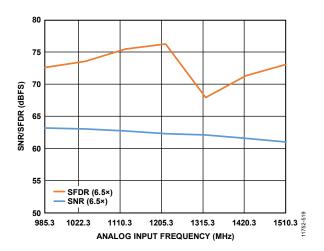


Figure 43. SNR/SFDR vs.  $f_{IN}$ ; 1 GHz <  $f_{IN}$  < 1.5 GHz; Buffer Control 1 (0x018) = 6.5×

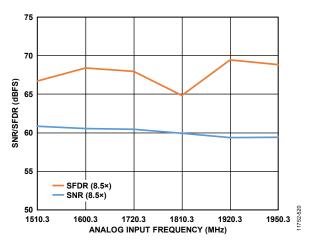


Figure 44. SNR/SFDR vs.  $f_{IN}$ ; 1.5 GHz <  $f_{IN}$  < 2 GHz; Buffer Control 1 (0x018) = 8.5×

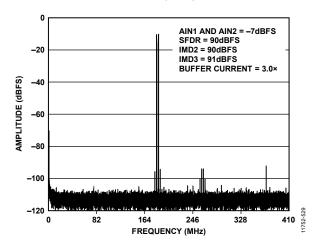


Figure 45. Two-Tone FFT;  $f_{IN1} = 184 \text{ MHz}$ ,  $f_{IN2} = 187 \text{ MHz}$ 

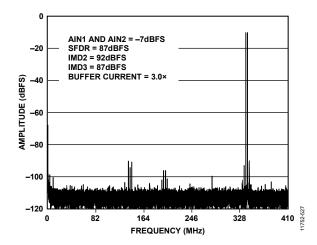


Figure 46. Two-Tone FFT;  $f_{IN1} = 338$  MHz,  $f_{IN2} = 341$  MHz

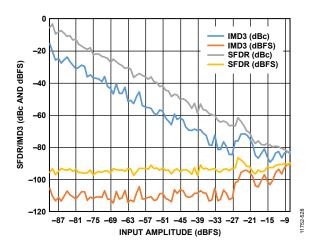


Figure 47. Two-Tone SFDR/IMD3 vs. Input Amplitude (A<sub>IN</sub>) with  $f_{\rm IN1}=184$  MHz and  $f_{\rm IN2}=187$  MHz

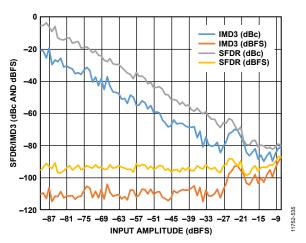


Figure 48. Two-Tone IMD3/SFDR vs. Input Amplitude ( $A_{IN}$ ) with  $f_{IN1} = 338$  MHz and  $f_{IN2} = 341$  MHz

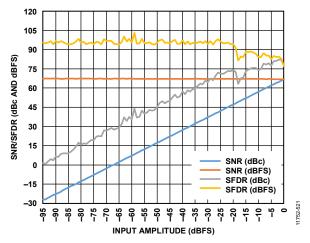


Figure 49. SNR/SFDR vs. Analog Input Level,  $f_{IN} = 170.3 \text{ MHz}$ 

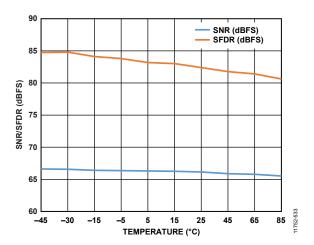


Figure 50. SNR/SFDR vs. Temperature,  $f_{IN} = 170.3 \text{ MHz}$ 

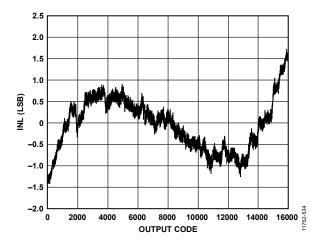


Figure 51. INL,  $f_{IN} = 10.3 MHz$ 

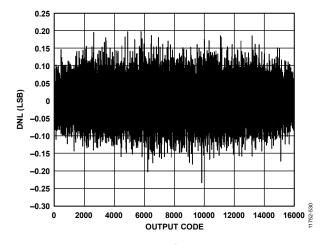


Figure 52. DNL,  $f_{IN} = 15 MHz$ 

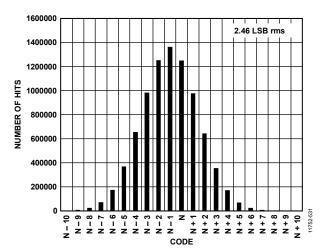


Figure 53. Input-Referred Noise Histogram

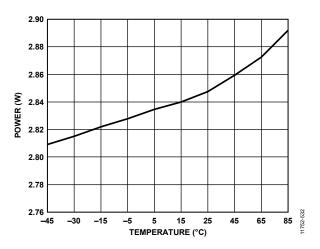


Figure 54. Power Dissipation vs. Temperature

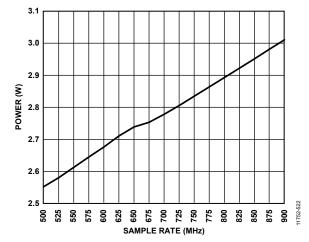


Figure 55. Power Dissipation vs.  $f_S$ ; L = 4, M = 2, F = 1 for  $fS \ge 625$  MSPS and L = 2, M = 2, F = 2 for  $f_S < 625$  MSPS (Default SPI)

#### AD9680-500

AVDD1 = 1.25 V,  $AVDD1\_SR = 1.25 \text{ V}$ , AVDD2 = 2.5 V, AVDD3 = 3.3 V, DVDD = 1.25 V, DRVDD = 1.25 V, SPIVDD = 1.8 V, 2.06 V p-p full-scale differential input,  $A_{IN} = -1.0 \text{ dBFS}$ , default SPI settings, clock divider = 2,  $T_A = 25^{\circ}\text{C}$ , 128k FFT sample, unless otherwise noted. See Table 10 for recommended settings.

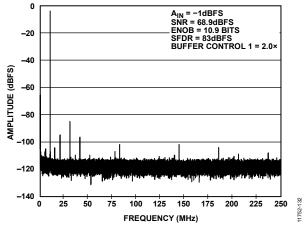


Figure 56. Single-Tone FFT with  $f_{IN} = 10.3 \text{ MHz}$ 

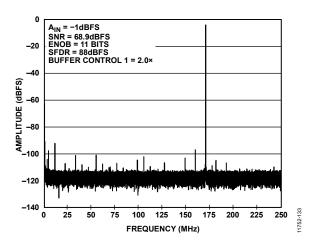


Figure 57. Single-Tone FFT with  $f_{IN} = 170.3 \text{ MHz}$ 

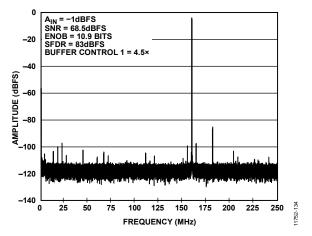


Figure 58. Single-Tone FFT with  $f_{IN} = 340.3 \text{ MHz}$ 

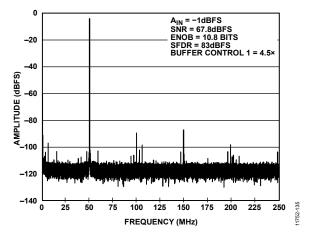


Figure 59. Single-Tone FFT with  $f_{\rm IN}$  = 450.3 MHz

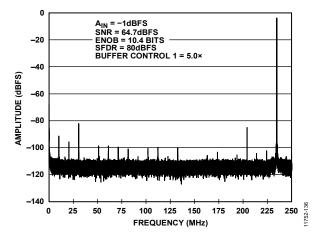


Figure 60. Single-Tone FFT with  $f_{IN} = 765.3 \text{ MHz}$ 

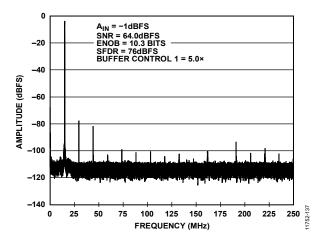


Figure 61. Single-Tone FFT with  $f_{IN} = 985.3 \text{ MHz}$ 

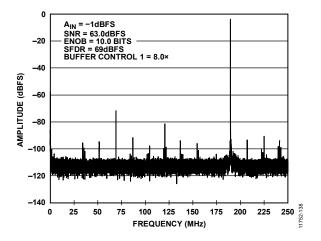


Figure 62. Single-Tone FFT with  $f_{IN} = 1310.3 \text{ MHz}$ 

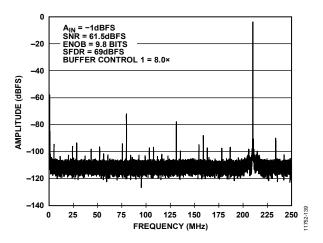


Figure 63. Single-Tone FFT with  $f_{IN} = 1710.3 \text{ MHz}$ 

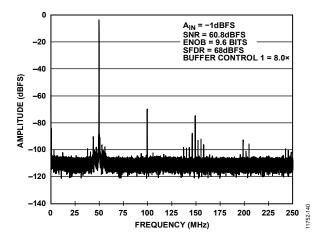


Figure 64. Single-Tone FFT with  $f_{IN} = 1950.3 \text{ MHz}$ 

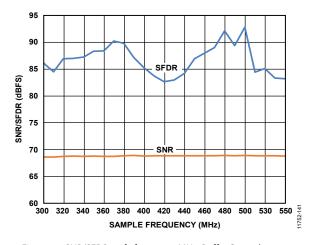


Figure 65. SNR/SFDR vs.  $f_s$ ,  $f_{IN}$  = 170.3 MHz; Buffer Control 1 = 2.0×

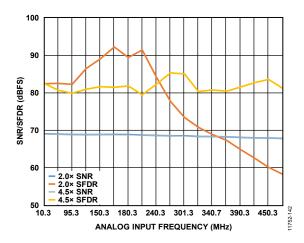


Figure 66. SNR/SFDR vs.  $f_{IN}$ ;  $f_{IN} < 500$  MHz; Buffer Control 1 (0x018) =  $2.0 \times$  and  $4.5 \times$ 

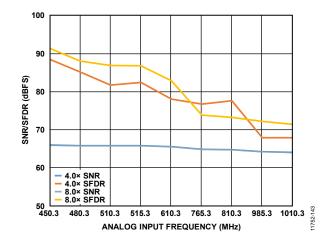


Figure 67. SNR/SFDR vs.  $f_{IN}$ ; 500 MHz <  $f_{IN}$  < 1 GHz; Buffer Control 1 (0x018) = 4.0× and 8.0×

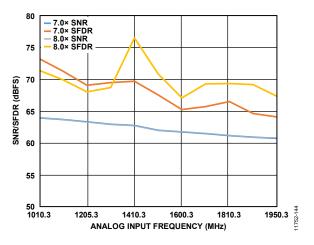


Figure 68. SNR/SFDR vs.  $f_{IN}$ ; 1 GHz <  $f_{IN}$  < 2 GHz; Buffer Control 1 (0x018) = 7.0× and 8.0×

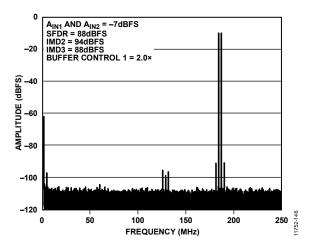


Figure 69. Two-Tone FFT;  $f_{IN1} = 184$  MHz,  $f_{IN2} = 187$  MHz

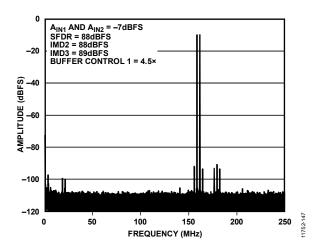


Figure 70. Two-Tone FFT;  $f_{IN1} = 338 \text{ MHz}$ ,  $f_{IN2} = 341 \text{ MHz}$ 

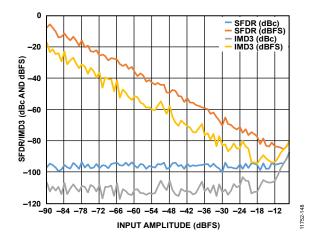


Figure 71. Two-Tone SFDR/IMD3 vs. Input Amplitude ( $A_{IN}$ ) with  $f_{IN1} = 184$  MHz and  $f_{IN2} = 187$  MHz

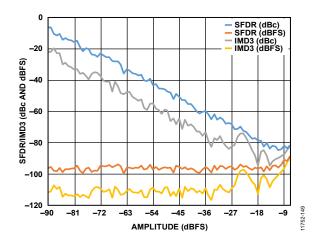


Figure 72. Two-Tone IMD3/SFDR vs. Input Amplitude ( $A_{\rm IN}$ ) with  $f_{\rm IN1}=338$  MHz and  $f_{\rm IN2}=341$  MHz

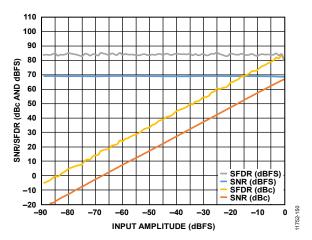


Figure 73. SNR/SFDR vs. Analog Input Level,  $f_{IN} = 170.3 \text{ MHz}$ 

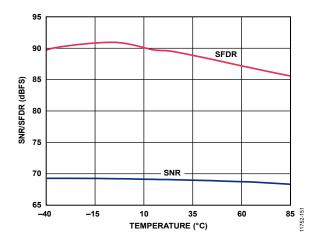


Figure 74. SNR/SFDR vs. Temperature,  $f_{IN} = 170.3 \text{ MHz}$ 

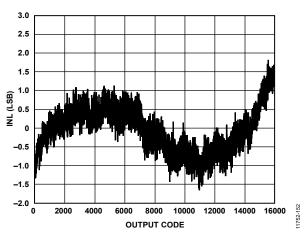


Figure 75. INL,  $f_{IN} = 10.3 MHz$ 

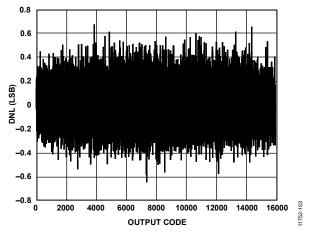


Figure 76. DNL,  $f_{IN} = 15 MHz$ 

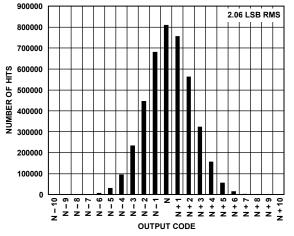


Figure 77. Input-Referred Noise Histogram

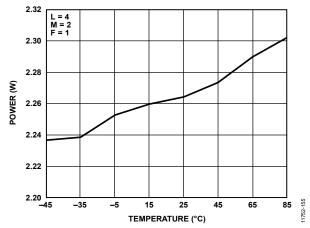


Figure 78. Power Dissipation vs. Temperature

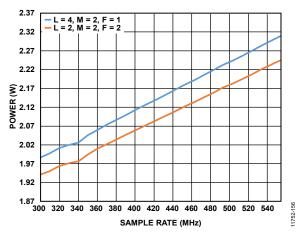


Figure 79. Power Dissipation vs. fs

### **EQUIVALENT CIRCUITS**

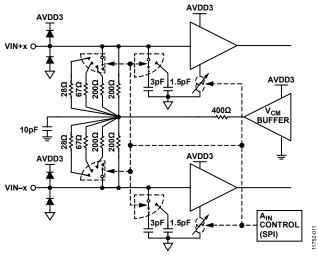


Figure 80. Analog Inputs

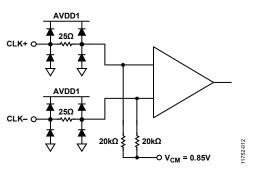
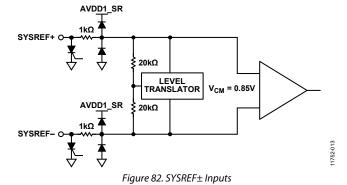


Figure 81. Clock Inputs



DATA+

DATA+

DATA
DATA
DRVDD

SERDOUTx+

x = 0, 1, 2, 3

DRVDD

DRVDD

DRVDD

DRVDD

DRGND

DRVDD

DRGND

Figure 83. Digital Outputs

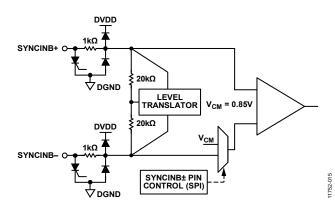
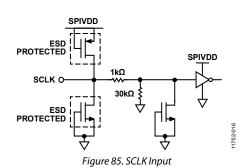


Figure 84. SYNCINB± Inputs



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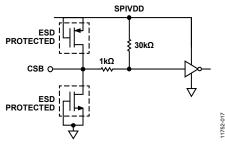


Figure 86. CSB Input

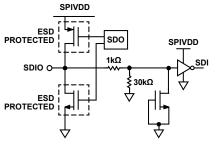


Figure 87. SDIO Input

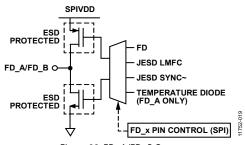


Figure 88. FD\_A/FD\_B Outputs

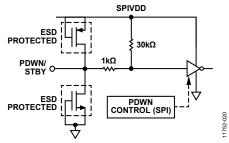


Figure 89. PDWN/STBY Input

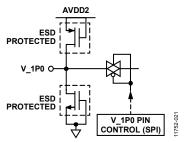


Figure 90. V\_1P0 Input/Output

#### THEORY OF OPERATION

The AD9680 has two analog input channels and four JESD204B output lane pairs. The ADC is designed to sample wide bandwidth analog signals of up to 2 GHz. The AD9680 is optimized for wide input bandwidth, high sampling rate, excellent linearity, and low power in a small package.

The dual ADC cores feature a multistage, differential pipelined architecture with integrated output error correction logic. Each ADC features wide bandwidth inputs supporting a variety of user-selectable input ranges. An integrated voltage reference eases design considerations.

The AD9680 has several functions that simplify the AGC function in a communications receiver. The programmable threshold detector allows monitoring of the incoming signal power using the fast detect output bits of the ADC. If the input signal level exceeds the programmable threshold, the fast detect indicator goes high. Because this threshold indicator has low latency, the user can quickly turn down the system gain to avoid an overrange condition at the ADC input.

The Subclass 1 JESD204B-based high speed serialized output data lanes can be configured in one-lane (L = 1), two-lane (L = 2), and four-lane (L = 4) configurations, depending on the sample rate and the decimation ratio. Multiple device synchronization is supported through the SYSREF $\pm$  and SYNCINB $\pm$  input pins.

#### **ADC ARCHITECTURE**

The architecture of the AD9680 consists of an input buffered pipelined ADC. The input buffer is designed to provide a termination impedance to the analog input signal. This termination impedance can be changed using the SPI to meet the termination needs of the driver/amplifier. The default termination value is set to  $400~\Omega$ . The equivalent circuit diagram of the analog input termination is shown in Figure 80. The input buffer is optimized for high linearity, low noise, and low power.

The input buffer provides a linear high input impedance (for ease of drive) and reduces kickback from the ADC. The buffer is optimized for high linearity, low noise, and low power. The quantized outputs from each stage are combined into a final 14-bit result in the digital correction logic. The pipelined architecture permits the first stage to operate with a new input sample; at the same time, the remaining stages operate with the preceding samples. Sampling occurs on the rising edge of the clock.

#### **ANALOG INPUT CONSIDERATIONS**

The analog input to the AD9680 is a differential buffer. The internal common-mode voltage of the buffer is 2.05 V. The clock signal alternately switches the input circuit between sample mode and hold mode. When the input circuit is switched

into sample mode, the signal source must be capable of charging the sample capacitors and settling within one-half of a clock cycle. A small resistor, in series with each input, can help reduce the peak transient current injected from the output stage of the driving source. In addition, low Q inductors or ferrite beads can be placed on each leg of the input to reduce high differential capacitance at the analog inputs and, thus, achieve the maximum bandwidth of the ADC. Such use of low Q inductors or ferrite beads is required when driving the converter front end at high IF frequencies. Either a differential capacitor or two single-ended capacitors can be placed on the inputs to provide a matching passive network. This ultimately creates a low-pass filter at the input, which limits unwanted broadband noise. For more information, refer to the AN-742 Application Note, the AN-827 Application Note, and the Analog Dialogue article "Transformer-Coupled Front-End for Wideband A/D Converters" (Volume 39, April 2005). In general, the precise values depend on the application.

For best dynamic performance, the source impedances driving VIN+x and VIN-x must be matched such that common-mode settling errors are symmetrical. These errors are reduced by the common-mode rejection of the ADC. An internal reference buffer creates a differential reference that defines the span of the ADC core.

Maximum SNR performance is achieved by setting the ADC to the largest span in a differential configuration. In the case of the AD9680, the available span is programmable through the SPI port from 1.46 V p-p to 2.06 V p-p differential, with 1.70 V p-p differential being the default for the AD9680-1000 and AD9680-820, and 2.06 V p-p differential being the default for the AD9680-500.

#### **Differential Input Configurations**

There are several ways to drive the AD9680, either actively or passively. However, optimum performance is achieved by driving the analog input differentially.

For applications where SNR and SFDR are key parameters, differential transformer coupling is the recommended input configuration (see Figure 91 and Table 9) because the noise performance of most amplifiers is not adequate to achieve the true performance of the AD9680.

For low to midrange frequencies, a double balun or double transformer network (see Figure 91 and Table 9) is recommended for optimum performance of the AD9680. For higher frequencies in the second or third Nyquist zones, it is better to remove some of the front-end passive components to ensure wideband operation (see Figure 91 and Table 9).

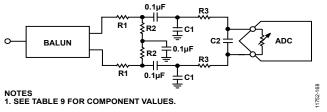


Figure 91. Differential Transformer-Coupled Configuration for AD9680

Table 9. Differential Transformer-Coupled Input Configuration Component Values

Device	Frequency Range	Transformer	R1 (Ω)	R2 (Ω)	R3 (Ω)	C1 (pF)	C2 (pF)
AD9680-500	DC to 250 MHz	ETC1-1-13	10	50	10	4	2
	250 MHz to 2 GHz	BAL-0006/BAL-0006SMG	10	50	10	4	2
AD9680-820	DC to 410 MHz	ETC1-1-13	10	50	10	4	2
	410 MHz to 2 GHz	BAL-0006/BAL-0006SMG	10	50	10	4	2
AD9680-1000	DC to 500 MHz	ETC1-1-13/BAL-0006SMG	25	25	10	4	2
	500 MHz to 2 GHz	BAL-0006/BAL-0006SMG	25	25	0	Open	Open

#### **Input Common Mode**

The analog inputs of the AD9680 are internally biased to the common mode as shown in Figure 92. The common-mode buffer has a limited range in that the performance suffers greatly if the common-mode voltage drops by more than 100 mV. Therefore, in dc-coupled applications, set the common-mode voltage to 2.05 V,  $\pm 100$  mV to ensure proper ADC operation. The full-scale voltage setting must be at a 1.7 V p-p differential if running in a dc-coupled application.

#### **Analog Input Buffer Controls and SFDR Optimization**

The AD9680 input buffer offers flexible controls for the analog inputs, such as input termination, buffer current, and input full-scale adjustment. All the available controls are shown in Figure 92.

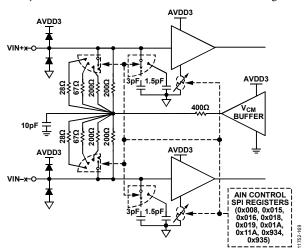


Figure 92. Analog Input Controls

Using the 0x018, 0x019, 0x01A, 0x11A, 0x934, and 0x935 registers, the buffer behavior on each channel can be adjusted to optimize the SFDR over various input frequencies and bandwidths of interest.

# Input Buffer Control Registers (0x018, 0x019, 0x01A, 0x935, 0x934, 0x11A)

The input buffer has many registers that set the bias currents and other settings for operation at different frequencies. These bias currents and settings can be changed to suit the input frequency range of operation. Register 0x018 controls the buffer bias current to help with the kickback from the ADC core. This setting can be scaled from a low setting of 1.0× to a high setting of 8.5×. The default setting is 3.0× for the AD9680-1000 and AD9680-820, and 2.0× for the AD9680-500. These settings are sufficient for operation in the first Nyquist zone for the products. When the input buffer current in Register 0x018 is set, the amount of current required by the AVDD3 supply changes. This relationship is shown in Figure 93. For a complete list of buffer current settings, see Table 36.

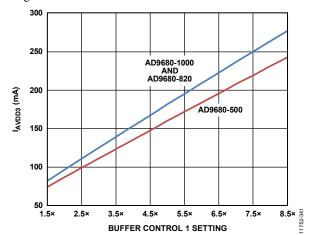


Figure 93. IAVDD3 vs. Buffer Control 1 Setting in Register 0x018

The 0x019, 0x01A, 0x11A, and 0x935 registers offer secondary bias controls for the input buffer for frequencies >500 MHz. Register 0x934 can be used to reduce input capacitance to achieve wider signal bandwidth but may result in slightly lower linearity and noise performance. These register settings do not impact the AVDD3 power as much as Register 0x018 does. For frequencies <500 MHz, it is recommended to use the default settings for these registers. Table 10 shows the recommended values for the buffer current control registers for various speed grades.

Register 0x11A is used when sampling in higher Nyquist zones (>500 MHz for the AD9680-1000). This setting enables the ADC sampling network to optimize the sampling and settling times internal to the ADC for high frequency operation. For frequencies greater than 500 MHz, it is recommended to operate the ADC core at a 1.46 V full-scale setting irrespective of the speed grade. This setting offers better SFDR without any significant penalty in SNR.

Figure 94, Figure 95, and Figure 96 show the SFDR vs. analog input frequency for various buffer settings for the AD9680-1000. The recommended settings shown in Table 10 were used to take the data while changing the contents of Register 0x018 only.

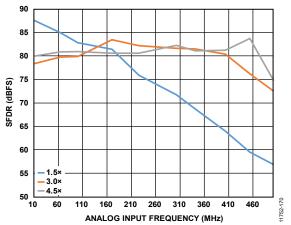


Figure 94. Buffer Current Sweeps, AD9680-1000 (SFDR vs.  $I_{BUFF}$ );  $f_{IN} < 500$  MHz; Front-End Network Shown in Figure 91

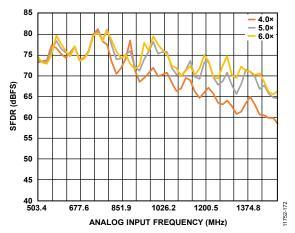


Figure 95. Buffer Current Sweeps, AD9680-1000 (SFDR vs.  $I_{BUFF}$ ); 500 MHz  $< f_{IN} < 1500$  MHz; Front-End Network Shown in Figure 91

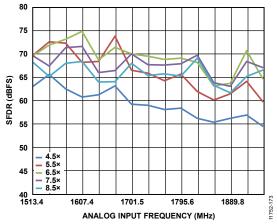


Figure 96. Buffer Current Sweeps, AD9680-1000 (SFDR vs.  $I_{BUFF}$ ); 1500 MHz <  $f_{IN}$  < 2000 MHz; Front-End Network Shown in Figure 91

In certain high frequency applications, the SFDR can be improved by reducing the full-scale setting, as shown in Table 10. At high frequencies, the performance of the ADC core is limited by jitter. The SFDR can be improved by backing off of the full scale level. Figure 97 shows the SFDR and SNR vs. full-scale input level at different high frequencies for the AD9680-1000.

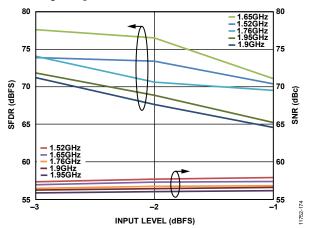


Figure 97. SNR/SFDR vs. Analog Input Level vs. Input Frequencies, AD9680-1000

Figure 98, Figure 99, and Figure 100 show the SFDR vs. analog input frequency for various buffer settings for the AD9680-820. The recommended settings shown in Table 10 were used to take the data while changing the contents of Register 0x018 only.

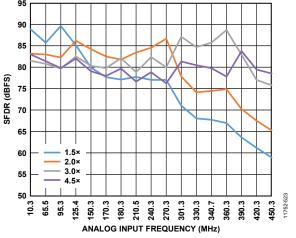


Figure 98. Buffer Current Sweeps, AD9680-820 (SFDR vs.  $I_{BUFF}$ );  $f_{IN} < 500$  MHz; Front-End Network Shown in Figure 91

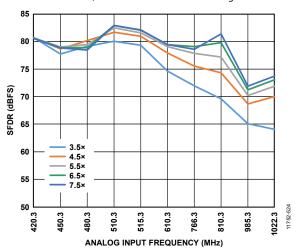


Figure 99. Buffer Current Sweeps, AD9680-820 (SFDR vs.  $I_{BUFF}$ ); 500 MHz <  $f_{IN}$  < 1000 MHz; Front-End Network Shown in Figure 91

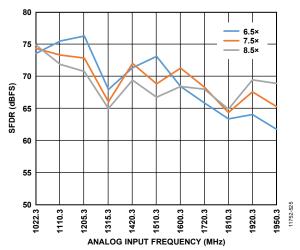


Figure 100. Buffer Current Sweeps, AD9680-820 (SFDR vs.  $I_{BUFF}$ ); 1000 MHz <  $f_{IN}$  < 2000 MHz; Front-End Network Shown in Figure 91

Figure 101, Figure 102, and Figure 103 show the SFDR vs. analog input frequency for various buffer settings for the AD9680-500. The recommended settings shown in Table 10 were used to take the data while changing the contents of Register 0x018 only.

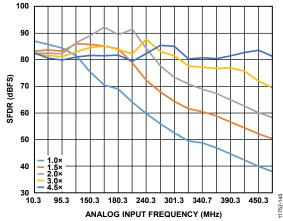


Figure 101. Buffer Current Sweeps, AD9680-500 (SFDR vs.  $l_{BUFF}$ );  $f_{IN}$  < 500MHz; Front-End Network Shown in Figure 91 Buffer Control 1 (0x018) = 1.0×, 1.5×, 2.0×, 3.0×, or 4.5×

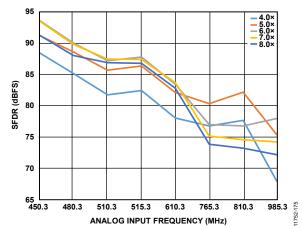


Figure 102. Buffer Current Sweeps, AD9680-500 (SFDR vs. IBUFF);  $450 \text{ MHz} < f_{\text{IN}} < 1000 \text{ MHz}$ ; Front-End Network Shown in Figure 91

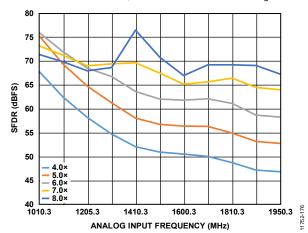


Figure 103. Buffer Current Sweeps, AD9680-500 (SFDR vs.  $I_{BUFF}$ ); 1 GHz  $< f_{IN} < 2$ GHz; Front-End Network Shown in Figure 91

Table 10. Recommended Register Settings for SFDR Optimization at Different Input Frequencies

Product	Frequency	Buffer Control 1 (0x018)— Buffer Current Control	Buffer Control 2 (0x019)— Buffer Bias Setting	Buffer Control 3 (0x01A)— Buffer Bias Setting	Buffer Control 4 (0x11A)— High Frequency Setting	Buffer Control 5 (0x935)— Low Frequency Setting	Input Full-Scale Range (0x025)	Input Full- Scale Control (0x030)	Input Termination (0x016) <sup>1</sup>	Input Capacitance (0x934)
AD9680- 500	DC to 250 MHz	0x20 (2.0×)	0x60 (Setting 3)	0x0A (Setting 3)	0x00 (off)	0x04 (on)	0x0C (2.06 V p-p)	0x04	0x0C/0x1C/	0x1F
	250 MHz to 500 MHz	0x70 (4.5×)	0x60 (Setting 3)	0x0A (Setting 3)	0x00 (off)	0x04 (on)	0x0C (2.06 V p-p)	0x04	0x0C/0x1C/	0x1F
	500 MHz to 1 GHz	0x80 (5.0×)	0x40 (Setting 1)	0x08 (Setting 1)	0x00 (off)	0x00 (off)	0x08 (1.46 V p-p)	0x18	0x0C/0x1C/	0x1F or 0x00 <sup>2</sup>
	1 GHz to 2 GHz	0xF0 (8.5×)	0x40 (Setting 1)	0x08 (Setting 1)	0x00 (off)	0x00 (off)	0x08 (1.46 V p-p)	0x18	0x0C/0x1C/	0x1F or 0x00 <sup>1</sup>
AD9680- 820	DC to 200 MHz	0x10 (1.5×)	0x40 (Setting 1)	0x09 (Setting 2)	0x00 (off)	0x04 (on)	0x0A (1.70 V p-p)	0x14	0x0C/0x1C/	0x1F
	DC to 410 MHz	0x40 (3.0×)	0x40 (Setting 1)	0x09 (Setting 2)	0x00 (off)	0x04 (on)	0x0A (1.70 V p-p)	0x14	0x0C/0x1C/	0x1F
	500 MHz to 1 GHz	0x80 (5.0×)	0x40 (Setting 1)	0x08 (Setting 1)	0x00 (off)	0x00 (off)	0x08 (1.46 V p-p)	0x18	0x0C/0x1C/	0x1F or 0x00 <sup>2</sup>
	1 GHz to 2 GHz	0xF0 (8.5×)	0x40 (Setting 1)	0x08 (Setting 1)	0x00 (off)	0x00 (off)	0x08 (1.46 V p-p)	0x18	0x0C/0x1C/	0x1F or 0x00 <sup>1</sup>
AD9680- 1000	DC to 150 MHz	0x10 (1.5×)	0x50 (Setting 2)	0x09 (Setting 2)	0x00 (off)	0x04 (on)	0x0A (1.70 V p-p)	0x18	0x0E/0x1E/	0x1F
	DC to 500 MHz	0x40 (3.0×)	0x50 (Setting 2)	0x09 (Setting 2)	0x00 (off)	0x04 (on)	0x0A (1.70 V p-p)	0x18	0x0E/0x1E/	0x1F
	500 MHz to 1 GHz	0xA0 (6.0×)	0x60 (Setting 3)	0x09 (Setting 2)	0x20 (on)	0x00 (off)	0x08 (1.46 V p-p)	0x18	0x0E/0x1E/	0x1F or 0x00 <sup>1</sup>
	1 GHz to 2 GHz	0xD0 (7.5×)	0x70 (Setting 4)	0x09 (Setting 2)	0x20 (on)	0x00 (off)	0x08 (1.46 V p-p)	0x18	0x0E/0x1E/	0x1F or 0x00 <sup>1</sup>

 $<sup>^1</sup>$  The input termination can be changed to accommodate the application with little or no impact to ac performance.  $^2$  The input capacitance can be set to 1.5 pF to achieve wider input bandwidth but results in slightly lower ac performance.

#### **Absolute Maximum Input Swing**

The absolute maximum input swing allowed at the inputs of the AD9680 is 4.3 V p-p differential. Signals operating near or at this level can cause permanent damage to the ADC.

#### **VOLTAGE REFERENCE**

A stable and accurate 1.0 V voltage reference is built into the AD9680. This internal 1.0 V reference is used to set the full-scale input range of the ADC. The full-scale input range can be adjusted via the ADC Function Register 0x025. For more information on adjusting the input swing, see Table 36. Figure 104 shows the block diagram of the internal 1.0 V reference controls.

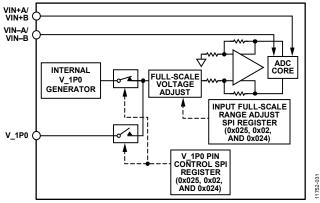


Figure 104. Internal Reference Configuration and Controls

The SPI Register 0x024 enables the user to either use this internal 1.0 V reference, or to provide an external 1.0 V reference. When using an external voltage reference, provide a 1.0 V reference. The full-scale adjustment is made using the SPI, irrespective of

the reference voltage. For more information on adjusting the full-scale level of the AD9680, refer to the Memory Map Register Table section.

The use of an external reference may be necessary, in some applications, to enhance the gain accuracy of the ADC or to improve thermal drift characteristics. Figure 105 shows the typical drift characteristics of the internal 1.0 V reference.

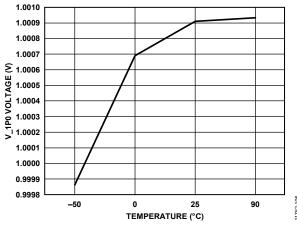


Figure 105. Typical V\_1P0 Drift

The external reference must be a stable 1.0 V reference. The ADR130 is a good option for providing the 1.0 V reference. Figure 106 shows how the ADR130 can be used to provide the external 1.0 V reference to the AD9680. The grayed out areas show unused blocks within the AD9680 while using the ADR130 to provide the external reference.

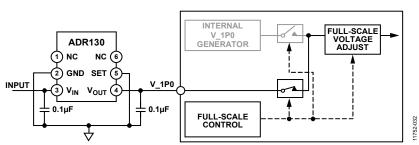


Figure 106. External Reference Using ADR130

#### **CLOCK INPUT CONSIDERATIONS**

For optimum performance, drive the AD9680 sample clock inputs (CLK+ and CLK-) with a differential signal. This signal is typically ac-coupled to the CLK+ and CLK- pins via a transformer or clock drivers. These pins are biased internally and require no additional biasing.

Figure 107 shows a preferred method for clocking the AD9680. The low jitter clock source is converted from a single-ended signal to a differential signal using an RF transformer.

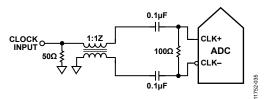


Figure 107. Transformer-Coupled Differential Clock

Another option is to ac couple a differential CML or LVDS signal to the sample clock input pins, as shown in Figure 108 and Figure 109.

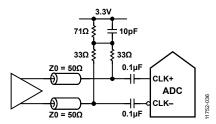


Figure 108. Differential CML Sample Clock

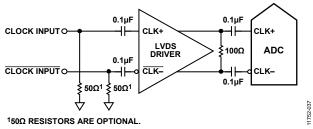


Figure 109. Differential LVDS Sample Clock

#### **Clock Duty Cycle Considerations**

Typical high speed ADCs use both clock edges to generate a variety of internal timing signals. As a result, these ADCs may be sensitive to clock duty cycle. Commonly, a 5% tolerance is required on the clock duty cycle to maintain dynamic performance characteristics. In applications where the clock duty cycle cannot be guaranteed to be 50%, a higher multiple frequency clock can be supplied to the device. The AD9680 can be clocked at 2 GHz with the internal clock divider set to 2. The output of the divider offers a 50% duty cycle, high slew rate (fast edge) clock signal to the internal ADC. See the Memory Map section for more details on using this feature.

#### **Input Clock Divider**

The AD9680 contains an input clock divider with the ability to divide the Nyquist input clock by 1, 2, 4, and 8. The divider ratios can be selected using Register 0x10B. This is shown in Figure 110.

The maximum frequency at the CLK± inputs is 4 GHz. This is the limit of the divider. In applications where the clock input is a multiple of the sample clock, care must be taken to program the appropriate divider ratio into the clock divider before applying the clock signal. This ensures that the current transients during device startup are controlled.

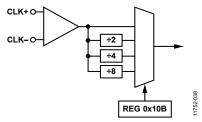


Figure 110. Clock Divider Circuit

The AD9680 clock divider can be synchronized using the external SYSREF± input. A valid SYSREF± causes the clock divider to reset to a programmable state. This synchronization feature allows multiple devices to have their clock dividers aligned to guarantee simultaneous input sampling. See the Multichip Synchronization section for more information.

#### Input Clock Divider 1/2 Period Delay Adjust

The input clock divider inside the AD9680 provides phase delay in increments of ½ the input clock cycle. Register 0x10C can be programmed to enable this delay independently for each channel. Changing this register does not affect the stability of the JESD204B link.

#### **Clock Fine Delay Adjust**

The AD9680 sampling edge instant can be adjusted by writing to Register 0x117 and Register 0x118. Setting Bit 0 of Register 0x117 enables the feature, and Bits[7:0] of Register 0x118 set the value of the delay. This value can be programmed individually for each channel. The clock delay can be adjusted from -151.7 ps to +150 ps in  $\sim 1.7$  ps increments. The clock delay adjust takes effect immediately when it is enabled via SPI writes. Enabling the clock fine delay adjust in Register 0x117 causes a datapath reset. However, the contents of Register 0x118 can be changed without affecting the stability of the JESD204B link.

#### **Clock Jitter Considerations**

High speed, high resolution ADCs are sensitive to the quality of the clock input. The degradation in SNR at a given input frequency  $(f_A)$  due only to aperture jitter  $(t_J)$  can be calculated by

$$SNR = 20 \times \log 10 (2 \times \pi \times f_A \times t_J)$$

In this equation, the rms aperture jitter represents the root mean square of all jitter sources, including the clock input, analog input signal, and ADC aperture jitter specifications.

IF undersampling applications are particularly sensitive to jitter (see Figure 111).

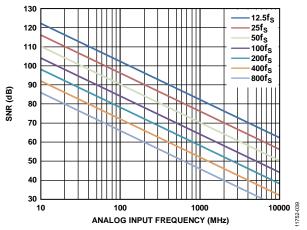


Figure 111. Ideal SNR vs. Input Frequency and Jitter

Treat the clock input as an analog signal in cases where aperture jitter may affect the dynamic range of the AD9680. Separate power supplies for clock drivers from the ADC output driver supplies to avoid modulating the clock signal with digital noise. If the clock is generated from another type of source (by gating, dividing, or other methods), retime the clock by the original clock at the last step. Refer to the AN-501 Application Note and the AN-756 Application Note for more in-depth information about jitter performance as it relates to ADCs.

Figure 112 shows the estimated SNR of the AD9680-1000 across input frequency for different clock induced jitter values. The SNR can be estimated by using the following equation:

Figure 112. Estimated SNR Degradation for the AD9680-1000 vs.
Input Frequency and RMS Jitter

#### Power-Down/Standby Mode

The AD9680 has a PDWN/STBY pin that can be used to configure the device in power-down or standby mode. The default operation is PDWN. The PDWN/STBY pin is a logic high pin. When in power-down mode, the JESD204B link is disrupted. The power-down option can also be set via Register 0x03F and Register 0x040.

In standby mode, the JESD204B link is not disrupted and transmits zeros for all converter samples. This can be changed using Register 0x571, Bit 7 to select /K/ characters.

### **Temperature Diode**

The AD9680 contains a diode-based temperature sensor for measuring the temperature of the die. This diode can output a voltage and serve as a coarse temperature sensor to monitor the internal die temperature.

The temperature diode voltage can be output to the FD\_A pin using the SPI. Use Register 0x028, Bit 0 to enable or disable the diode. Register 0x028 is a local register. Channel A must be selected in the device index register (0x008) to enable the temperature diode readout. Configure the FD\_A pin to output the diode voltage by programming Register 0x040[2:0]. See Table 36 for more information.

The voltage response of the temperature diode (SPIVDD = 1.8 V) is shown in Figure 113.

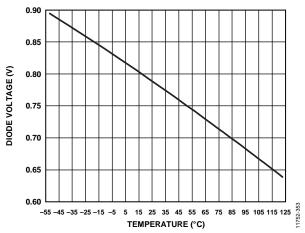


Figure 113. Temperature Diode Voltage vs. Temperature

# ADC OVERRANGE AND FAST DETECT

In receiver applications, it is desirable to have a mechanism to reliably determine when the converter is about to be clipped. The standard overrange bit in the JESD204B outputs provides information on the state of the analog input that is of limited usefulness. Therefore, it is helpful to have a programmable threshold below full scale that allows time to reduce the gain before the clip actually occurs. In addition, because input signals can have significant slew rates, the latency of this function is of major concern. Highly pipelined converters can have significant latency. The AD9680 contains fast detect circuitry for individual channels to monitor the threshold and assert the FD\_A and FD\_B pins.

#### **ADC OVERRANGE**

The ADC overrange indicator is asserted when an overrange is detected on the input of the ADC. The overrange indicator can be embedded within the JESD204B link as a control bit (when CSB > 0). The latency of this overrange indicator matches the sample latency.

The AD9680 also records any overrange condition in any of the eight virtual converters. For more information on the virtual converters, refer to Figure 119. The overrange status of each virtual converter is registered as a sticky bit in Register 0x563. The contents of Register 0x563 can be cleared using Register 0x562, by toggling the bits corresponding to the virtual converter to set and reset position.

# FAST THRESHOLD DETECTION (FD\_A AND FD\_B)

The FD bit is immediately set whenever the absolute value of the input signal exceeds the programmable upper threshold level. The FD bit is only cleared when the absolute value of the input signal drops below the lower threshold level for greater than the programmable dwell time. This feature provides hysteresis and prevents the FD bit from excessively toggling. The operation of the upper threshold and lower threshold registers, along with the dwell time registers, is shown in Figure 114.

The FD indicator is asserted if the input magnitude exceeds the value programmed in the fast detect upper threshold registers, located at Register 0x247 and Register 0x248. The selected threshold register is compared with the signal magnitude at the output of the ADC. The fast upper threshold detection has a latency of 28 clock cycles (maximum). The approximate upper threshold magnitude is defined by

*Upper Threshold Magnitude* (dBFS) = 20 log (*Threshold Magnitude*/2<sup>13</sup>)

The FD indicators are not cleared until the signal drops below the lower threshold for the programmed dwell time. The lower threshold is programmed in the fast detect lower threshold registers, located at Register 0x249 and Register 0x24A. The fast detect lower threshold register is a 13-bit register that is compared with the signal magnitude at the output of the ADC. This comparison is subject to the ADC pipeline latency, but is accurate in terms of converter resolution. The lower threshold magnitude is defined by

Lower Threshold Magnitude (dBFS) = 20 log (Threshold Magnitude/2<sup>13</sup>)

For example, to set an upper threshold of -6 dBFS, write 0xFFF to Register 0x247 and Register 0x248. To set a lower threshold of -10 dBFS, write 0xA1D to Register 0x249 and Register 0x24A.

The dwell time can be programmed from 1 to 65,535 sample clock cycles by placing the desired value in the fast detect dwell time registers, located at Register 0x24B and Register 0x24C. See the Memory Map section (Register 0x040, and Register 0x245 to Register 0x24C in Table 36) for more details.

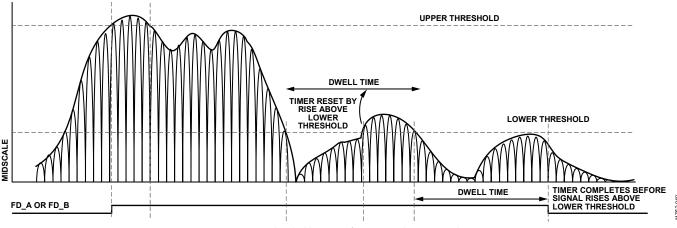


Figure 114. Threshold Settings for FD\_A and FD\_B Signals

1752-087

# SIGNAL MONITOR

The signal monitor block provides additional information about the signal being digitized by the ADC. The signal monitor computes the peak magnitude of the digitized signal. This information can be used to drive an AGC loop to optimize the range of the ADC in the presence of real-world signals.

The results of the signal monitor block can be obtained either by reading back the internal values from the SPI port or by embedding the signal monitoring information into the JESD204B interface as special control bits. A global, 24-bit programmable period controls the duration of the measurement. Figure 115 shows the simplified block diagram of the signal monitor block.

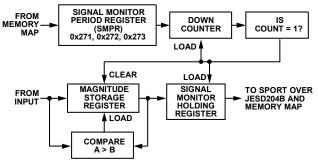


Figure 115. Signal Monitor Block

The peak detector captures the largest signal within the observation period. The detector only observes the magnitude of the signal. The resolution of the peak detector is a 13-bit value, and the observation period is 24 bits and represents

converter output samples. The peak magnitude can be derived by using the following equation:

 $Peak\ Magnitude\ (dBFS) = 20log(Peak\ Detector\ Value/2^{13})$ 

The magnitude of the input port signal is monitored over a programmable time period, which is determined by the signal monitor period register (SMPR). The peak detector function is enabled by setting Bit 1 of Register 0x270 in the signal monitor control register. The 24-bit SMPR must be programmed before activating this mode.

After enabling peak detection mode, the value in the SMPR is loaded into a monitor period timer, which decrements at the decimated clock rate. The magnitude of the input signal is compared with the value in the internal magnitude storage register (not accessible to the user), and the greater of the two is updated as the current peak level. The initial value of the magnitude storage register is set to the current ADC input signal magnitude. This comparison continues until the monitor period timer reaches a count of 1.

When the monitor period timer reaches a count of 1, the 13-bit peak level value is transferred to the signal monitor holding register, which can be read through the memory map or output through the SPORT over the JESD204B interface. The monitor period timer is reloaded with the value in the SMPR, and the countdown restarts. In addition, the magnitude of the first input sample is updated in the magnitude storage register, and the comparison and update procedure, as explained previously, continues.

#### **SPORT OVER JESD204B**

The signal monitor data can also be serialized and sent over the JESD204B interface as control bits. These control bits must be deserialized from the samples to reconstruct the statistical data. The signal control monitor function is enabled by setting Bits[1:0] of Register 0x279 and Bit 1 of Register 0x27A. Figure 116 shows two different example configurations for the signal monitor control bit locations inside the JESD204B samples. A maximum of three control bits can be inserted into the JESD204B samples; however, only one control bit is required for the signal monitor. Control bits are inserted from MSB to LSB. If only one control bit

is to be inserted (CS = 1), only the most significant control bit is used (see Example Configuration 1 and Example Configuration 2 in Figure 116). To select the SPORT over JESD204B option, program Register 0x559, Register 0x55A, and Register 0x58F. See Table 36 for more information on setting these bits.

Figure 117 shows the 25-bit frame data that encapsulates the peak detector value. The frame data is transmitted MSB first with five 5-bit subframes. Each subframe contains a start bit that can be used by a receiver to validate the deserialized data. Figure 118 shows the SPORT over JESD204B signal monitor data with a monitor period timer set to 80 samples.

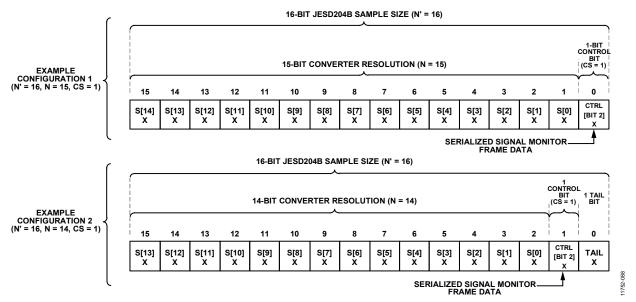


Figure 116. Signal Monitor Control Bit Locations

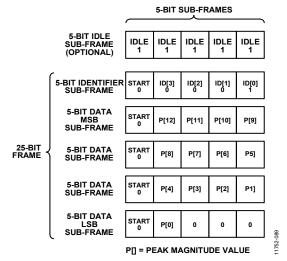


Figure 117. SPORT over JESD204B Signal Monitor Frame Data

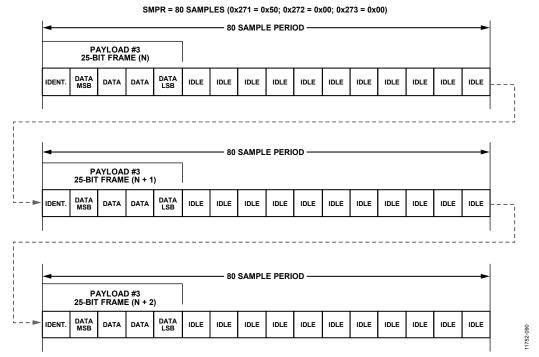


Figure 118. SPORT over JESD204B Signal Monitor Example with Period = 80 Samples

# **DIGITAL DOWNCONVERTER (DDC)**

The AD9680 includes four digital downconverters (DDC 0 to DDC 3) that provide filtering and reduce the output data rate. This digital processing section includes an NCO, a half-band decimating filter, an FIR filter, a gain stage, and a complex-real conversion stage. Each of these processing blocks has control lines that allow it to be independently enabled and disabled to provide the desired processing function. The digital downconverter can be configured to output either real data or complex output data.

The DDCs output a 16-bit stream. To enable this operation, the converter number of bits, N, is set to a default value of 16, even though the analog core only outputs 14 bits. In full bandwidth operation, the ADC outputs are the 14-bit word followed by two zeros, unless the tail bits are enabled.

# **DDC I/Q INPUT SELECTION**

The AD9680 has two ADC channels and four DDC channels. Each DDC channel has two input ports that can be paired to support both real or complex inputs through the I/Q crossbar mux. For real signals, both DDC input ports must select the same ADC channel (for example, DDC Input Port I = ADC Channel A, and Input Port Q = ADC Channel A). For complex signals, each DDC input port must select different ADC channels (for example, DDC Input Port I = ADC Channel A, and Input Port Q = ADC Channel B).

The inputs to each DDC are controlled by the DDC input selection registers (Register 0x311, Register 0x331, Register 0x351, and Register 0x371). See Table 36 for information on how to configure the DDCs.

## **DDC I/Q OUTPUT SELECTION**

Each DDC channel has two output ports that can be paired to support both real or complex outputs. For real output signals, only the DDC Output Port I is used (the DDC Output Port Q is invalid). For complex I/Q output signals, both DDC Output Port I and DDC Output Port Q are used.

The I/Q outputs to each DDC channel are controlled by the DDC complex to real enable bit (Bit 3) in the DDC control registers (Register 0x310, Register 0x330, Register 0x350, and Register 0x370).

The Chip Q ignore bit (Bit 5) in the chip application mode register (Register 0x200) controls the chip output muxing of all the DDC channels. When all DDC channels use real outputs, this bit must be set high to ignore all DDC Q output ports. When any of the DDC channels are set to use complex I/Q outputs, the user must clear this bit to use both DDC Output Port I and DDC Output Port Q. For more information, see Figure 127.

#### **DDC GENERAL DESCRIPTION**

The four DDC blocks are used to extract a portion of the full digital spectrum captured by the ADC(s). They are intended for IF sampling or oversampled baseband radios requiring wide bandwidth input signals.

Each DDC block contains the following signal processing stages:

# Frequency Translation Stage (Optional)

The frequency translation stage consists of a 12-bit complex NCO and quadrature mixers that can be used for frequency translation of both real or complex input signals. This stage shifts a portion of the available digital spectrum down to baseband.

# Filtering Stage

After shifting down to baseband, the filtering stage decimates the frequency spectrum using a chain of up to four half-band low-pass filters for rate conversion. The decimation process lowers the output data rate, which in turn reduces the output interface rate.

## Gain Stage (Optional)

Due to losses associated with mixing a real input signal down to baseband, the gain stage compensates by adding an additional 0 dB or 6 dB of gain.

#### Complex to Real Conversion Stage (Optional)

When real outputs are necessary, the complex to real conversion stage converts the complex outputs back to real by performing an  $f_s/4$  mixing operation plus a filter to remove the complex component of the signal.

Figure 119 shows the detailed block diagram of the DDCs implemented in the AD9680.

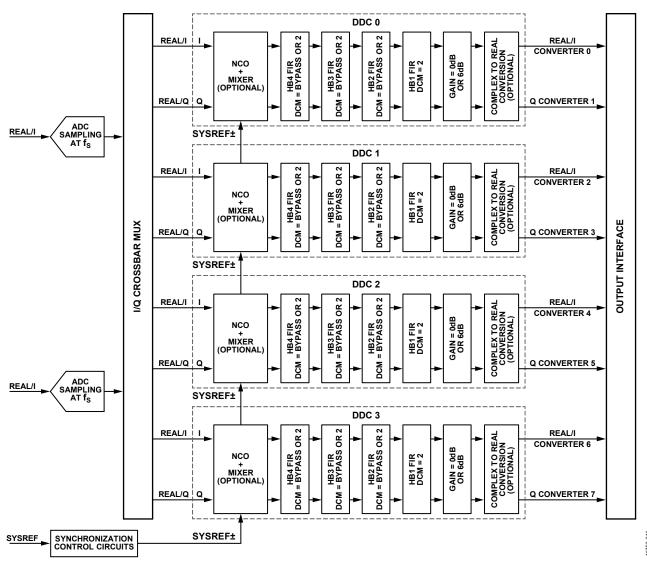


Figure 119. DDC Detailed Block Diagram

Figure 120 shows an example usage of one of the four DDC blocks with a real input signal and four half-band filters (HB4, HB3, HB2, and HB1). It shows both complex (decimate by 16) and real (decimate by 8) output options.

When DDCs have different decimation ratios, the chip decimation ratio (Register 0x201) must be set to the lowest decimation ratio of all the DDC blocks. In this scenario, samples of higher decimation ratio DDCs are repeated to match

the chip decimation ratio sample rate. Whenever the NCO frequency is set or changed, the DDC soft reset must be issued. If the DDC soft reset is not issued, the output may potentially show amplitude variations.

Table 11, Table 12, Table 13, Table 14, and Table 15 show the DDC samples when the chip decimation ratio is set to 1, 2, 4, 8, or 16, respectively.

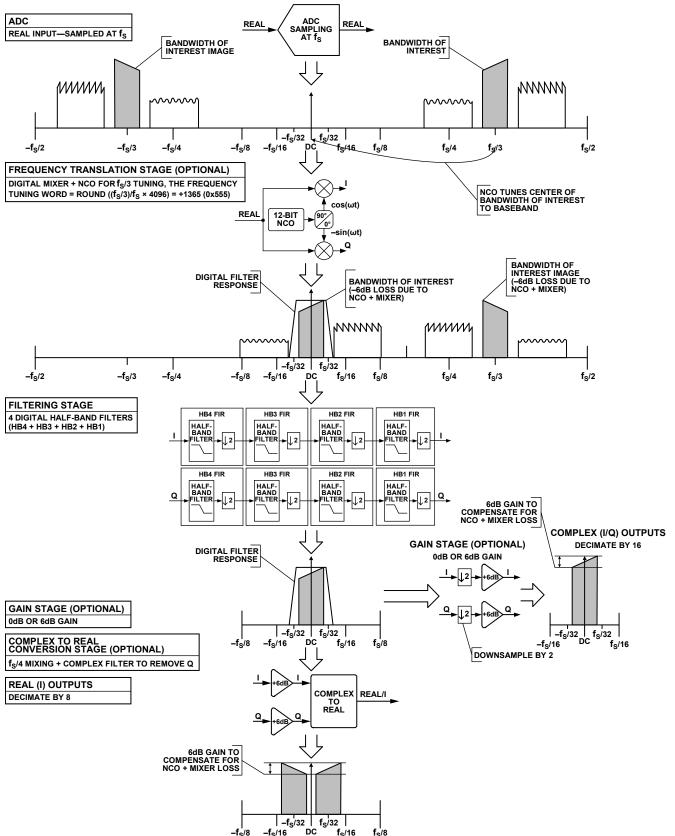


Figure 120. DDC Theory of Operation Example (Real Input—Decimate by 16)

**Table 11. DDC Samples, Chip Decimation Ratio = 1** 

Real (I) Output (Complex to Real Enabled)			Complex (I/Q) Outputs (Complex to Real Disabled)				
HB1 FIR (DCM <sup>1</sup> = 1)	HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 2)	HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 4)	HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 8)	HB1 FIR (DCM <sup>1</sup> = 2)	HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 4)	HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 8)	HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 16)
N	N	N	N	N	N	N	N
N + 1	N + 1	N + 1	N + 1	N + 1	N + 1	N + 1	N + 1
N + 2	N	N	N	N	N	N	N
N + 3	N + 1	N + 1	N + 1	N + 1	N + 1	N + 1	N + 1
N + 4	N + 2	N	N	N + 2	N	N	N
N + 5	N + 3	N + 1	N + 1	N + 3	N + 1	N + 1	N + 1
N + 6	N + 2	N	N	N + 2	N	N	N
N + 7	N + 3	N + 1	N + 1	N + 3	N + 1	N + 1	N + 1
N + 8	N + 4	N + 2	N	N + 4	N + 2	N	N
N + 9	N + 5	N + 3	N + 1	N + 5	N + 3	N + 1	N + 1
N + 10	N + 4	N + 2	N	N + 4	N + 2	N	N
N + 11	N + 5	N + 3	N + 1	N + 5	N + 3	N + 1	N + 1
N + 12	N + 6	N + 2	N	N + 6	N + 2	N	N
N + 13	N + 7	N + 3	N + 1	N + 7	N + 3	N + 1	N + 1
N + 14	N + 6	N + 2	N	N + 6	N + 2	N	N
N + 15	N + 7	N + 3	N + 1	N + 7	N + 3	N + 1	N + 1
N + 16	N + 8	N + 4	N + 2	N + 8	N + 4	N + 2	N
N + 17	N + 9	N + 5	N + 3	N + 9	N + 5	N + 3	N + 1
N + 18	N + 8	N + 4	N + 2	N + 8	N + 4	N + 2	N
N + 19	N + 9	N + 5	N + 3	N + 9	N + 5	N + 3	N + 1
N + 20	N + 10	N + 4	N + 2	N + 10	N + 4	N + 2	N
N + 21	N + 11	N + 5	N + 3	N + 11	N + 5	N + 3	N + 1
N + 22	N + 10	N + 4	N + 2	N + 10	N + 4	N + 2	N
N + 23	N + 11	N + 5	N + 3	N + 11	N + 5	N + 3	N + 1
N + 24	N + 12	N + 6	N + 2	N + 12	N + 6	N + 2	N
N + 25	N + 13	N + 7	N + 3	N + 13	N + 7	N + 3	N + 1
N + 26	N + 12	N + 6	N + 2	N + 12	N + 6	N + 2	N
N + 27	N + 13	N + 7	N + 3	N + 13	N + 7	N + 3	N + 1
N + 28	N + 14	N + 6	N + 2	N + 14	N + 6	N + 2	N
N + 29	N + 15	N + 7	N + 3	N + 15	N + 7	N + 3	N + 1
N + 30	N + 14	N + 6	N + 2	N + 14	N + 6	N + 2	N
N + 31	N + 15	N + 7	N + 3	N + 15	N + 7	N + 3	N + 1

<sup>&</sup>lt;sup>1</sup> DCM = decimation.

**Table 12. DDC Samples, Chip Decimation Ratio = 2** 

Real (I) Output (Complex to Real Enabled)			Com	Complex (I/Q) Outputs (Complex to Real Disabled)				
HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 2)	HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 4)	HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 8)	HB1 FIR (DCM¹ = 2)	HB2 FIR + HB1 FIR (DCM¹ = 4)	HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 8)	HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 16)		
N	N	N	N	N	N	N		
N + 1	N + 1	N + 1	N + 1	N + 1	N + 1	N + 1		
N + 2	N	N	N + 2	N	N	N		
N + 3	N + 1	N + 1	N + 3	N + 1	N + 1	N + 1		
N + 4	N + 2	N	N + 4	N + 2	N	N		
N + 5	N + 3	N + 1	N + 5	N + 3	N + 1	N + 1		
N + 6	N + 2	N	N + 6	N + 2	N	N		
N + 7	N + 3	N + 1	N + 7	N + 3	N + 1	N + 1		
N + 8	N + 4	N + 2	N + 8	N + 4	N + 2	N		
N + 9	N + 5	N + 3	N + 9	N + 5	N + 3	N + 1		
N + 10	N + 4	N + 2	N + 10	N + 4	N + 2	N		
N + 11	N + 5	N + 3	N + 11	N + 5	N + 3	N + 1		
N + 12	N + 6	N + 2	N + 12	N + 6	N + 2	N		
N + 13	N + 7	N + 3	N + 13	N + 7	N + 3	N + 1		
N + 14	N + 6	N + 2	N + 14	N + 6	N + 2	N		
N + 15	N + 7	N + 3	N + 15	N + 7	N + 3	N + 1		

<sup>&</sup>lt;sup>1</sup> DCM = decimation.

**Table 13. DDC Samples, Chip Decimation Ratio = 4** 

Real (I) Output (C	Complex to Real Enabled)	Complex (I	/Q) Outputs (Complex to	Real Disabled)
HB3 FIR + HB2 FIR + HB1 FIR (DCM¹ = 4)	HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 8)	HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 4)	HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 8)	HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 16)
N	N	N	N	N
N + 1	N + 1	N + 1	N + 1	N + 1
N + 2	N	N + 2	N	N
N + 3	N + 1	N + 3	N + 1	N + 1
N + 4	N + 2	N + 4	N + 2	N
N + 5	N + 3	N + 5	N + 3	N + 1
N + 6	N + 2	N + 6	N + 2	N
N + 7	N + 3	N + 7	N + 3	N + 1

 $<sup>^{1}</sup>$  DCM = decimation.

Table 14. DDC Samples, Chip Decimation Ratio = 8

Real (I) Output (Complex to Real Enabled)	Complex (I/Q) Output	s (Complex to Real Disabled)
HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 8)	HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 8)	HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 16)
N	N	N
N + 1	N + 1	N + 1
N + 2	N + 2	N
N + 3	N + 3	N + 1
N + 4	N + 4	N + 2
N + 5	N + 5	N + 3
N + 6	N + 6	N + 2
N + 7	N + 7	N + 3

<sup>&</sup>lt;sup>1</sup> DCM = decimation.

**Table 15. DDC Samples, Chip Decimation Ratio = 16** 

Real (I) Output (Complex to Real Enabled)	Complex (I/Q) Outputs (Complex to Real Disabled)
HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM1 = 16)	HB4 FIR + HB3 FIR + HB2 FIR + HB1 FIR (DCM <sup>1</sup> = 16)
Not applicable	N
Not applicable	N + 1
Not applicable	N + 2
Not applicable	N + 3

 $<sup>^{1}</sup>$  DCM = decimation.

If the chip decimation ratio is set to decimate by 4, DDC 0 is set to use HB2 + HB1 filters (complex outputs decimate by 4), and DDC 1 is set to use HB4 + HB3 + HB2 + HB1 filters (real outputs decimate by 8), then DDC 1 repeats its output data two times for every one DDC 0 output. The resulting output samples are shown in Table 16.

Table 16. DDC Output Samples when Chip DCM<sup>1</sup> = 4, DDC 0 DCM<sup>1</sup> = 4 (Complex), and DDC 1 DCM<sup>1</sup> = 8 (Real)

	DDC 0		DDC 1		
<b>DDC Input Samples</b>	Output Port I	Output Port Q	Output Port I	Output Port Q	
N	I0 [N]	Q0 [N]	I1 [N]	Not applicable	
N + 1					
N + 2					
N + 3					
N + 4	I0 [N + 1]	Q0 [N + 1]	I1 [N + 1]	Not applicable	
N + 5					
N + 6					
N + 7					
N + 8	I0 [N + 2]	Q0 [N + 2]	I1 [N]	Not applicable	
N + 9					
N + 10					
N + 11					
N + 12	I0 [N + 3]	Q0 [N + 3]	I1 [N + 1]	Not applicable	
N + 13					
N + 14					
N + 15					

 $<sup>^{1}</sup>$  DCM = decimation.

# FREQUENCY TRANSLATION GENERAL DESCRIPTION

Frequency translation is accomplished by using a 12-bit complex NCO along with a digital quadrature mixer. The frequency translation translates either a real or complex input signal from an intermediate frequency (IF) to a baseband complex digital output (carrier frequency = 0 Hz).

The frequency translation stage of each DDC can be controlled individually and supports four different IF modes using Bits[5:4] of the DDC control registers (Register 0x310, Register 0x330, Register 0x350, and Register 0x370). These IF modes are

- Variable IF mode
- 0 Hz IF (ZIF) mode
- f<sub>s</sub>/4 Hz IF mode
- Test mode

#### Variable IF Mode

NCO and mixers are enabled. NCO output frequency can be used to digitally tune the IF frequency.

## 0 Hz IF (ZIF) Mode

Mixers are bypassed and the NCO disabled.

#### f<sub>s</sub>/4 Hz IF Mode

Mixers and NCO are enabled in special down mixing by  $f_{\text{S}}/4$  mode to save power.

#### Test Mode

Input samples are forced to 0.999 to positive full scale. NCO is enabled. This test mode allows the NCOs to directly drive the decimation filters.

Figure 121 and Figure 122 show examples of the frequency translation stage for both real and complex inputs.

# NCO FREQUENCY TUNING WORD (FTW) SELECTION 12-BIT NCO FTW = MIXING FREQUENCY/ADC SAMPLE RATE × 4096

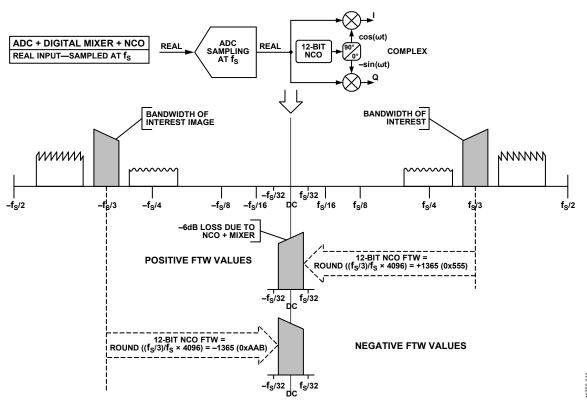


Figure 121. DDC NCO Frequency Tuning Word Selection—Real Inputs

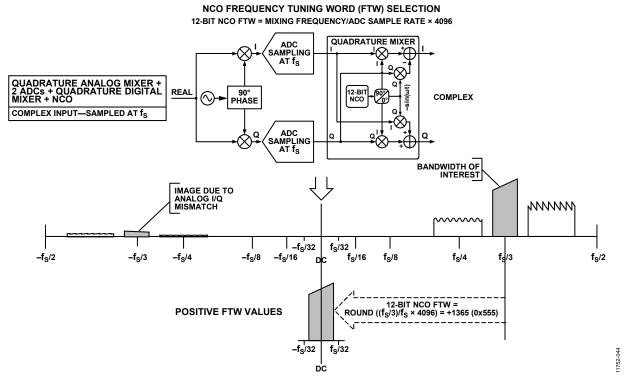


Figure 122. DDC NCO Frequency Tuning Word Selection—Complex Inputs

#### **DDC NCO PLUS MIXER LOSS AND SFDR**

When mixing a real input signal down to baseband, 6 dB of loss is introduced in the signal due to filtering of the negative image. An additional 0.05 dB of loss is introduced by the NCO. The total loss of a real input signal mixed down to baseband is 6.05 dB. For this reason, it is recommended that the user compensate for this loss by enabling the additional 6 dB of gain in the gain stage of the DDC to recenter the dynamic range of the signal within the full scale of the output bits.

When mixing a complex input signal down to baseband, the maximum value each I/Q sample can reach is  $1.414 \times$  full scale after it passes through the complex mixer. To avoid overrange of the I/Q samples and to keep the data bitwidths aligned with real mixing, 3.06 dB of loss (0.707  $\times$  full scale) is introduced in the mixer for complex signals. An additional 0.05 dB of loss is introduced by the NCO. The total loss of a complex input signal mixed down to baseband is -3.11 dB.

The worst case spurious signal from the NCO is greater than 102 dBc SFDR for all output frequencies.

#### NUMERICALLY CONTROLLED OSCILLATOR

The AD9680 has a 12-bit NCO for each DDC that enables the frequency translation process. The NCO allows the input spectrum to be tuned to dc, where it can be effectively filtered by the subsequent filter blocks to prevent aliasing. The NCO can be set up by providing a frequency tuning word (FTW) and a phase offset word (POW).

#### Setting Up the NCO FTW and POW

The NCO frequency value is given by the 12-bit twos complement number entered in the NCO FTW. Frequencies between  $-f_s/2$  and  $f_s/2$  ( $f_s/2$  excluded) are represented using the following frequency words:

- 0x800 represents a frequency of  $-f_s/2$ .
- 0x000 represents dc (frequency is 0 Hz).
- 0x7FF represents a frequency of  $+f_S/2 f_S/2^{12}$ .

The NCO frequency tuning word can be calculated using the following equation:

$$NCO\_FTW = round \left( 2^{12} \frac{Mod(f_C, f_S)}{f_S} \right)$$

where:

*NCO\_FTW* is a 12-bit twos complement number representing the NCO FTW.

 $f_S$  is the AD9680 sampling frequency (clock rate) in Hz.  $f_C$  is the desired carrier frequency in Hz.

Mod() is a remainder function. For example, Mod(110,100) = 10, and for negative numbers, Mod(-32, 10) = -2.

round() is a rounding function. For example, round(3.6) = 4, and for negative numbers, round(-3.4) = -3.

Note that this equation applies to the aliasing of signals in the digital domain (that is, aliasing introduced when digitizing analog signals).

For example, if the ADC sampling frequency (f<sub>s</sub>) is 1250 MSPS and the carrier frequency (f<sub>c</sub>) is 416.667 MHz,

$$NCO\_FTW = round \left( 2^{12} \frac{Mod(416.667,1250)}{1250} \right) = 1365 \text{ MHz}$$

This, in turn, converts to 0x555 in the 12-bit twos complement representation for NCO\_FTW. The actual carrier frequency can be calculated based on the following equation:

$$f_C - actual = \frac{NCO - FTW \times f_S}{2^{12}} = 416.56 \text{ MHz}$$

A 12-bit POW is available for each NCO to create a known phase relationship between multiple AD9680 chips or individual DDC channels inside one AD9680.

The following procedure must be followed to update the FTW and/or POW registers to ensure proper operation of the NCO:

- Write to the FTW registers for all the DDCs.
- Write to the POW registers for all the DDCs.
- Synchronize the NCOs either through the DDC soft reset bit accessible through the SPI, or through the assertion of the SYSREF± pin.

Note that the NCOs must be synchronized either through SPI or through the SYSREF± pin after all writes to the FTW or POW registers have completed. This synchronization is necessary to ensure the proper operation of the NCO.

#### **NCO Synchronization**

Each NCO contains a separate phase accumulator word (PAW) that determines the instantaneous phase of the NCO. The initial reset value of each PAW is determined by the POW described in the Setting Up the NCO FTW and POW section. The phase increment value of each PAW is determined by the FTW.

Two methods can be used to synchronize multiple PAWs within the chip:

- Using the SPI. The DDC NCO soft reset bit in the DDC synchronization control register (Register 0x300, Bit 4) can be used to reset all the PAWs in the chip. This is accomplished by toggling the DDC NCO soft reset bit. This method can only be used to synchronize DDC channels within the same AD9680 chip.
- Using the SYSREF± pin. When the SYSREF± pin is enabled in the SYSREF± control registers (Register 0x120 and Register 0x121), and the DDC synchronization is enabled in Bits[1:0] in the DDC synchronization control register (Register 0x300), any subsequent SYSREF± event resets all the PAWs in the chip. This method can be used to synchronize DDC channels within the same AD9680 chip, or DDC channels within separate AD9680 chips.

#### Mixer

The NCO is accompanied by a mixer, whose operation is similar to an analog quadrature mixer. The mixer performs the downconversion of input signals (real or complex) by using the NCO frequency as a local oscillator. For real input signals, this mixer performs a real mixer operation (with two multipliers). For complex input signals, the mixer performs a complex mixer operation (with four multipliers and two adders). The mixer adjusts its operation based on the input signal (real or complex) provided to each individual channel. The selection of real or complex inputs can be controlled individually for each DDC block by using Bit 7 of the DDC control register (Register 0x310, Register 0x330, Register 0x350, and Register 0x370).

# **FIR FILTERS**

# **GENERAL DESCRIPTION**

There are four sets of decimate-by-2, low-pass, half-band, finite impulse response (FIR) filters (HB1 FIR, HB2 FIR, HB3 FIR, and HB4 FIR, shown in Figure 119). These filters follow the frequency translation stage. After the carrier of interest is tuned down to dc (carrier frequency = 0 Hz), these filters efficiently lower the sample rate while providing sufficient alias rejection from unwanted adjacent carriers around the bandwidth of interest.

HB1 FIR is always enabled and cannot be bypassed. The HB2, HB3, and HB4 FIR filters are optional and can be bypassed for higher output sample rates.

Table 17 shows the different bandwidth options by including different half-band filters. In all cases, the DDC filtering stage of the AD9680 provides less than -0.001 dB of pass-band ripple and >100 dB of stop-band alias rejection.

Table 18 shows the amount of stop-band alias rejection for multiple pass-band ripple/cutoff points. The decimation ratio of the filtering stage of each DDC can be controlled individually through Bits[1:0] of the DDC control registers (0x310, 0x330, 0x350, and 0x370).

**Table 17. DDC Filter Characteristics** 

		Real Ou	tput	Complex (I/	Q) Output				
ADC Sample Rate (MSPS)	Half Band Filter Selection	Decimation Ratio	Output Sample Rate (MSPS)	Decimation Ratio	Output Sample Rate (MSPS)	Alias Protected Bandwidth (MHz)	Ideal SNR Improvement (dB) <sup>1</sup>	Pass- Band Ripple (dB)	Alias Rejection (dB)
1000	HB1	1	1000	2	500 (I) + 500 (Q)	385.0	1	<-0.001	>100
	HB1 + HB2	2	500	4	250 (I) + 250 (Q)	192.5	4		
	HB1 + HB2 + HB3	4	250	8	125 (I) + 125 (Q)	96.3	7		
	HB1 + HB2 + HB3 + HB4	8	125	16	62.5 (I) + 62.5 (Q)	48.1	10		
820	HB1	1	820	2	410 (I) + 410 (Q)	315.7	1		
	HB1 + HB2	2	410	4	205 (I) + 205 (Q)	157.8	4		
	HB1 + HB2 + HB3	4	205	8	102.5 (I) + 102.5 (Q)	78.9	7		
	HB1 + HB2 + HB3 + HB4	8	102.5	16	51.25 (I) + 51.25 (Q)	39.4	10		
500	HB1	1	500	2	250 (I) + 250 (Q)	192.5	1		
	HB1 + HB2	2	250	4	125 (I) + 125 (Q)	96.3	4		
	HB1 + HB2 + HB3	4	125	8	62.5 (I) + 62.5 (Q)	48.1	7		
	HB1 + HB2 + HB3 + HB4	8	62.5	16	31.25 (I) + 31.25 (Q)	24.1	10		

 $<sup>^{1}</sup>$  Ideal SNR improvement due to oversampling and filtering =  $10\log(bandwidth/(f_s/2))$ .

**Table 18. DDC Filter Alias Rejection** 

Alias Rejection (dB)	Pass-Band Ripple/ Cutoff Point (dB)	Alias Protected Bandwidth for Real (I) Outputs <sup>1</sup>	Alias Protected Bandwidth for Complex (I/Q) Outputs <sup>1</sup>
>100	<-0.001	<38.5% × f <sub>OUT</sub>	<77% × f <sub>оит</sub>
90	<-0.001	<38.7% × fоит	<77.4% × fouт
85	<-0.001	$<38.9\% \times f_{OUT}$	<77.8% × f <sub>оит</sub>
63.3	<-0.006	<40% × f <sub>OUT</sub>	<80% × f <sub>OUT</sub>
25	-0.5	44.4% × f <sub>OUT</sub>	88.8% × f <sub>OUT</sub>
19.3	-1.0	45.6% × fоит	91.2% × fоит
10.7	-3.0	48% × f <sub>OUT</sub>	96% × f <sub>ou⊤</sub>

 $<sup>^{1}</sup>$  four is the ADC input sample rate f<sub>s</sub>/DDC decimation ratio.

#### **HALF-BAND FILTERS**

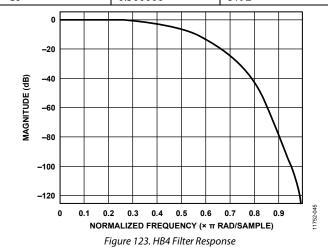
The AD9680 offers four half-band filters to enable digital signal processing of the ADC converted data. These half-band filters are bypassable and can be individually selected.

#### **HB4 Filter**

The first decimate-by-2, half-band, low-pass FIR filter (HB4) uses an 11-tap, symmetrical, fixed-coefficient filter implementation, optimized for low power consumption. The HB4 filter is only used when complex outputs (decimate by 16) or real outputs (decimate by 8) are enabled; otherwise, the filter is bypassed. Table 19 and Figure 123 show the coefficients and response of the HB4 filter.

**Table 19. HB4 Filter Coefficients** 

	Table 19. 11b4 Pitter Coefficients				
HB4 Coefficient Number		Normalized Coefficient	Decimal Coefficient (15-Bit)		
	C1, C11	0.006042	99		
	C2, C10	0	0		
	C3, C9	-0.049316	-808		
	C4, C8	0	0		
	C5, C7	0.293273	4805		
	C6	0.500000	8192		



HB3 Filter

The second decimate-by-2, half-band, low-pass, FIR filter (HB3) uses an 11-tap, symmetrical, fixed coefficient filter implementation, optimized for low power consumption. The HB3 filter is only used when complex outputs (decimate by 8 or 16) or real outputs (decimate by 4 or 8) are enabled; otherwise, the filter is bypassed. Table 20 and Figure 124 show the coefficients and response of the HB3 filter.

**Table 20. HB3 Filter Coefficients** 

HB3 Coefficient Number	Normalized Coefficient	Decimal Coefficient (18-Bit)
C1, C11	0.006554	859
C2, C10	0	0
C3, C9	-0.050819	-6661
C4, C8	0	0
C5, C7	0.294266	38,570
C6	0.500000	65,536

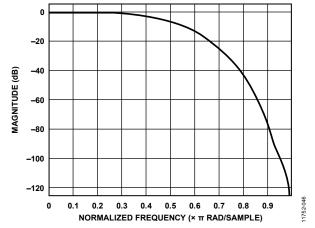


Figure 124. HB3 Filter Response

#### **HB2 Filter**

The third decimate-by-2, half-band, low-pass FIR filter (HB2) uses a 19-tap, symmetrical, fixed coefficient filter implementation that is optimized for low power consumption. The HB2 filter is only used when complex outputs (decimate by 4, 8, or 16) or real outputs (decimate by 2, 4, or 8) are enabled; otherwise, the filter is bypassed.

Table 21 and Figure 125 show the coefficients and response of the HB2 filter.

**Table 21. HB2 Filter Coefficients** 

HB2 Coefficient Number	Normalized Coefficient	Decimal Coefficient (19-Bit)
C1, C19	0.000614	161
C2, C18	0	0
C3, C17	-0.005066	-1328
C4, C16	0	0
C5, C15	0.022179	5814
C6, C14	0	0
C7, C13	-0.073517	-19,272
C8, C12	0	0
C9, C11	0.305786	80,160
C10	0.500000	131,072

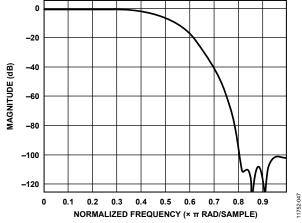


Figure 125. HB2 Filter Response

# HB1 Filter

The fourth and final decimate-by-2, half-band, low-pass FIR filter (HB1) uses a 55-tap, symmetrical, fixed coefficient filter implementation, optimized for low power consumption. The HB1 filter is always enabled and cannot be bypassed. Table 22 and Figure 126 show the coefficients and response of the HB1 filter.

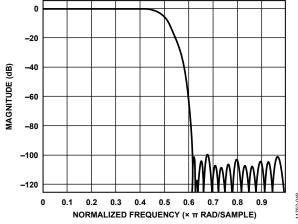


Figure 126. HB1 Filter Response

**Table 22. HB1 Filter Coefficients** 

HB1 Coefficient Normalized Decimal Coefficier				
HB1 Coefficient Number	Normalized Coefficient	(21-Bit)		
C1, C55	-0.000023	-24		
C2, C54	0	0		
C3, C53	0.000097	102		
C4, C52	0	0		
C5, C51	-0.000288	−302		
C6, C50	0	0		
C7, C49	0.000696	730		
C8, C48	0	0		
C9, C47	-0.0014725	−1544		
C10, C46	0.0014725	0		
C11, C45	0.002827	2964		
C12, C44	0	0		
C13, C43	-0.005039	-5284		
C14, C42	0	0		
C15, C41	0.008491	8903		
C16, C40	0	0		
C17, C39	-0.013717	-14,383		
C18, C38	0	0		
C19, C37	0.021591	22,640		
C20, C36	0	0		
C21, C35	-0.033833	-35,476		
C22, C34	0	0		
C23, C33	0.054806	57,468		
C24, C32	0	0		
C25, C31	-0.100557	-105,442		
C26, C30	0	0		
C27, C29	0.316421	331,792		
C28	0.500000	524,288		

#### **DDC GAIN STAGE**

Each DDC contains an independently controlled gain stage. The gain is selectable as either 0 dB or 6 dB. When mixing a real input signal down to baseband, it is recommended that the user enable the 6 dB of gain to recenter the dynamic range of the signal within the full scale of the output bits.

When mixing a complex input signal down to baseband, the mixer has already recentered the dynamic range of the signal within the full scale of the output bits and no additional gain is necessary. However, the optional 6 dB gain can be used to compensate for low signal strengths. The downsample by 2 portion of the HB1 FIR filter is bypassed when using the complex to real conversion stage (see Figure 127).

#### **DDC COMPLEX TO REAL CONVERSION**

Each DDC contains an independently controlled complex to real conversion block. The complex to real conversion block reuses the last filter (HB1 FIR) in the filtering stage, along with an  $f_{\rm s}/4$  complex mixer to upconvert the signal.

After up converting the signal, the Q portion of the complex mixer is no longer needed and is dropped.

Figure 127 shows a simplified block diagram of the complex to real conversion.

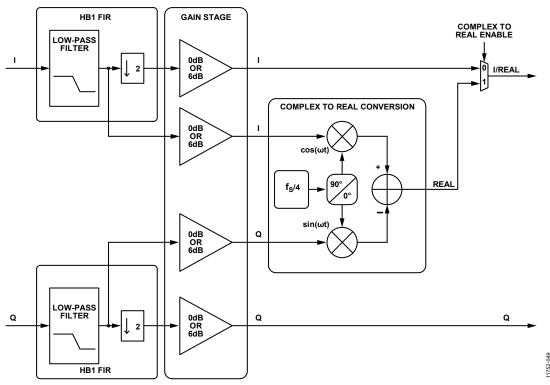


Figure 127. Complex to Real Conversion Block

# **DDC EXAMPLE CONFIGURATIONS**

Table 23 describes the register settings for multiple DDC example configurations.

**Table 23. DDC Example Configurations** 

Chip Application	Chip Decimation	DDC Input	DDC Output	Bandwidth	No. of Virtual Converters	
Layer	Ratio	Type	Type	per DDC <sup>1</sup>	Required	Register Settings <sup>2</sup>
One DDC	2	Complex	Complex	38.5% × f <sub>s</sub>	2	Register 0x200 = 0x01 (one DDC; I/Q selected)
						Register 0x201 = 0x01 (chip decimate by 2)
						Register 0x310 = 0x83 (complex mixer; 0 dB gain; variable IF; complex outputs; HB1 filter)
						Register 0x311 = 0x04 (DDC I input = ADC Channel A; DDC Q input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
Two DDCs	4	Complex	Complex	$19.25\% \times f_s$	4	Register $0x200 = 0x02$ (two DDCs; I/Q selected)
						Register $0x201 = 0x02$ (chip decimate by 4)
						Register 0x310, Register 0x330 = 0x80 (complex mixer; 0 dB gain; variable IF; complex outputs; HB2 + HB1 filters)
						Register 0x311, Register 0x331 = 0x04 (DDC I input = ADC Channel A; DDC Q input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
						Register 0x334, Register 0x335, Register 0x340, Register 0x341 = FTW and POW set as required by application for DDC 1
Two DDCs	4	Complex	Real	9.63% × f <sub>s</sub>	2	Register 0x200 = 0x22 (two DDCs; I only selected)
						Register 0x201 = 0x02 (Chip Decimate by 4)
						Register 0x310, Register 0x330 = 0x89 (complex mixer; 0 dB gain; variable IF; real output; HB3 + HB2 + HB1 filters)
						Register 0x311, Register 0x331 = 0x04 (DDC I Input = ADC Channel A; DDC Q Input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
						Register 0x334, Register 0x335, Register 0x340, Register 0x341 = FTW and POW set as required by application for DDC 1
Two DDCs	4	Real	Real	9.63% × f <sub>s</sub>	2	Register 0x200 = 0x22 (two DDCs; I only selected)
						Register $0x201 = 0x02$ (chip decimate by 4)
						Register 0x310, Register 0x330 = 0x49 (real mixer; 6 dB gain; variable IF; real output; HB3 + HB2 + HB1 filters)
						Register 0x311 = 0x00 (DDC 0 I input = ADC Channel A; DDC 0 Q input = ADC Channel A)
						Register 0x331 = 0x05 (DDC 1 I input = ADC Channel B; DDC 1 Q input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
						Register 0x334, Register 0x335, Register 0x340, Register 0x341 = FTW and POW set as required by application for DDC 1
Two DDCs	4	Real	Complex	$19.25\% \times f_s$	4	Register $0x200 = 0x02$ (two DDCs; I/Q selected)
						Register 0x201 = 0x02 (chip decimate by 4)
						Register 0x310, Register 0x330 = 0x40 (real mixer; 6 dB gain; variable IF; complex output; HB2 + HB1 filters)
						Register 0x311 = 0x00 (DDC 0 I input = ADC Channel A; DDC 0 Q input = ADC Channel A)
						Register 0x331 = 0x05 (DDC 1 I input = ADC Channel B; DDC 1 Q input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
						Register 0x334, Register 0x335, Register 0x340, Register 0x341 = FTW and POW set as required by application for DDC 1

Chip Application	Chip Decimation	DDC Input	DDC Output	Bandwidth per DDC <sup>1</sup>	No. of Virtual Converters	Desister Settings
Two DDCs	Ratio 8	Type	<b>Type</b> Real	•	Required 2	Register Settings <sup>2</sup> Register 0x200 - 0x22 (true DDCs: Lephyselected)
I WO DDCS	0	Real	Neai	4.81% × f <sub>s</sub>	2	Register 0x200 = 0x22 (two DDCs; I only selected) Register 0x201 = 0x03 (chip decimate by 8)
						Register 0x310, Register 0x330 = 0x4A (real mixer; 6 dB gain; variable IF; real output; HB4 + HB3 + HB2 + HB1 filters)
						Register 0x311 = 0x00 (DDC 0 I input = ADC Channel A; DDC 0 Q input = ADC Channel A)
						Register 0x331 = 0x05 (DDC 1 I input = ADC Channel B; DDC 1 Q input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
						Register 0x334, Register 0x335, Register 0x340, Register 0x341 = FTW and POW set as required by application for DDC 1
Four DDCs	8	Real	Complex	$9.63\% \times f_s$	8	Register $0x200 = 0x03$ (four DDCs; I/Q selected)
						Register 0x201 = 0x03 (chip decimate by 8)
						Register 0x310, Register 0x330, Register 0x350, Register 0x370 = 0x41 (real mixer; 6 dB gain; variable IF; complex output; HB3+HB2+HB1 filters)
						Register 0x311 = 0x00 (DDC 0 I input = ADC Channel A; DDC 0 Q input = ADC Channel A)
						Register 0x331 = 0x00 (DDC 1 I input = ADC Channel A; DDC 1 Q input = ADC Channel A)
						Register 0x351 = 0x05 (DDC 2 I input = ADC Channel B; DDC 2 Q input = ADC Channel B)
						Register 0x371 = 0x05 (DDC 3 I input = ADC Channel B; DDC 3 Q input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
						Register 0x334, Register 0x335, Register 0x340, Register 0x341 = FTW and POW set as required by application for DDC 1
						Register 0x354, Register 0x355, Register 0x360, Register 0x361 = FTW and POW set as required by application for DDC 2
						Register 0x374, Register 0x375, Register 0x380, Register 0x381 = FTW and POW set as required by application for DDC 3
Four DDCs	8	Real	Real	$4.81\% \times f_s$	4	Register 0x200 = 0x23 (four DDCs; I only selected)
						Register 0x201 = 0x03 (chip decimate by 8)
						Register 0x310, Register 0x330, Register 0x350, Register 0x370 = 0x4A (real mixer; 6 dB gain; variable IF; real output; HB4 + HB3 + HB2 + HB1 filters)
						Register 0x311 = 0x00 (DDC 0 I input = ADC Channel A; DDC 0 Q input = ADC Channel A)
						Register 0x331 = 0x00 (DDC 1 I input = ADC Channel A; DDC 1 Q input = ADC Channel A)
						Register 0x351 = 0x05 (DDC 2 I input = ADC Channel B; DDC 2 Q input = ADC Channel B)
						Register 0x371 = 0x05 (DDC 3 I input = ADC Channel B; DDC 3 Q input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
						Register 0x334, Register 0x335, Register 0x340, Register 0x341 = FTW and POW set as required by application for DDC 1
						Register 0x354, Register 0x355, Register 0x360, Register 0x361 = FTW and POW set as required by application for DDC 2
						Register 0x374, Register 0x375, Register 0x380, Register 0x381 = FTW and POW set as required by application for DDC 3

Chip Application Layer	Chip Decimation Ratio	DDC Input Type	DDC Output Type	Bandwidth per DDC <sup>1</sup>	No. of Virtual Converters Required	Register Settings <sup>2</sup>
Four DDCs	16	Real	Complex	$4.81\% \times f_s$	8	Register 0x200 = 0x03 (four DDCs; I/Q selected)
						Register $0x201 = 0x04$ (chip decimate by 16)
						Register 0x310, Register 0x330, Register 0x350, Register 0x370 = 0x42 (real mixer; 6d B gain; variable IF; complex output; HB4 + HB3 + HB2 + HB1 filters)
						Register 0x311 = 0x00 (DDC 0 I input = ADC Channel A; DDC 0 Q input = ADC Channel A)
						Register 0x331 = 0x00 (DDC 1 I input = ADC Channel A; DDC 1 Q input = ADC Channel A)
						Register 0x351 = 0x05 (DDC 2 I input = ADC Channel B; DDC 2 Q input = ADC Channel B)
						Register 0x371 = 0x05 (DDC 3 I input = ADC Channel B; DDC 3 Q input = ADC Channel B)
						Register 0x314, Register 0x315, Register 0x320, Register 0x321 = FTW and POW set as required by application for DDC 0
						Register 0x334, Register 0x335, Register 0x340, Register 0x341 = FTW and POW set as required by application for DDC 1
						Register 0x354, Register 0x355, Register 0x360, Register 0x361 = FTW and POW set as required by application for DDC 2
						Register 0x374, Register 0x375, Register 0x380, Register 0x381 = FTW and POW set as required by application for DDC 3

<sup>&</sup>lt;sup>1</sup> fs is the ADC sample rate. Bandwidths listed are <-0.001 dB of pass-band ripple and >100 dB of stop-band alias rejection. <sup>2</sup> The NCOs must be synchronized either through the SPI or through the SYSREF± pin after all writes to the FTW or POW registers have completed, to ensure the proper operation of the NCO. See the NCO Synchronization section for more information.

# DIGITAL OUTPUTS INTRODUCTION TO THE JESD204B INTERFACE

The AD9680 digital outputs are designed to the JEDEC standard JESD204B, serial interface for data converters. JESD204B is a protocol to link the AD9680 to a digital processing device over a serial interface with lane rates of up to 12.5 Gbps. The benefits of the JESD204B interface over LVDS include a reduction in required board area for data interface routing, and an ability to enable smaller packages for converter and logic devices.

#### **JESD204B OVERVIEW**

The JESD204B data transmit block assembles the parallel data from the ADC into frames and uses 8-bit/10-bit encoding as well as optional scrambling to form serial output data. Lane synchronization is supported through the use of special control characters during the initial establishment of the link. Additional control characters are embedded in the data stream to maintain synchronization thereafter. A JESD204B receiver is required to complete the serial link. For additional details on the JESD204B interface, refer to the JESD204B standard.

The AD9680 JESD204B data transmit block maps up to two physical ADCs or up to eight virtual converters (when DDCs are enabled) over a link. A link can be configured to use one, two, or four JESD204B lanes. The JESD204B specification refers to a number of parameters to define the link, and these parameters must match between the JESD204B transmitter (the AD9680 output) and the JESD204B receiver (the logic device input).

The JESD204B link is described according to the following parameters:

- L is the number of lanes/converter device (lanes/link) (AD9680 value = 1, 2, or 4)
- M is the number of converters/converter device (virtual converters/link) (AD9680 value = 1, 2, 4, or 8)
- F is the octets/frame (AD9680 value = 1, 2, 4, 8, or 16)
- N' is the number of bits per sample (JESD204B word size) (AD9680 value = 8 or 16)
- N is the converter resolution (AD9680 value = 7 to 16)
- CS is the number of control bits/sample (AD9680 value = 0, 1, 2, or 3)

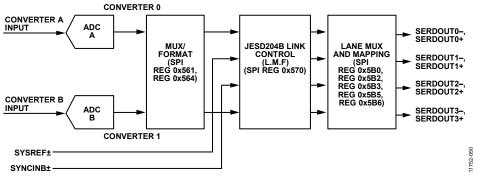
- K is the number of frames per multiframe (AD9680 value = 4, 8, 12, 16, 20, 24, 28, or 32)
- S is the samples transmitted/single converter/frame cycle (AD9680 value = set automatically based on L, M, F, and N')
- HD is the high density mode (AD9680 = set automatically based on L, M, F, and N')
- CF is the number of control words/frame clock cycle/converter device (AD9680 value = 0)

Figure 128 shows a simplified block diagram of the AD9680 JESD204B link. By default, the AD9680 is configured to use two converters and four lanes. Converter A data is output to SERDOUT0± and/or SERDOUT1±, and Converter B is output to SERDOUT2± and/or SERDOUT3±. The AD9680 allows other configurations such as combining the outputs of both converters onto a single lane, or changing the mapping of the A and B digital output paths. These modes are set up via a quick configuration register in the SPI register map, along with additional customizable options.

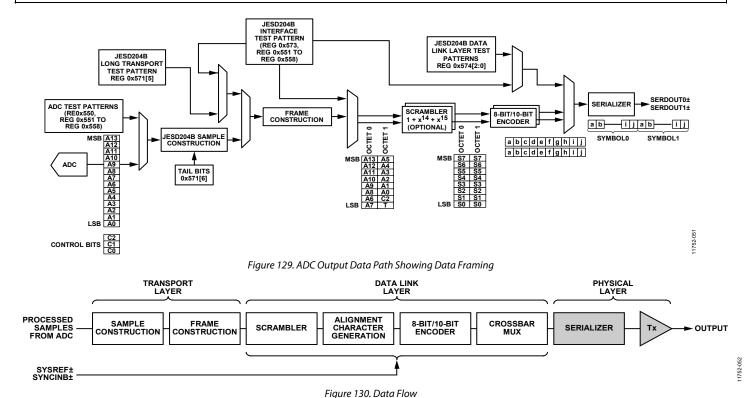
By default in the AD9680, the 14-bit converter word from each converter is broken into two octets (eight bits of data). Bit 13 (MSB) through Bit 6 are in the first octet. The second octet contains Bit 5 through Bit 0 (LSB) and two tail bits. The tail bits can be configured as zeros or a pseudorandom number sequence. The tail bits can also be replaced with control bits indicating overrange, SYSREF±, or fast detect output.

The two resulting octets can be scrambled. Scrambling is optional; however, it is recommended to avoid spectral peaks when transmitting similar digital data patterns. The scrambler uses a self-synchronizing, polynomial-based algorithm defined by the equation  $1 + x^{14} + x^{15}$ . The descrambler in the receiver is a self-synchronizing version of the scrambler polynomial.

The two octets are then encoded with an 8-bit/10-bit encoder. The 8-bit/10-bit encoder works by taking eight bits of data (an octet) and encoding them into a 10-bit symbol. Figure 129 shows how the 14-bit data is taken from the ADC, how the tail bits are added, how the two octets are scrambled, and how the octets are encoded into two 10-bit symbols. Figure 129 illustrates the default data format.



 $Figure\ 128.\ Transmit\ Link\ Simplified\ Block\ Diagram\ Showing\ Full\ Bandwidth\ Mode\ (Register\ 0x200=0x00)$ 



#### **FUNCTIONAL OVERVIEW**

The block diagram in Figure 130 shows the flow of data through the JESD204B hardware from the sample input to the physical output. The processing can be divided into layers that are derived from the open source initiative (OSI) model widely used to describe the abstraction layers of communications systems. These layers are the transport layer, data link layer, and physical layer (serializer and output driver).

# **Transport Layer**

The transport layer handles packing the data (consisting of samples and optional control bits) into JESD204B frames that are mapped to 8-bit octets. These octets are sent to the data link layer. The transport layer mapping is controlled by rules derived from the link parameters. Tail bits are added to fill gaps where required. The following equation can be used to determine the number of tail bits within a sample (JESD204B word):

$$T = N' - N - CS$$

# **Data Link Layer**

The data link layer is responsible for the low level functions of passing data across the link. These include optionally scrambling the data, inserting control characters for multichip synchronization/lane alignment/monitoring, and encoding 8-bit octets into 10-bit symbols. The data link layer is also responsible for sending the initial lane alignment sequence (ILAS), which contains the link configuration data used by the receiver to verify the settings in the transport layer.

## **Physical Layer**

The physical layer consists of the high speed circuitry clocked at the serial clock rate. In this layer, parallel data is converted into one, two, or four lanes of high speed differential serial data.

# **JESD204B LINK ESTABLISHMENT**

The AD9680 JESD204B transmitter (Tx) interface operates in Subclass 1 as defined in the JEDEC Standard 204B (July 2011 specification). The link establishment process is divided into the following steps: code group synchronization and SYNCINB±, initial lane alignment sequence, and user data and error correction.

## Code Group Synchronization (CGS) and SYNCINB±

The CGS is the process by which the JESD204B receiver finds the boundaries between the 10-bit symbols in the stream of data. During the CGS phase, the JESD204B transmit block transmits /K28.5/ characters. The receiver must locate /K28.5/ characters in its input data stream using clock and data recovery (CDR) techniques.

The receiver issues a synchronization request by asserting the SYNCINB± pin of the AD9680 low. The JESD204B Tx then begins sending /K/ characters. Once the receiver has synchronized, it waits for the correct reception of at least four consecutive /K/ symbols. It then deasserts SYNCINB±. The AD9680 then transmits an ILAS on the following local multiframe clock (LMFC) boundary.

For more information on the code group synchronization phase, refer to the JEDEC Standard JESD204B, July 2011, Section 5.3.3.1.

The SYNCINB± pin operation can also be controlled by the SPI. The SYNCINB± signal is a differential dc-coupled LVDS mode signal by default, but it can also be driven single-ended. For more information on configuring the SYNCINB± pin operation, refer to Register 0x572.

The SYNCINB± pins can also be configured to run in CMOS (single-ended) mode, by setting Bit[4] in Register 0x572. When running SYNCINB± in CMOS mode, connect the CMOS SYNCINB signal to Pin 21 (SYNCINB+) and leave Pin 20 (SYNCINB-) floating.

#### **Initial Lane Alignment Sequence (ILAS)**

The ILAS phase follows the CGS phase and begins on the next LMFC boundary. The ILAS consists of four mulitframes, with an /R/ character marking the beginning and an /A/ character marking the end. The ILAS begins by sending an /R/ character followed by 0 to 255 ramp data for one multiframe. On the second multiframe, the link configuration data is sent, starting with the third character. The second character is a /Q/ character to confirm that the link configuration data will follow. All undefined data slots are filled with ramp data. The ILAS sequence is never scrambled.

The ILAS sequence construction is shown in Figure 131. The four multiframes include the following:

- Multiframe 1. Begins with an /R/ character (/K28.0/) and ends with an /A/ character (/K28.3/).
- Multiframe 2. Begins with an /R/ character followed by a /Q/ character (/K28.4/), followed by link configuration parameters over 14 configuration octets (see Table 24) and ends with an /A/ character. Many of the parameter values are of the value 1 notation.
- Multiframe 3. Begins with an /R/ character (/K28.0/) and ends with an /A/ character (/K28.3/).
- Multiframe 4. Begins with an /R/ character (/K28.0/) and ends with an /A/ character (/K28.3/).

#### **User Data and Error Detection**

After the initial lane alignment sequence is complete, the user data is sent. Normally, within a frame, all characters are considered user data. However, to monitor the frame clock and multiframe clock synchronization, there is a mechanism for replacing characters with /F/ or /A/ alignment characters when the data meets certain conditions. These conditions are different for unscrambled and scrambled data. The scrambling operation is enabled by default, but it can be disabled using the SPI.

For scrambled data, any 0xFC character at the end of a frame is replaced by an /F/, and any 0x7C character at the end of a multiframe is replaced with an /A/. The JESD204B receiver (Rx) checks for /F/ and /A/ characters in the received data stream and verifies that they only occur in the expected locations. If an unexpected /F/ or /A/ character is found, the receiver handles the situation by using dynamic realignment or asserting the SYNCINB± signal for more than four frames to initiate a resynchronization. For unscrambled data, if the final character of two subsequent frames is equal, the second character is replaced with an /F/ if it is at the end of a frame, and an /A/ if it is at the end of a multiframe.

Insertion of alignment characters can be modified using SPI. The frame alignment character insertion (FACI) is enabled by default. More information on the link controls is available in the Memory Map section, Register 0x571.

#### 8-Bit/10-Bit Encoder

The 8-bit/10-bit encoder converts 8-bit octets into 10-bit symbols and inserts control characters into the stream when needed. The control characters used in JESD204B are shown in Table 24. The 8-bit/10-bit encoding ensures that the signal is dc balanced by using the same number of ones and zeros across multiple symbols.

The 8-bit/10-bit interface has options that can be controlled via the SPI. These operations include bypass and invert. These options are troubleshooting tools for the verification of the digital front end (DFE). Refer to the Memory Map section, Register 0x572[2:1] for information on configuring the 8-bit/10-bit encoder.

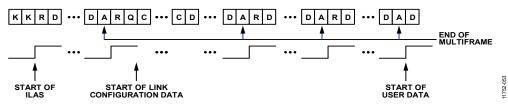


Figure 131. Initial Lane Alignment Sequence

<b>Table 24. AD9680</b> (	Control (	Characters	used in	JESD204B
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			10-Bit Value,	10-Bit Value,	
Abbreviation	Control Symbol	8-Bit Value	$RD^1 = -1$	$RD^1 = +1$	Description
/R/	/K28.0/	000 11100	001111 0100	110000 1011	Start of multiframe
/A/	/K28.3/	011 11100	001111 0011	110000 1100	Lane alignment
/Q/	/K28.4/	100 11100	001111 0100	110000 1101	Start of link configuration data
/K/	/K28.5/	101 11100	001111 1010	110000 0101	Group synchronization
/F/	/K28.7/	111 11100	001111 1000	110000 0111	Frame alignment

<sup>&</sup>lt;sup>1</sup> RD = running disparity.

# PHYSICAL LAYER (DRIVER) OUTPUTS

# **Digital Outputs, Timing, and Controls**

The AD9680 physical layer consists of drivers that are defined in the JEDEC Standard JESD204B, July 2011. The differential digital outputs are powered up by default. The drivers use a dynamic  $100~\Omega$  internal termination to reduce unwanted reflections.

Place a 100  $\Omega$  differential termination resistor at each receiver input to result in a nominal 300 mV p-p swing at the receiver (see Figure 132). Alternatively, single-ended 50  $\Omega$  termination can be used. When single-ended termination is used, the termination voltage is DRVDD/2. Otherwise, 0.1  $\mu$ F ac coupling capacitors can be used to terminate to any single-ended voltage.

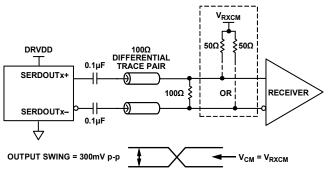


Figure 132. AC-Coupled Digital Output Termination Example

The AD9680 digital outputs can interface with custom ASICs and FPGA receivers, providing superior switching performance in noisy environments. Single point-to-point network topologies are recommended with a single differential 100  $\Omega$  termination resistor placed as close to the receiver inputs as possible. The common mode of the digital output automatically biases itself to half the DRVDD supply of 1.2 V ( $V_{\rm CM}$  = 0.6 V). See Figure 133 for dc coupling the outputs to the receiver logic.

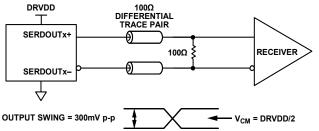


Figure 133. DC-Coupled Digital Output Termination Example

If there is no far-end receiver termination, or if there is poor differential trace routing, timing errors can result. To avoid such timing errors, it is recommended that the trace length be less than six inches, and that the differential output traces be close together and at equal lengths.

Figure 134 to Figure 139 show an example of the digital output data eye, time interval error (TIE) jitter histogram, and bathtub curve for one AD9680 lane running at 10 Gbps and 6 Gbps, respectively. The format of the output data is twos complement by default. To change the output data format, see the Memory Map section (Register 0x561 in Table 36).

#### **De-Emphasis**

De-emphasis enables the receiver eye diagram mask to be met in conditions where the interconnect insertion loss does not meet the JESD204B specification. Use the de-emphasis feature only when the receiver is unable to recover the clock due to excessive insertion loss. Under normal conditions, it is disabled to conserve power. Additionally, enabling and setting too high a de-emphasis value on a short link can cause the receiver eye diagram to fail. Use the de-emphasis setting with caution because it can increase electromagnetic interference (EMI). See the Memory Map section (Register 0x5C1 to Register 0x5C5 in Table 36) for more details.

# Phase-Locked Loop

The phase-locked loop (PLL) is used to generate the serializer clock, which operates at the JESD204B lane rate. The status of the PLL lock can be checked in the PLL locked status bit (Register 0x56F, Bit 7). This read only bit lets the user know if the PLL has achieved a lock for the specific setup. The JESD204B lane rate control, Bit 4 of Register 0x56E, must be set to correspond with the lane rate.

752-055

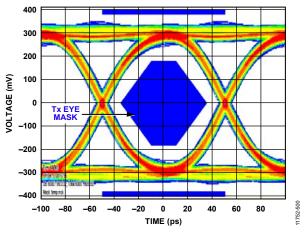


Figure 134. Digital Outputs Data Eye, External 100  $\Omega$  Terminations at 10 Gbps

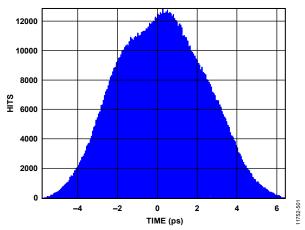


Figure 135. Digital Outputs Histogram, External 100  $\Omega$  Terminations at 10 Gbps

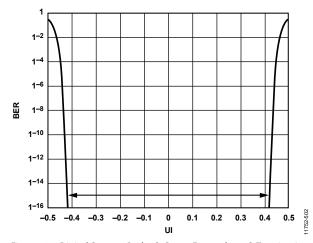


Figure 136. Digital Outputs Bathtub Curve, External 100  $\Omega$  Terminations at 10 Gbps

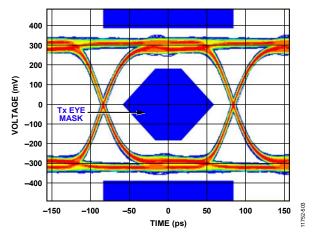


Figure 137. Digital Outputs Data Eye, External 100  $\Omega$  Terminations at 6 Gbps

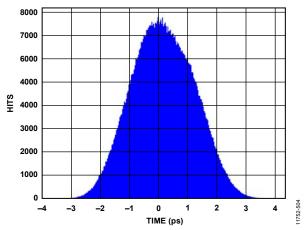


Figure 138. Digital Outputs Histogram, External 100  $\Omega$  Terminations at 6 Gbps

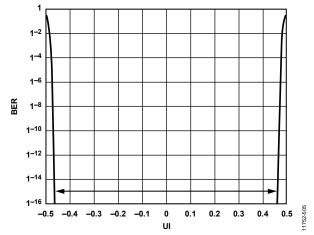


Figure 139. Digital Outputs Bathtub Curve, External 100  $\Omega$  Terminations at 6 Gbps

#### **JESD204B TX CONVERTER MAPPING**

To support the different chip operating modes, the AD9680 design treats each sample stream (real or I/Q) as originating from separate virtual converters. The I/Q samples are always mapped in pairs with the I samples mapped to the first virtual converter and the Q samples mapped to the second virtual converter. With this transport layer mapping, the number of virtual converters are the same whether

- A single real converter is used along with a digital downconverter block producing I/Q outputs, or
- An analog downconversion is used with two real converters producing I/Q outputs.

Figure 140 shows a block diagram of the two scenarios described for I/Q transport layer mapping.

The JESD204B Tx block for AD9680 supports up to four DDC blocks. Each DDC block outputs either two sample streams (I/Q) for the complex data components (real + imaginary), or one sample stream for real (I) data. The JESD204B interface can be configured to use up to eight virtual converters depending on the DDC configuration. Figure 141 shows the virtual converters and their relationship to the DDC outputs when complex outputs are used. Table 25 shows the virtual converter mapping for each chip operating mode when channel swapping is disabled.

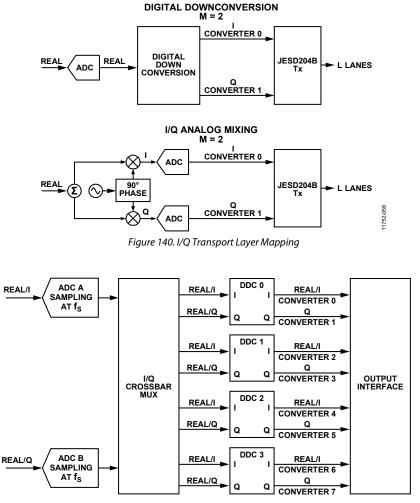


Figure 141. DDCs and Virtual Converter Mapping

Table 25. Virtual Converter Mapping

	Chip				٧	irtual Conve	erter Mappi	ng		
Number of Virtual Converters Supported	Operating Mode (0x200, Bits[1:0])	Chip Q Ignore (0x200, Bit 5)	0	1	2	3	4	5	6	7
1 to 2	Full bandwidth mode (0x0)	Real or complex (0x0)	ADC A samples	ADC B samples	Unused	Unused	Unused	Unused	Unused	Unused
1	One DDC mode (0x1)	Real (I only) (0x1)	DDC 0 I samples	Unused	Unused	Unused	Unused	Unused	Unused	Unused
2	One DDC mode (0x1)	Complex (I/Q) (0x0)	DDC 0 I samples	DDC 0 Q samples	Unused	Unused	Unused	Unused	Unused	Unused
2	Two DDC mode (0x2)	Real (I Only) (0x1)	DDC 0 I samples	DDC 1 I samples	Unused	Unused	Unused	Unused	Unused	Unused
4	Two DDC mode (0x2)	Complex (I/Q) (0x0)	DDC 0 I samples	DDC 0 Q samples	DDC 1 I samples	DDC 1 Q samples	Unused	Unused	Unused	Unused
4	Four DDC mode (0x3)	Real (I Only) (0x1)	DDC 0 I samples	DDC 1 I samples	DDC 2 I samples	DDC 3 I samples	Unused	Unused	Unused	Unused
8	Four DDC mode (0x3)	Complex (I/Q) (0x0)	DDC 0 I samples	DDC 0 Q samples	DDC 1 I samples	DDC 1 Q samples	DDC 21 samples	DDC 2 Q samples	DDC 3 I samples	DDC 3 Q samples

#### **CONFIGURING THE JESD204B LINK**

The AD9680 has one JESD204B link. The device offers an easy way to set up the JESD204B link through the JESD04B quick configuration register (Register 0x570). The serial outputs (SERDOUT0± to SERDOUT3±) are considered to be part of one JESD204B link. The basic parameters that determine the link setup are

- Number of lanes per link (L)
- Number of converters per link (M)
- Number of octets per frame (F)

If the internal DDCs are used for on-chip digital processing, M represents the number of virtual converters. The virtual converter mapping setup is shown in Figure 141.

The maximum lane rate allowed by the JESD204B specification is 12.5 Gbps. The lane line rate is related to the JESD204B parameters using the following equation:

$$Lane\ Line\ Rate = \frac{M \times N' \times \left(\frac{10}{8}\right) \times f_{OUT}}{L}$$

where 
$$f_{OUT} = \frac{f_{ADC\_CLOCK}}{Decimation \ Ratio}$$
 .

The decimation ratio (DCM) is the parameter programmed in Register 0x201.

The following steps can be used to configure the output:

- 1. Power down the link.
- 2. Select quick configuration options.
- 3. Configure detailed options.
- 4. Set output lane mapping (optional).
- 5. Set additional driver configuration options (optional).
- 6. Power up the link.

If the lane line rate calculated is less than 6.25 Gbps, select the low line rate option by programming a value of 0x10 to Register 0x56E.

Table 26 and Table 27 show the JESD204B output configurations supported for both N'=16 and N'=8 for a given number of virtual converters. Take care to ensure that the serial line rate for a given configuration is within the supported range of 3.125 Gbps to 12.5 Gbps.

Table 26. JESD204B Output Configurations for N'=16

Number of Virtual			JESD204B Transport Layer Settings <sup>2</sup>								
Converters Supported (Same Value as M)	JESD204B Quick Configuration (0x570)	JESD204B Serial Line Rate <sup>1</sup>	L	м	F	s	HD	N	N'	cs	K³
1	0x01	20 × f <sub>OUT</sub>	1	1	2	1	0	8 to 16	16	0 to 3	Only valid K
	0x40	$10 \times f_{OUT}$	2	1	1	1	1	8 to 16	16	0 to 3	values that
	0x41	$10 \times f_{\text{OUT}}$	2	1	2	2	0	8 to 16	16	0 to 3	are divisible
	0x80	$5 \times f_{OUT}$	4	1	1	2	1	8 to 16	16	0 to 3	by 4 are supported
	0x81	$5 \times f_{OUT}$	4	1	2	4	0	8 to 16	16	0 to 3	зарропса
2	0x0A	40 × f <sub>оит</sub>	1	2	4	1	0	8 to 16	16	0 to 3	]
	0x49	$20 \times f_{\text{OUT}}$	2	2	2	1	0	8 to 16	16	0 to 3	
	0x88	$10 \times f_{\text{OUT}}$	4	2	1	1	1	8 to 16	16	0 to 3	
	0x89	$10 \times f_{\text{OUT}}$	4	2	2	2	0	8 to 16	16	0 to 3	
4	0x13	$80 \times f_{\text{OUT}}$	1	4	8	1	0	8 to 16	16	0 to 3	
	0x52	$40 \times f_{OUT}$	2	4	4	1	0	8 to 16	16	0 to 3	
	0x91	$20 \times f_{\text{OUT}}$	4	4	2	1	0	8 to 16	16	0 to 3	
8	0x1C	160 × f <sub>оит</sub>	1	8	16	1	0	8 to 16	16	0 to 3	1
	0x5B	$80 \times f_{\text{OUT}}$	2	8	8	1	0	8 to 16	16	0 to 3	
	0x9A	$40 \times f_{OUT}$	4	8	4	1	0	8 to 16	16	0 to 3	

¹  $f_{OUT}$  = output sample rate = ADC sample rate/chip decimation ratio. The JESD204B serial line rate must be ≥3125 Mbps and ≤12,500 Mbps; when the serial line rate is ≤12.5 Gbps and ≥ 6.25 Gbps, the low line rate mode must be disabled (set Bit 4 to 0x0 in 0x56E). When the serial line rate is <6.25 Gbps and ≥3.125 Gbps, the low line rate mode must be enabled (set Bit 4 to 0x1 in 0x56E).

<sup>&</sup>lt;sup>2</sup> JESD204B transport layer descriptions are as described in the JESD204B Overview section.

<sup>&</sup>lt;sup>3</sup> For F = 1, K = 20, 24, 28, and 32. For F = 2, K = 12, 16, 20, 24, 28, and 32. For F = 4, K = 8, 12, 16, 20, 24, 28, and 32. For F = 8 and F = 16, K = 4, 8, 12, 16, 20, 24, 28, and 32.

Table 27. JESD204B Output Configurations for N'=8

Number of Virtual					J	ESD2	204B Tr	ansport	Layer S	Settings <sup>2</sup>	1
Converters Supported (Same Value as M)	Configuration (0x570)	Serial Line Rate <sup>1</sup>	L	м	F	s	HD	N	N'	cs	<b>K</b> <sup>3</sup>
1	0x00	10 × f <sub>оит</sub>	1	1	1	1	0	7 to 8	8	0 to 1	Only valid K
	0x01	$10 \times f_{OUT}$	1	1	2	2	0	7 to 8	8	0 to 1	values which
	0x40	$5 \times f_{OUT}$	2	1	1	2	0	7 to 8	8	0 to 1	are divisible
	0x41	5 × f <sub>OUT</sub>	2	1	2	4	0	7 to 8	8	0 to 1	by 4 are supported
	0x42	5 × f <sub>OUT</sub>	2	1	4	8	0	7 to 8	8	0 to 1	
	0x80	2.5 × f <sub>o∪T</sub>	4	1	1	4	0	7 to 8	8	0 to 1	
	0x81	2.5 × f <sub>OUT</sub>	4	1	2	8	0	7 to 8	8	0 to 1	
2	0x09	$20 \times f_{OUT}$	1	2	2	1	0	7 to 8	8	0 to 1	
	0x48	10 × f <sub>o∪T</sub>	2	2	1	1	0	7 to 8	8	0 to 1	
	0x49	10 × f <sub>o∪T</sub>	2	2	2	2	0	7 to 8	8	0 to 1	
	0x88	5 × f <sub>OUT</sub>	4	2	1	2	0	7 to 8	8	0 to 1	
	0x89	$5 \times f_{OUT}$	4	2	2	4	0	7 to 8	8	0 to 1	
	0x8A	$5 \times f_{OUT}$	4	2	4	8	0	7 to 8	8	0 to 1	

¹  $f_{OUT}$  = output sample rate = ADC sample rate/chip decimation ratio. The JESD204B serial line rate must be ≥3125 Mbps and ≤12,500 Mbps; when the serial line rate is ≤12.5 Gbps and ≥6.25 Gbps, the low line rate mode must be disabled (set Bit 4 to 0x0 in Register 0x56E). When the serial line rate is <6.25 Gbps and ≥3.125 Gbps, the low line rate mode must be enabled (set Bit 4 to 0x1 in Register 0x56E).

See the Example 1: Full Bandwidth Mode section and the Example 2: ADC with DDC Option (Two ADCs Plus Four DDCs) section for two examples describing which JESD204B transport layer settings are valid for a given chip mode.

# **Example 1: Full Bandwidth Mode**

Chip application mode = full bandwidth mode (see Figure 142).

- Two 14-bit converters at 1000 MSPS
- Full bandwidth application layer mode
- No decimation

# JESD204B output configuration:

- Two virtual converters required (see Table 26)
- Output sample rate  $(f_{OUT}) = 1000/1 = 1000 \text{ MSPS}$

JESD204B supported output configurations (see Table 26) include:

- N' = 16 bits
- N = 14 bits
- L = 4, M = 2, and F = 1, or L = 4, M = 2, and F = 2 (quick configuration = 0x88 or 0x89)
- CS = 0 to 2
- K = 32
- Output serial line rate = 10 Gbps per lane, low line rate mode disabled

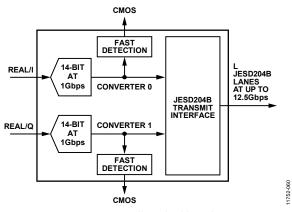


Figure 142. Full Bandwidth Mode

# Example 2: ADC with DDC Option (Two ADCs Plus Four DDCs)

Chip application mode = four-DDC mode. (see Figure 143).

- Two 14-bit converters at 1 MSPS
- Four DDC application layer mode with complex outputs (I/Q)
- Chip decimation ratio = 16
- DDC decimation ratio = 16 (see Table 15).

# JESD204B output configuration:

- Virtual converters required = 8 (see Table 26)
- Output sample rate  $(f_{OUT}) = 1000/16 = 62.5 \text{ MSPS}$

<sup>&</sup>lt;sup>2</sup> JESD204B transport layer descriptions are as described in the JESD204B Overview section.

<sup>&</sup>lt;sup>3</sup> For F = 1, K = 20, 24, 28, and 32. For F = 2, K = 12, 16, 20, 24, 28, and 32. For F = 4, K = 8, 12, 16, 20, 24, 28, and 32. For F = 8 and F = 16, K = 4, 8, 12, 16, 20, 24, 28, and 32.

JESD204B supported output configurations (see Table 26):

- N' = 16 bits
- N = 14 bits
- L = 1, M = 8, and F = 16, or L = 2, M = 8, and F = 8 (quick configuration = 0x1C or 0x5B)
- CS = 0 to 1
- K = 32
- Output serial line rate = 10 Gbps per lane (L = 1) or 5 Gbps per lane (L = 2)

For L = 1, low line rate mode is disabled. For L = 2, low line rate mode is enabled.

Example 2 shows the flexibility in the digital and lane configurations for the AD9680. The sample rate is 1 GSPS; however, the outputs are all combined in either one or two lanes, depending on the I/O speed capability of the receiving device.

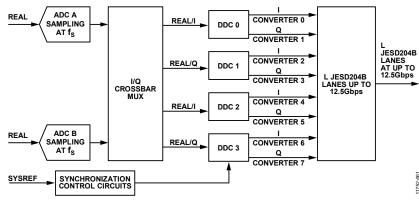


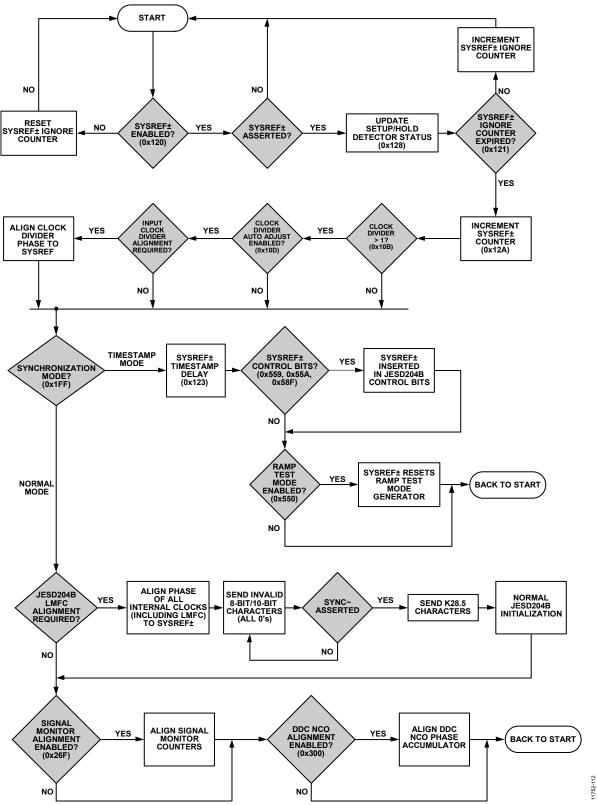
Figure 143. Two ADC Plus Four DDC Mode

# **MULTICHIP SYNCHRONIZATION**

The AD9680 has a SYSREF± input that provides flexible options for synchronizing the internal blocks. The SYSREF± input is a source synchronous system reference signal that enables multichip synchronization. The input clock divider, DDCs, signal monitor block, and JESD204B link can be synchronized using the SYSREF± input. For the highest level of timing accuracy, SYSREF± must meet setup and hold requirements relative to the CLK± input.

The flowchart in Figure 144 describes the internal mechanism for multichip synchronization in the AD9680. The AD9680

supports several features that aid users in meeting the requirements set out for capturing a SYSREF± signal. The SYSREF sample event can be defined as either a synchronous low to high transition, or a synchronous high to low transition. Additionally, the AD9680 allows the SYSREF signal to be sampled using either the rising edge or falling edge of the CLK± input. The AD9680 also has the ability to ignore a programmable number (up to 16) of SYSREF± events. The SYSREF± control options can be selected using Register 0x120 and Register 0x121.



# SYSREF± SETUP/HOLD WINDOW MONITOR

To ensure a valid SYSREF signal capture, the AD9680 has a SYSREF $\pm$  setup/hold window monitor. This feature allows the system designer to determine the location of the SYSREF $\pm$  signals relative to the CLK $\pm$  signals by reading back the amount of setup/hold margin on the interface through the memory map.

Figure 145 and Figure 146 show the setup and hold status values for different phases of SYSREF±. The setup detector returns the status of the SYSREF± signal before the CLK± edge, and the hold detector returns the status of the SYSREF signal after the CLK± edge. Register 0x128 stores the status of SYSREF± and lets the user know if the SYSREF± signal is captured by the ADC.

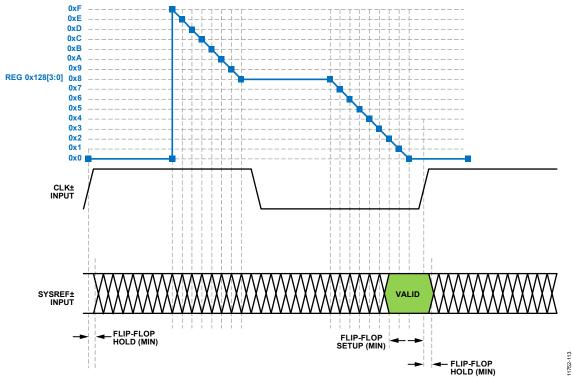


Figure 145. SYSREF± Setup Detector

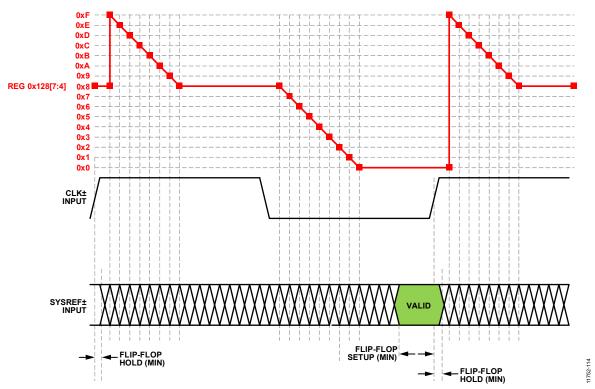


Figure 146. SYSREF± Hold Detector

Table 28 shows the description of the contents of Register 0x128 and how to interpret them.

Table 28. SYSREF± Setup/Hold Monitor, Register 0x128

1 WOIT 201 0 1 0 1 (2) 2 2 0 0 1 W	P, 11014 1,1011101, 10810101 0111	
Register 0x128[7:4] Hold Status	Register 0x128[3:0] Setup Status	Description
0x0	0x0 to 0x7	Possible setup error. The smaller this number, the smaller the setup margin.
0x0 to 0x8	0x8	No setup or hold error (best hold margin).
0x8	0x9 to 0xF	No setup or hold error (best setup and hold margin).
0x8	0x0	No setup or hold error (best setup margin).
0x9 to 0xF	0x0	Possible hold error. The larger this number, the smaller the hold margin.
0x0	0x0	Possible setup or hold error.

# TEST MODES ADC TEST MODES

The AD9680 has various test options that aid in the system level implementation. The AD9680 has ADC test modes that are available in Register 0x550. These test modes are described in Table 29. When an output test mode is enabled, the analog section of the ADC is disconnected from the digital back-end blocks, and the test pattern is run through the output formatting block. Some of the test patterns are subject to output formatting, and

some are not. The PN generators from the PN sequence tests can be reset by setting Bit 4 or Bit 5 of Register 0x550. These tests can be performed with or without an analog signal (if present, the analog signal is ignored); however, they do require an encode clock. For more information, see the AN-877 Application Note, *Interfacing to High Speed ADCs via SPI*.

Table 29. ADC Test Modes<sup>1</sup>

Output Test Mode	Dattorn Name	Everession	Default/ Seed Value	Samula (N. N. J. N. J. )
Bit Sequence	Pattern Name	Expression		Sample (N, N + 1, N + 2,)
0000	Off (default)	N/A	N/A	N/A
0001	Midscale short	00 0000 0000 0000	N/A	N/A
0010	+Full-scale short	01 1111 1111 1111	N/A	N/A
0011	–Full-scale short	10 0000 0000 0000	N/A	N/A
0100	Checkerboard	10 1010 1010 1010	N/A	0x1555, 0x2AAA, 0x1555, 0x2AAA, 0x1555
0101	PN sequence long	$X^{23} + X^{18} + 1$	0x3AFF	0x3FD7, 0x0002, 0x26E0, 0x0A3D, 0x1CA6
0110	PN sequence short	$X^9 + X^5 + 1$	0x0092	0x125B, 0x3C9A, 0x2660, 0x0c65, 0x0697
0111	One-/zero-word toggle	11 1111 1111 1111	N/A	0x0000, 0x3FFF, 0x0000, 0x3FFF, 0x0000
1000	User input	Register 0x551 to Register 0x558	N/A	User Pattern 1[15:2], User Pattern 2[15:2], User Pattern 3[15:2], User Pattern 4[15:2], User Pattern 1[15:2] for repeat mode User Pattern 1[15:2], User Pattern 2[15:2], User Pattern 3[15:2], User Pattern 4[15:2], 0x0000 for single mode
1111	Ramp Output	(X) % 2 <sup>14</sup>	N/A	$(X) \% 2^{14}, (X + 1) \% 2^{14}, (X + 2) \% 2^{14}, (X + 3) \% 2^{14}$

<sup>&</sup>lt;sup>1</sup> N/A means not applicable.

#### **JESD204B BLOCK TEST MODES**

In addition to the ADC pipeline test modes, the AD9680 also has flexible test modes in the JESD204B block. These test modes are listed in Register 0x573 and Register 0x574. These test patterns can be injected at various points along the output data path. These test injection points are shown in Figure 129. Table 30 describes the various test modes available in the JESD204B block. For the AD9680, a transition from test modes (Register  $0x573 \neq 0x00$ ) to normal mode (Register 0x573 = 0x00) requires an SPI soft reset. This is done by writing 0x81 to Register 0x00 (self cleared).

#### **Transport Layer Sample Test Mode**

The transport layer samples are implemented in the AD9680 as defined by section 5.1.6.3 in the JEDEC JESD204B Specification.

These tests are shown in Register 0x571[5]. The test pattern is equivalent to the raw samples from the ADC.

#### **Interface Test Modes**

The interface test modes are described in Register 0x573, Bits[3:0]. These test modes are also explained in Table 30. The interface tests can be injected at various points along the data. See Figure 129 for more information on the test injection points. Register 0x573, Bits[5:4] show where these tests are injected.

Table 31, Table 32, and Table 33 show examples of some of the test modes when injected at the JESD Sample Input, PHY 10-bit Input, and Scrambler 8-bit Input. UP in the tables represent the user pattern control bits from the customer register map.

Table 30. JESD204B Interface Test Modes

Output Test Mode			
Bit Sequence	Pattern Name	Expression	Default
0000	Off (default)	Not applicable	Not applicable
0001	Alternating checker board	0x5555, 0xAAAA, 0x5555,	Not applicable
0010	1/0 word toggle	0x0000, 0xFFFF, 0x0000,	Not applicable
0011	31-bit PN sequence	$X^{31} + X^{28} + 1$	0x0003AFFF
0100	23-bit PN sequence	$X^{23} + X^{18} + 1$	0x003AFF
0101	15-bit PN sequence	$X^{15} + X^{14} + 1$	0x03AF
0110	9-bit PN sequence	$X^9 + X^5 + 1$	0x092
0111	7-bit PN sequence	$X^7 + X^6 + 1$	0x07
1000	Ramp output	(X) % 2 <sup>16</sup>	Ramp size depends on test injection point
1110	Continuous/repeat user test	Register 0x551 to Register 0x558	User Pattern 1 to User Pattern 4, then repeat
1111	Single user test	Register 0x551 to Register 0x558	User Pattern 1 to User Pattern 4, then zeros

Table 31. JESD204B Sample Input for M=2, S=2, N'=16 (Register 0x573[5:4]='b00)

Frame	Converter	Sample	Alternating	1/0 Word					
Number	Number	Number	Checkerboard	Toggle	Ramp	PN9	PN23	User Repeat	User Single
0	0	0	0x5555	0x0000	(X) % 2 <sup>16</sup>	0x496F	0xFF5C	UP1[15:0]	UP1[15:0]
0	0	1	0x5555	0x0000	(X) % 2 <sup>16</sup>	0x496F	0xFF5C	UP1[15:0]	UP1[15:0]
0	1	0	0x5555	0x0000	(X) % 2 <sup>16</sup>	0x496F	0xFF5C	UP1[15:0]	UP1[15:0]
0	1	1	0x5555	0x0000	(X) % 2 <sup>16</sup>	0x496F	0xFF5C	UP1[15:0]	UP1[15:0]
1	0	0	0xAAAA	0xFFFF	$(X + 1) \% 2^{16}$	0xC9A9	0x0029	UP2[15:0]	UP2[15:0]
1	0	1	0xAAAA	0xFFFF	$(X + 1) \% 2^{16}$	0xC9A9	0x0029	UP2[15:0]	UP2[15:0]
1	1	0	0xAAAA	0xFFFF	$(X + 1) \% 2^{16}$	0xC9A9	0x0029	UP2[15:0]	UP2[15:0]
1	1	1	0xAAAA	0xFFFF	$(X + 1) \% 2^{16}$	0xC9A9	0x0029	UP2[15:0]	UP2[15:0]
2	0	0	0x5555	0x0000	$(X +2) \% 2^{16}$	0x980C	0xB80A	UP3[15:0]	UP3[15:0]
2	0	1	0x5555	0x0000	$(X +2) \% 2^{16}$	0x980C	0xB80A	UP3[15:0]	UP3[15:0]
2	1	0	0x5555	0x0000	$(X +2) \% 2^{16}$	0x980C	0xB80A	UP3[15:0]	UP3[15:0]
2	1	1	0x5555	0x0000	$(X +2) \% 2^{16}$	0x980C	0xB80A	UP3[15:0]	UP3[15:0]
3	0	0	0xAAAA	0xFFFF	$(X +3) \% 2^{16}$	0x651A	0x3D72	UP4[15:0]	UP4[15:0]
3	0	1	0xAAAA	0xFFFF	$(X +3) \% 2^{16}$	0x651A	0x3D72	UP4[15:0]	UP4[15:0]
3	1	0	0xAAAA	0xFFFF	$(X +3) \% 2^{16}$	0x651A	0x3D72	UP4[15:0]	UP4[15:0]
3	1	1	0xAAAA	0xFFFF	$(X + 3) \% 2^{16}$	0x651A	0x3D72	UP4[15:0]	UP4[15:0]
4	0	0	0x5555	0x0000	(X +4) % 2 <sup>16</sup>	0x5FD1	0x9B26	UP1[15:0]	0x0000
4	0	1	0x5555	0x0000	$(X +4) \% 2^{16}$	0x5FD1	0x9B26	UP1[15:0]	0x0000
4	1	0	0x5555	0x0000	$(X +4) \% 2^{16}$	0x5FD1	0x9B26	UP1[15:0]	0x0000
4	1	1	0x5555	0x0000	$(X +4) \% 2^{16}$	0x5FD1	0x9B26	UP1[15:0]	0x0000

Table 32. Physical Layer 10-bit Input (Register 0x573[5:4]='b01)

10-Bit Symbol Number	Alternating Checkerboard	1/0 Word Toggle	Ramp	PN9	PN23	User Repeat	User Single
0	0x155	0x000	(X) % 2 <sup>10</sup>	0x125	0x3FD	UP1[15:6]	UP1[15:6]
1	0x2AA	0x3FF	$(X + 1) \% 2^{10}$	0x2FC	0x1C0	UP2[15:6]	UP2[15:6]
2	0x155	0x000	$(X + 2) \% 2^{10}$	0x26A	0x00A	UP3[15:6]	UP3[15:6]
3	0x2AA	0x3FF	$(X + 3) \% 2^{10}$	0x198	0x1B8	UP4[15:6]	UP4[15:6]
4	0x155	0x000	$(X + 4) \% 2^{10}$	0x031	0x028	UP1[15:6]	0x000
5	0x2AA	0x3FF	$(X + 5) \% 2^{10}$	0x251	0x3D7	UP2[15:6]	0x000
6	0x155	0x000	$(X + 6) \% 2^{10}$	0x297	0x0A6	UP3[15:6]	0x000
7	0x2AA	0x3FF	$(X + 7) \% 2^{10}$	0x3D1	0x326	UP4[15:6]	0x000
8	0x155	0x000	$(X + 8) \% 2^{10}$	0x18E	0x10F	UP1[15:6]	0x000
9	0x2AA	0x3FF	$(X + 9) \% 2^{10}$	0x2CB	0x3FD	UP2[15:6]	0x000
10	0x155	0x000	$(X + 10) \% 2^{10}$	0x0F1	0x31E	UP3[15:6]	0x000
11	0x2AA	0x3FF	$(X + 11) \% 2^{10}$	0x3DD	0x008	UP4[15:6]	0x000

Table 33. Scrambler 8-bit Input (Register 0x573[5:4]='b10)

8-Bit Octet Number	Alternating Checkerboard	1/0 Word Toggle	Ramp	PN9	PN23	User Repeat	User Single
0	0x55	0x00	(X) % 2 <sup>8</sup>	0x49	0xFF	UP1[15:9]	UP1[15:9]
1	0xAA	0xFF	$(X + 1) \% 2^8$	0x6F	0x5C	UP2[15:9]	UP2[15:9]
2	0x55	0x00	$(X + 2) \% 2^8$	0xC9	0x00	UP3[15:9]	UP3[15:9]
3	0xAA	0xFF	$(X + 3) \% 2^8$	0xA9	0x29	UP4[15:9]	UP4[15:9]
4	0x55	0x00	$(X + 4) \% 2^8$	0x98	0xB8	UP1[15:9]	0x00
5	0xAA	0xFF	$(X + 5) \% 2^8$	0x0C	0x0A	UP2[15:9]	0x00
6	0x55	0x00	$(X + 6) \% 2^8$	0x65	0x3D	UP3[15:9]	0x00
7	0xAA	0xFF	$(X + 7) \% 2^8$	0x1A	0x72	UP4[15:9]	0x00
8	0x55	0x00	$(X + 8) \% 2^8$	0x5F	0x9B	UP1[15:9]	0x00
9	0xAA	0xFF	$(X + 9) \% 2^8$	0xD1	0x26	UP2[15:9]	0x00
10	0x55	0x00	$(X + 10) \% 2^8$	0x63	0x43	UP3[15:9]	0x00
11	0xAA	0xFF	$(X + 11) \% 2^8$	0xAC	0xFF	UP4[15:9]	0x00

## **Data Link Layer Test Modes**

The data link layer test modes are implemented in the AD9680 as defined by section 5.3.3.8.2 in the JEDEC JESD204B Specification. These tests are shown in Register 0x574 Bits[2:0].

Test patterns inserted at this point are useful for verifying the functionality of the data link layer. When the data link layer test modes are enabled, disable SYNCINB $\pm$  by writing 0xC0 to Register 0x572.

## SERIAL PORT INTERFACE

The AD9680 SPI allows the user to configure the converter for specific functions or operations through a structured register space provided inside the ADC. The SPI gives the user added flexibility and customization, depending on the application. Addresses are accessed via the serial port and can be written to or read from via the port. Memory is organized into bytes that can be further divided into fields. These fields are documented in the Memory Map section. For detailed operational information, see the Serial Control Interface Standard (Rev. 1.0).

#### **CONFIGURATION USING THE SPI**

Three pins define the SPI of the AD9680 ADC: the SCLK pin, the SDIO pin, and the CSB pin (see Table 34). The SCLK (serial clock) pin is used to synchronize the read and write data presented from/to the ADC. The SDIO (serial data input/output) pin is a dual-purpose pin that allows data to be sent and read from the internal ADC memory map registers. The CSB (chip select bar) pin is an active low control that enables or disables the read and write cycles.

**Table 34. Serial Port Interface Pins** 

Pin	Function
SCLK	Serial clock. The serial shift clock input that is used to synchronize serial interface, reads, and writes.
SDIO	Serial data input/output. A dual-purpose pin that typically serves as an input or an output, depending on the instruction being sent and the relative position in the timing frame.
CSB	Chip select bar. An active low control that gates the read and write cycles.

The falling edge of CSB, in conjunction with the rising edge of SCLK, determines the start of the framing. An example of the serial timing and its definitions can be found in Figure 4 and Table 5.

Other modes involving the CSB pin are available. The CSB pin can be held low indefinitely, which permanently enables the device; this is called streaming. The CSB can stall high between bytes to allow additional external timing. When CSB is tied high, SPI functions are placed in a high impedance mode. This mode turns on any SPI pin secondary functions.

All data is composed of 8-bit words. The first bit of each individual byte of serial data indicates whether a read or write

command is issued, which allows the SDIO pin to change direction from an input to an output.

In addition to word length, the instruction phase determines whether the serial frame is a read or write operation, allowing the serial port to be used both to program the chip and to read the contents of the on-chip memory. If the instruction is a readback operation, performing a readback causes the SDIO pin to change direction from an input to an output at the appropriate point in the serial frame.

Data can be sent in MSB first mode or in LSB first mode. MSB first is the default on power-up and can be changed via the SPI port configuration register. For more information about this and other features, see the Serial Control Interface Standard (Rev. 1.0).

#### HARDWARE INTERFACE

The pins described in Table 34 comprise the physical interface between the user programming device and the serial port of the AD9680. The SCLK pin and the CSB pin function as inputs when using the SPI interface. The SDIO pin is bidirectional, functioning as an input during write phases and as an output during readback.

The SPI interface is flexible enough to be controlled by either FPGAs or microcontrollers. One method for SPI configuration is described in detail in the AN-812 Application Note, *Microcontroller-Based Serial Port Interface (SPI) Boot Circuit*.

Do not activate the SPI port during periods when the full dynamic performance of the converter is required. Because the SCLK signal, the CSB signal, and the SDIO signal are typically asynchronous to the ADC clock, noise from these signals can degrade converter performance. If the on-board SPI bus is used for other devices, it may be necessary to provide buffers between this bus and the AD9680 to prevent these signals from transitioning at the converter inputs during critical sampling periods.

#### SPI ACCESSIBLE FEATURES

Table 35 provides a brief description of the general features that are accessible via the SPI. These features are described in detail in the Serial Control Interface Standard (Rev. 1.0). The AD9680 device-specific features are described in the Memory Map section.

Table 35. Features Accessible Using the SPI

Feature Name	Description
Mode	Allows the user to set either power-down mode or standby mode.
Clock	Allows the user to access the clock divider via the SPI.
DDC	Allows the user to set up decimation filters for different applications.
Test Input/Output	Allows the user to set test modes to have known data on output bits.
Output Mode	Allows the user to set up outputs.
SERDES Output Setup	Allows the user to vary SERDES settings such as swing and emphasis.

## MEMORY MAP

### **READING THE MEMORY MAP REGISTER TABLE**

Each row in the memory map register table has eight bit locations. The memory map is divided into four sections: the Analog Devices SPI registers (Register 0x000 to Register 0x00D), the analog input buffer control registers, the ADC function registers, the DDC function registers, and the digital outputs and test modes registers.

Table 36 (see the Memory Map Register Table section) documents the default hexadecimal value for each hexadecimal address shown. The column with the heading Bit 7 (MSB) is the start of the default hexadecimal value given. For example, Address 0x561, the output mode register, has a hexadecimal default value of 0x01, which means that Bit 0=1, and the remaining bits are 0x. This setting is the default output format value, which is twos complement. For more information on this function and others, see the Table 36.

### **Open and Reserved Locations**

All address and bit locations that are not included in Table 36 are not currently supported for this device. Write unused bits of a valid address location with 0s unless the default value is set otherwise. Writing to these locations is required only when part of an address location is unassigned (for example, Address 0x561). If the entire address location is open (for example, Address 0x13), do not write to this address location.

#### **Default Values**

After the AD9680 is reset, critical registers are loaded with default values. The default values for the registers are given in the memory map register table, Table 36.

#### **Logic Levels**

An explanation of logic level terminology follows:

- "Bit is set" is synonymous with "bit is set to Logic 1" or "writing Logic 1 for the bit."
- "Clear a bit" is synonymous with "bit is set to Logic 0" or "writing Logic 0 for the bit."
- X denotes a don't care bit.

#### **Channel-Specific Registers**

Some channel setup functions, such as the input termination (Register 0x016), can be programmed to a different value for each channel. In these cases, channel address locations are internally duplicated for each channel. These registers and bits are designated in Table 36 as local. These local registers and bits can be accessed by setting the appropriate Channel A or Channel B bits in Register 0x008. If both bits are set, the subsequent write affects the registers of both channels. In a read cycle, set only Channel A or Channel B to read one of the two registers. If both bits are set during an SPI read cycle, the device returns the value for Channel A. Registers and bits designated as global in Table 36 affect the entire device and the channel features for which independent settings are not allowed between channels. The settings in Register 0x005 do not affect the global registers and bits.

#### **SPI Soft Reset**

After issuing a soft reset by programming 0x81 to Register 0x000, the AD9680 requires 5 ms to recover. When programming the AD9680 for application setup, ensure that an adequate delay is programmed into the firmware after asserting the soft reset and before starting the device setup.

## **MEMORY MAP REGISTER TABLE**

All address locations that are not included in Table 36 are not currently supported for this device and should not be written.

Table 36. Memory Map Registers

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
	Devices SPI Registe	, ,									
0x000	INTERFACE_ CONFIG_A	Soft reset (self clearing)	LSB first 0 = MSB 1 = LSB	Address ascension	0	0	Address ascension	LSB first 0 = MSB 1 = LSB	Soft reset (self clearing)	0x00	
0x001	INTERFACE_ CONFIG_B	Single instruction	0	0	0	0	0	Datapath soft reset (self clearing)	0	0x00	
0x002	DEVICE_ CONFIG (local)	0	0	0	0	0	0	10 = s	al operation tandby ver-down	0x00	
0x003	CHIP_TYPE						011 = high s	peed ADC		0x03	Read only
0x004	CHIP_ID (low byte)	1	1	0	0	0	1	0	1	0xC5	Read only
0x005	CHIP_ID (high byte)	0	0	0	0	0	0	0	0	0x00	Read only
0x006	CHIP_ GRADE		1000 =	000 MSPS 820 MSPS 500 MSPS		Х	Х	Х	Х		Read only
0x008	Device index	0	0	0	0	0	0	Channel B	Channel A	0x0	
0x00A	Scratch pad	0	0	0	0	0	0	0	0	0x00	
0x00B	SPI revision	0	0	0	0	0	0	0	1	0x01	
0x00C	Vendor ID (low byte)	0	1	0	1	0	1	1	0	0x56	Read only
0x00D	Vendor ID (high byte)	0	0	0	0	0	1	0	0	0x04	Read only
Analog I	nput Buffer Contro	ol Registers									
0x015	Analog input (local)	0	0	0	0	0	0	0	Input disable 0 = normal operation 1 = input disabled	0x00	
0x016	Input termination (local)	Anal	0000 = 40 0001 = 0010 =	erential termin $\Omega \Omega$ (default) = 200 $\Omega$ = 100 $\Omega$ = 50 $\Omega$	ation	110	-500	0x0E for AD9680- 1000; 0x0C for AD9680- 820 and AD9680- 500			
0x934	Input capacitance (local)	0	0	0			0x1F				
0x018	Buffer Control 1 (local)	0000 = 1.0× buffer current 0001 = 1.5× buffer current 0010 = 2.0× buffer current (default for AD9680-500) 0011 = 2.5× buffer current 0100 = 3.0× buffer current (default for AD9680-1000 and AD9680-820) 0101 = 3.5× buffer current  1111 = 8.5× buffer current				0	0	0	0	0x40 for AD9680- 1000 and AD9680- 820; 0x20 for AD9680- 500	

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x019	Buffer Control 2 (local)	0100 = 0101 =	Setting 2 (de Setting 3 (de	efault for AD96 fault for AD966 fault for AD966 fault for AD96 Setting 4	30-1000)	0	0	0	0	0x50 for AD9680- 1000; 0x40 for AD9680- 820; 0x60 for AD9680- 500	
0x01A	Buffer Control 3 (local)	0	0	0	0	1000 = Setting 1 1001 = Setting 2 (default for AD9680-1000 and AD9680-820) 1010 = Setting 3 (default for AD9680-500)				0x09 for AD9680- 1000 and AD9680- 820; 0x0A for AD9680- 500	
0x11A	Buffer Control 4 (local)	0	0	High frequency setting 0 = off (default) 1 = on	0	0	0	0	0		
0x935	Buffer Control 5 (local)	0	0	0	0	0	Low frequency operation 0 = off 1 = on (default)	0	0		
0x025	Input full- scale range (local)	0	0	0	0	Full-scale adjust 0000 = 1.94 V 1000 = 1.46 V 1001 = 1.58 V 1010 = 1.70 V (default for AD9680-1000 and AD9680-820) 1011 = 1.82 V 1100 = 2.06 V (default for AD9680-500)				0x0A for AD9680- 1000 and AD9680- 820; 0x0C for AD9680- 500	V p-p differ- ential; use in conjunc- tion with Reg. 0x030
0x030	Input full- scale control (local)	0	0	0	See Table 1 for diff A A A	Full-scale conf 0 for recomm erent frequen default value D9680-1000 = D9680-820 = D9680-500 = D-500 = 110 (f	ended settings cy bands; es: = 110 101	0	0		Used in conjunc- tion with Reg. 0x025
	nction Registers	•		•							
0x024	V_1P0 control	0	0	0	0	0	0	0	1.0 V reference select 0 = internal 1 = external	0x00	
0x028	Temperature diode	0	0	0	0	0	0	0	Diode selection 0 = no diode selected 1 = temper- ature diode selected	0x00	Used in conjunc- tion with Reg. 0x040

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x03F	PDWN/ STBY pin control (local)	0 = PDWN/ STBY enabled 1 = disabled	0	0	0	0	0	0	0	0x00	Used in conjunc- tion with Reg. 0x040
0x040	Chip pin control	PDWN/STB' 00 = pow 01 = sta 10 = dis	er down andby	000 = 001 = JE 010 = JESD2	st Detect B (FD Fast Detect B c ESD204B LMFC 04B internal SY 111 = disabled	output 000 = Fast Detect A output Coutput 001 = JESD204B LMFC output YNC~ output 010 = JESD204B internal SYNC~ output			utput output NC~ output	0x3F	
0x10B	Clock divider	0	0	0	0	0	000 = divide by 1 001 = divide by 2 011 = divide by 4 111 = divide by 8				
0x10C	Clock divider phase (local)	0	0	0	0	0 0 0 0 0 0	ntly controls Channel A and Channel B clock divider phase offset 000 = 0 input clock cycles delayed 101 = ½ input clock cycles delayed 101 = 1 input clock cycles delayed 11 = 1½ input clock cycles delayed 100 = 2 input clock cycles delayed 101 = 2½ input clock cycles delayed 11 = 1½ input clock cycles delayed			0x00	
0x10D	Clock divider and SYSREF control	Clock divider auto phase adjust 0 = disabled 1 = enabled	0	0	0	Clock diviskew 00 = no no 01 = 1 de negat 10 = 2 dev negat	der negative window egative skew vice clock of ive skew vice clocks of ive skew vice skew vice clocks of ive skew vice skew vice skew vice skew vice clocks of positive skew vice			0x00	Clock divider must be >1
0x117	Clock delay control	0	0	0	0	0	0	0	Clock fine delay adjust enable 0 = disabled 1 = enabled	0x00	Enabling the clock fine delay adjust causes a datapath reset
0x118	Clock fine delay (local)		twos compl	I lement coded	control to adju ≤ -88 = - -87 = - 0 = 0	lelay adjust[7:1 st the fine san 151.7 ps skew 150 ps skew  0 ps skew  +150 ps skew	nple clock skew i	in ~1.7 ps steps	I.	0x00	Used in con- junction with Reg. 0x0117
0x11C	Clock status	0	0	0	0	0	0	0	0 = no input clock detected 1 = input clock detected	Read only	
0x120	SYSREF± Control 1	0	SYSREF± flag reset 0 = normal operat- ion 1 = flags held in reset	0	SYSREF± transition select 0 = low to high 1 = high to low	CLK± edge select 0 = rising 1 = falling	00 = di 01 = cor	node select isabled ntinuous N shot	0	0x00	

Reg Addr	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x121	SYSREF± Control 2	0	0	0	0	000 0010 =	YSREF N-shot ign 0000 = next \$ 1 = ignore the first ignore the first t = ignore the first	lect nsition ansitions	0x00	Mode select (Reg 0x120, Bits [2:1]) must be N-shot	
0x123	SYSREF± timestamp delay control					± timestamp of 0x00 = no d 0x01 = 1 clock  c7F = 127 cloc	delay			0x00	lgnored when Reg. 0x01FF = 0x00
0x128	SYSREF± Status 1	SYSR		us, Register 0x1 o Table 28			REF± setup status	28[3:0],	Read only		
0x129	SYSREF± and clock divider status	0	0	0	0	0001 = 0010 : 00 0	ivider phase whe 0000 = i = SYSREF± is ½ cy = SYSREF± is 1 cy 011 = 1½ input cl 0100 = 2 input cl 101 = 2½ input cl	om clock om clock oyed ved oyed	Read only		
0x12A	SYSREF± counter		S	YSREF counter	, Bits[7:0] incre		$111 = 7\frac{1}{2}$ input class SYSREF± is capt		yed	Read only	
0x1FF	Chip sync mode							, 00 = 1	zation mode normal nestamp	0x00	
0x200	Chip application mode	0	0	Chip Q ignore 0 = normal (I/Q) 1 = ignore (I only)	0	0	0	Chip opera 00 = full band 01 = DI 10 = DDC 0 a 11 = DDC	ating mode dwidth mode DC 0 on and DDC 1 on C 0, DDC 1, d DDC 3 on	0x00	
0x201	Chip decimation ratio	0	0	0	0	0	000 = full sa 001 010 011	ecimation ratio ample rate (dec = decimate by = decimate by = decimate by = decimate by	select cimate = 1) y 2 y 4 y 8	0x00	
0x228	Customer offset		0	ffset adjust in L	SBs from +127	to –128 (two:	s complement fo	rmat)		0x00	
0x245	Fast detect (FD) control (local)	0	0	0	0	Force FD_A/ FD_B pins; 0 = normal function; 1 = force to value	Force value of FD_A/FD_B pins if force pins is true, this value is output on FD pins	0	Enable fast detect output	0x00	
0x247	FD upper threshold LSB (local)			F	ast detect uppe	er threshold, E	Bits[7:0]			0x00	
0x248	FD upper threshold MSB (local)	0	0	0		Fast detect upper threshold, Bits[12:8]				0x00	
0x249	FD lower threshold LSB (local)			F	ast detect lowe	er threshold, B		0x00			
0x24A	FD lower threshold MSB (local)	0	0	0		Fast dete	ct lower threshol		0x00		
0x24B	FD dwell time LSB (local)			1	Fast detect d	well time, Bits		0x00			

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x24C	FD dwell time MSB (local)	(MSD)	_   Dico		Fast detect d				Dit 0 (E35)	0x00	Notes
0x26F	Signal monitor synchroniza- tion control	0	0	0	0	0	0	00 = 0 01 = 0	zation mode disabled ontinuous one shot	0x00	Refer to the Signal Monitor section
0x270	Signal monitor control (local)	0	0	0	0	0	0	Peak detector 0 = disabled 1 = enabled	0	0x00	
0x271	Signal Monitor Period Register 0 (local)		Signal monitor period, Bits[7:0]  Signal monitor period, Bits[15:8]								
0x272	Signal Monitor Period Register 1 (local)	Signal monitor period, Bits[15:8]								0x00	In deci- mated output clock cycles
0x273	Signal Monitor Period Register 2 (local)	Signal monitor period, Bits[23:16]							0x00	In deci- mated output clock cycles	
0x274	Signal monitor result control (local)	0	0	0	Result update 1 = update results (self clear)	0	0	0	Result selection 0 = reserved 1 = peak detector	0x01	
0x275	Signal Monitor Result Register 0 (local)	Wher	n Register (	x0274[0] = 1, r		itor result, Bits peak detecto		ue [12:0]; result bits	s [6:0] = 0	Read only	Updated based or Reg. 0x274[4]
0x276	Signal Monitor Result Register 1 (local)				Signal monit	tor result, Bits	[15:8]			Read only	Updated based or Reg. 0x274[4]
0x277	Signal Monitor Result Register 1 (local)	0	0	0	0		Signal moni	tor result, Bits[19:1	6]	Read only	Updated based or Reg. 0x274[4]
0x278	Signal monitor period counter result (local)	Period count result, Bits[7:0]								Read only	Updated based or Reg. 0x274[4]
0x279	Signal monitor SPORT over JESD204B control (local)	0	0	0	0	0	0		reserved enable	0x00	
0x27A	SPORT over JESD204B input selection (local)	0	0	0	0	0	0	Peak detector 0 = disabled 1 = enabled	0	0x00	

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
· ·	nction Registers (S					1			1 210 2 (222)		1
0x300	DDC synchro- nization control	0	0	0	DDC NCO soft reset 0 = normal operation 1 = reset	0	0	Synchronization mode (triggered by SYSREF±) 00 = disabled 01 = continuous 11 = one shot			
0x310	DDC 0 control	Mixer select 0 = real mixer 1 = complex mixer	Gain select 0 = 0 dB gain 1 = 6 dB gain	frequei 00 = varia (mixers en. 01 = 0 Hz II bypassed, 10 = f <sub>ADC</sub> /4 dc m 11 = test inputs fo	ermediate ncy) mode able IF mode s and NCO abled) F mode (mixer NCO disabled) 4 Hz IF mode own-mixing node) mode (mixer orced to +fs, enabled)	Complex to real enable 0 = disabled 1 = enabled	0	Decimation rate select (complex to real disabled)  11 = decimate by 2  00 = decimate by 8  10 = decimate by 16 (complex to real enabled)  11 = decimate by 1  00 = decimate by 2  01 = decimate by 4  10 = decimate by 8		0x00	
0x311	DDC 0 input selection	0	0	0	0	0	Q input select 0 = Ch A 1 = Ch B	0	I input select 0 = Ch A 1 = Ch B	0x00	Refer to the DDC section
0x314	DDC 0 frequency LSB		•	. [	DDC 0 NCO freq twos co	uency value, E omplement	Bits[7:0]	•	0x00		
0x315	DDC 0 frequency MSB	Х	X	Х	X	DI	DC 0 NCO freque twos con	0x00			
0x320	DDC 0 phase LSB		1	•	DDC 0 NCO ph twos co	nase value, Bit omplement	rs[7:0]		0x00		
0x321	DDC 0 phase MSB	X	Х	X	Х		DDC 0 NCO phase value, Bits[11:8] twos complement				
0x327	DDC 0 output test mode selection	0	0	0	0	0	Q output test mode enable 0 = disabled 1 = enabled from Channel B	0	I output test mode enable 0 = disabled 1 = enabled from Channel A	0x00	Refer to the DDC section
0x330	DDC 1 control	Mixer select 0 = real mixer 1 = complex mixer	Gain select 0 = 0 dB gain 1 = 6 dB gain	frequei 00 = varia (mixers en. 01 = 0 Hz I bypassed, 10 = f <sub>ADC</sub> /4 d m 11 = test inputs fo	ermediate ency) mode able IF mode s and NCO abled) F mode(mixer NCO disabled) 4 Hz IF mode ownmixing node) mode (mixer orced to +fs, enabled)	Complex to real enable 0 = disabled 1 = enabled	0	Decimation rate select (complex to real disabled)  11 = decimate by 2  00 = decimate by 4  01 = decimate by 16 (complex to real enabled)  11 = decimate by 1  00 = decimate by 1  11 = decimate by 1  00 = decimate by 1		0x00	
0x331	DDC 1 input selection	0	0	0	0	0	Q input select 0 = Ch A 1 = Ch B	0	I input select 0 = Ch A 1 = Ch B	0x05	Refer to the DDC section
0x334	DDC 1 frequency LSB	DDC 1 NCO frequency value, Bits[7:0] twos complement								0x00	
0x335	DDC 1 frequency MSB	Х	X	X	X	DI	DC 1 NCO freque twos con	11:8]	0x00		

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x340	DDC 1 phase LSB	(	1 2		DDC 1 NCO pl			1		0x00	
0x341	DDC 1 phase MSB	Х	Х	Х	X		DDC 1 NCO phase twos com		:8]	0x00	
0x347	DDC 1 output test mode selection	0	0	0	0	0	Q output test mode enable 0 = disabled 1 = enabled from Ch B	0	I output test mode enable 0 = disabled 1 = enabled from Ch A	0x00	Refer to the DDC section
0x350	DDC 2 control	Mixer select 0 = real mixer 1 = complex mixer	Gain select 0 = 0 dB gain 1 = 6 dB gain	00 = varia (mixers ena 01 = 0 Hz   I bypassed,   I 10 = f <sub>ADC</sub> /4 dd m 11 = test i inputs fo	mode able IF mode s and NCO abled) F mode (mixer NCO disabled) 4 Hz IF mode own-mixing node) mode (mixer orced to +fs, enabled)	Complex to real enable 0 = disabled 1 = enabled	0	(comple disa 11 = deci 00 = deci 10 = deci (comple ena 11 = deci 00 = deci	n rate select ex to real bled) mate by 2 mate by 4 mate by 8 mate by 16 ex to real bled) mate by 17 mate by 18	0x00	
0x351	DDC 2 input selection	0	0	0	0	0	Q input select 0 = Ch A 1 = Ch B	0	I input select 0 = Ch A 1 = Ch B	0x00	Refer to the DDC section
0x354	DDC 2 frequency LSB	DDC 2 NCO frequency value, Bits[7:0] twos complement							0x00		
0x355	DDC2 frequency MSB	Х	X	X	X	DI	DC 2 NCO frequency value, Bits[11:8] twos complement			0x00	
0x360	DDC 2 phase LSB		•	•	DDC 2 NCO pł	nase value, Bit omplement	s[7:0]			0x00	
0x361	DDC 2 phase MSB	Х	Х	Х	Х		DDC 2 NCO phase twos com		:8]	0x00	
0x367	DDC 2 output test mode selection	0	0	0	0	0	Q output test mode enable 0 = disabled 1 = enabled from Ch B	0	I output test mode enable 0 = disabled 1 = enabled from Ch A	0x00	Refer to the DDC section
0x370	DDC 3 control	Mixer select 0 = real mixer 1 = complex mixer	Gain select 0 = 0 db gain 1 = 6 db gain	00 = varia (mixers ena 01 = 0 Hz II bypassed, I 10 = f <sub>ADC</sub> /4 dc (f <sub>ADC</sub> /4 dc m 11 = test i inputs fo	mode able IF mode s and NCO abled) F mode(mixer NCO disabled) 4 Hz IF mode ownmixing node) mode (mixer orced to +fs, enabled)	Complex to real enable 0 = disabled 1 = enabled	0	(comple disa 11 = deci 00 = deci 10 = deci (comple ena 11 = deci 00 = deci	n rate select ex to real bled) mate by 2 mate by 4 mate by 8 mate by 16 ex to real bled) mate by 17 mate by 18	0x00	
0x371	DDC 3 input selection	0	0	0	0	0	Q input select 0 = Ch A 1 = Ch B	0	I input select 0 = Ch A 1 = Ch B	0x05	Refer to the DDC section

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x374	DDC 3 frequency LSB	(	1		DC 3 NCO freq		e, Bits[7:0]	1		0x00	
0x375	DDC 3 frequency MSB	Х	X	X	X		DDC 3 NCO frequer twos com		s[11:8]	0x00	
0x380	DDC3 phase LSB		1		DDC 3 NCO pł	nase value, I omplement			0x00		
0x381	DDC 3 phase MSB	Х	Х	Х	X		DDC 3 NCO phas twos com	0x00			
0x387	DDC 3 output test mode selection	0	0	0	0	0	Q output test mode enable 0 = disabled 1 = enabled from Ch B	0	I output test mode enable 0 = disabled 1 = enabled from Ch A	0x00	Refer to the DDC section
	Outputs and Test N		-	1	T	I				T	I
0x550	ADC test modes (local)	User pattern selection 0 = cont- inuous repeat 1 = single pattern	0	Reset PN long gen 0 = long PN enable 1 = long PN reset	Reset PN short gen 0 = short PN enable 1 = short PN reset	Test mode selection  0000 = off, normal operation  0001 = midscale short  0010 = positive full scale  0011 = negative full scale  0100 = alternating checker board  0101 = PN sequence, long  0110 = PN sequence, short  0111 = 1/0 word toggle  1000 = the user pattern test mode (used with Register 0x0550, Bit 7 and User Pattern 1 to  User Pattern 4 registers)  1111 = ramp output				0x00	
0x551	User Pattern 1 LSB	0	0	0	0	0	0	0	0	0x00	Used with Reg. 0x550 and Reg. 0x573
0x552	User Pattern 1 MSB	0	0	0	0	0	0	0	0	0x00	Used with Reg. 0x550 and Reg. 0x573
0x553	User Pattern 2 LSB	0	0	0	0	0	0	0	0	0x00	Used with Reg. 0x550 and Reg. 0x573
0x554	User Pattern 2 MSB	0	0	0	0	0	0	0	0	0x00	Used with Reg. 0x550 and Reg. 0x573
0x555	User Pattern 3 LSB	0	0	0	0	0	0	0	0	0x00	Used with Reg. 0x550 and Reg. 0x573
0x556	User Pattern 3 MSB	0	0	0	0	0	0	0	0	0x00	Used with Reg. 0x550 and Reg. 0x573

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x557	User Pattern 4 LSB	0	0	0	0	0	0	0	0	0x00	Used with Reg. 0x550 and Reg. 0x573
0x558	User Pattern 4 MSB	0	0	0	0	0	0	0	0	0x00	Used with Reg. 0x550 and Reg. 0x573
0x559	Output Mode Control 1	0	0 0 011	ter Control Bit 1000 = tie low (1 101 = overrang = fast detect ( 101 = SYSREF d when CS (Reg = 2 or 3	'b0) e bit FD) bit :±	0	000 001 011 =	r Control Bit 0 s 0 = tie low (1'b 1 = overrange b fast detect (FE 01 = SYSREF± nen CS (Registe	0) oit )) bit	0x00	
0x55A	Output Mode Control 2	0	0	0	0	0	000 001 011 =	r Control Bit 2 s 0 = tie low (1'b 1 = overrange b fast detect (FE 101 = SYSREF 5 (Register 0x58	0) pit D) bit	0x01	
0x561	Output mode	0	0	0	0	0	Sample invert 0 = normal 1 = sample invert	00 = offs	mat select set binary complement	0x01	
0x562	Output overrange (OR) clear	Virtual Converter 7 OR 0 = OR bit enabled 1 = OR bit cleared	Virtual Convert- er 6 OR 0 = OR bit enabled 1 = OR bit cleared	Virtual Converter 5 OR 0 = OR bit enabled 1 = OR bit cleared	Virtual Converter 4 OR 0 = OR bit enabled 1 = OR bit cleared	Virtual Convert- er 3 OR 0 = OR bit enabled 1 = OR bit cleared	Virtual Converter 2 OR 0 = OR bit enabled 1 = OR bit cleared	Virtual Converter 1 OR 0 = OR bit enabled 1 = OR bit cleared	Virtual Converter 0 OR 0 = OR bit enabled 1 = OR bit cleared	0x00	
0x563	Output OR status	Virtual Converter 7 OR 0 = no OR 1 = OR occurred	Virtual Convert- er 6 OR 0 = no OR 1 = OR occurred	Virtual Converter 5 OR 0 = no OR 1 = OR occurred	Virtual Converter 4 OR 0 = no OR 1 = OR occurred	Virtual Convert- er 3 OR 0 = no OR 1 = OR occurred	Virtual Converter 2 OR 0 = no OR 1 = OR occurred	Virtual Converter 1 OR 0 = no OR 1 = OR occurred	Virtual Converter 0 OR 0 = no OR 1 = OR occurred	0x00	Read only
0x564	Output channel select	0	0	0	0	0	0	0	Converter channel swap 0 = normal channel ordering 1 = channel swap enabled	0x00	
0x56E	JESD204B lane rate control	0	0	0	0 = serial lane rate ≥6.25 Gbps and ≤12.5 Gbps 1 = serial lane rate must be ≥ 3.125 Gbps and ≤6.25 Gbps	0	0	0	0	0x00 for AD9680- 1000 and AD9680- 820; 0x10 for AD9680- 500	

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x56F	JESD204B PLL lock status	PLL lock 0 = not locked 1 = locked	0	0	0	0	0	0	0	0x00	Read only
0x570	JESD204B quick config- uration	JESD204B quick configuration L = number of lanes = $2^{\text{Register 0x570, Bits[7:6]}}$ M = number of converters = $2^{\text{Register 0x570, Bits[5:3]}}$ F = number of octets/frame = $2^{\text{Register 0x570, Bits[2:0]}}$								0x88 for AD9680- 1000 and AD9680- 820; 0x49 for AD9680- 500	Refer to Table 26 and Table 27
0x571	JESD204B Link Mode Control 1	Standby mode 0 = all converter outputs 0 1 = CGS (/K28.5/)	Tail bit (t) PN 0 = disable 1 = enable T = N' - N - CS	Long transport layer test 0 = disable 1 = enable	Lane synch- ronization 0 = disable FACI uses /K28.7/ 1 = enable FACI uses /K28.3/ and /K28.7/	11 = ILAS always on test 1 =		0 = enabled	Link control 0 = active 1 = power down	0x14	
0x572	JESD204B Link Mode Control 2	SYNCINB± p 00 = normal 10 = ignore s (force CGS) 11 = ignore s (force ILAS/u	SYNCINB±	SYNCINB± pin invert 0 = active low 1 = active high	SYNCINB± pin type 0 = differential 1 = CMOS	0	8-bit/10-bit bypass 0 = normal 1 = bypass	8-/10-bit bit invert 0 = normal 1 = invert the abcd efghij symbols	0	0x00	
0x573	JESD204B Link Mode Control 3	CHKSUM mode  00 = sum of all 8-bit link     config registers 01 = sum of individual     link config fields 10 = checksum set to     zero  Test injection point 00 = N' sample input 01 = 10-bit data at 8-bit/10-bit output (for PHY testing) 10 = 8-bit data at scrambler input				001 010 010 01 01	JESD204B test = normal operation 0001 = alternation 0010 = 1/0 v 1 = 31-bit PN seq 0 = 23-bit PN seq 1 = 15-bit PN seq 10 = 9-bit PN seq 11 = 7-bit PN seq 1000 = rar 1110 = continuou 1111 = since	disabled) rd X <sup>28</sup> + 1 X <sup>18</sup> + 1 X <sup>14</sup> + 1 5 + 1 6 + 1	0x00		
0x574	JESD204B Link Mode Control 4	ILAS delay  0000 = transmit ILAS on first LMFC after SYNCINB± deasserted  0001 = transmit ILAS on second LMFC after SYNCINB± deasserted  1111 = transmit ILAS on 16th LMFC after SYNCINB± deasserted				0	Link layer test mode  000 = normal operation (link layer test mode disabled)  001 = continuous sequence of /D21.5/ characters  100 = modified RPAT test sequence 101 = JSPAT test sequence 110 = JTSPAT test sequence			0x00	
0x578	JESD204B LMFC offset	0	0	0		LMF	C phase offset val			0x00	
0x580	JESD204B DID config		1	1	JESD204B T	x DID value[7	:0]			0x00	
0x581	JESD204B BID config	0	0	0	0	JESD204B Tx BID value, Bits[3:0]				0x00	
0x583	JESD204B LID Config 1	0	0	0	Lane 0 LID value, Bits[4:0]						
0x584	JESD204B LID Config 2	0	0	0	Lane 1 LID value, Bits[4:0]						
0x585	JESD204B LID Config 3	0	0	0	Lane 2 LID value, Bits[4:0]						
0x586	JESD204B LID Config 4	0	0	0		Lar	ne 3 LID value, Bit	s[4:0]		0x03	

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x58B	JESD204B parameters SCR/L	JESD204B scrambling (SCR) 0 = disabled 1 = enabled	0	0	0	0	0	JESD204 00 = 01 = 11 = Read 0	Blanes (L) 1 lane 2 lanes 4 lanes only, see er 0x570	0x8X	Notes
0x58C	JESD204B F config			Number o	of octets per f	rame, F = Regi	ster 0x58C[7:0] + 1	1		0x88	Read only, see Reg 0x570
0x58D	JESD204B K config	0	0	0		ber of frames Only values w		0x1F	See Reg 0x570		
0x58E	JESD204B M config			0x00 = lir $0x01 = lin$ $0x03 = lin$	nk connected k connected k connected	onverters per to one virtual to two virtual to four virtual to eight virtua			Read only		
0x58F	JESD204B CS/N config	Number of a (CS) per: 00 = no co (CS = 01 = 1 contr 1); Control 10 = 2 cor (CS = 2); Co and 1 11 = 3 cor (CS = 3); all a (2, 1)	sample ntrol bits = 0) ol bit (CS = Bit 2 only ntrol bits ntrol Bit 2 only ntrol bits control bits	0		AE		0x0F			
0x590	JESD204B N' config	0	0	Subclass support (Subclass V) 0 = Subclass 0 (no deter- ministic latency) 1 = Subclass 1		ADC r		0x2F			
0x591	JESD204B S config	0	0	1			es per converter fra lue = Register 0x59			0x20	Read only
0x592	JESD204B HD and CF config	HD value 0 = disabled 1 = enabled	0	0		Control wor	ds per frame clock lue = Register 0x5	cycle per link (C	CF)	0x80	Read only
0x5A0	JESD204B CHKSUM 0		<u> </u>	CH	IKSUM value	for SERDOUT	0±, Bits[7:0]			0x81	Read only
0x5A1	JESD204B CHKSUM 1			CH	HKSUM value	for SERDOUT	1±, Bits[7:0]			0x82	Read only
0x5A2	JESD204B CHKSUM 2			CH	HKSUM value	for SERDOUT	2±, Bits[7:0]			0x82	Read only
0x5A3	JESD204B CHKSUM 3			CH	KSUM value	for SERDOUT:	3±, Bits[7:0]			0x84	Read only
0x5B0	JESD204B lane power- down	1	SERD- OUT3± 0 = on 1 = off	1	SERD- OUT2± 0 = on 1 = off	JT2± OUT1± OUT0± 0=on 0=on					
0x5B2	JESD204B lane SERDOUT0± assign	X	X	Х	X	off         1 = off         1 = off           0         SERDOUT0± lane assignment 000 = Logical Lane 0 001 = Logical Lane 1 010 = Logical Lane 2 011 = Logical Lane 3					

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x5B3	JESD204B lane SERDOUT1± assign	X	Х	Х	X	0	000 001 010	T1± lane assig = Logical Lane = Logical Lane = Logical Lane = Logical Lane	nment e 0 e 1 e 2	0x11	
0x5B5	JESD204B lane SERDOUT2± assign	Х	Х	Х	X	0	SERDOL 000 001 010	T2± lane assig = Logical Lane = Logical Lane = Logical Lane = Logical Lane	nment e 0 e 1 e 2	0x22	
0x5B6	JESD204B lane SERDOUT3± assign	Х	X	Х	Х	0	SERDOL 000 001 010 011	e 0 e 1 e 2	0x33		
0x5BF	JESD serializer drive adjust	0	0	0	0	011 = Logical Lane 3  Swing voltage 0000 = 237.5 mV 0001 = 250 mV 0010 = 262.5 mV 0011 = 275 mV 0101 = 287.5 mV 0101 = 300 mV (default) 0110 = 312.5 mV 0111 = 325 mV 1000 = 337.5 mV 1001 = 350 mV 1011 = 375 mV 1011 = 375 mV 1111 = 475 mV				0x05	
0x5C1	De-emphasis select	0	SERD- OUT3± 0 = disable 1 = enable	0	SERD- OUT2± 0 = disable 1 = enable	0	SERDOUT1± 0 = disable 1 = enable	0	SERD- OUT0± 0 = disable 1 = enable	0x00	
0x5C2	De-emphasis setting for SERDOUT0±	0	0	0	0		SERDOUT0± de-e 0000 = 0001 = 0010 = 0011 = 0100 = 0101 = 0110 = 0111 =	gs	0x00		
0x5C3	De-emphasis setting for SERDOUT1±	0	0	0	0	SERDOUT1± de-emphasis settings 0000 = 0 dB 0001 = 0.3 dB 0010 = 0.8 dB 0011 = 1.4 dB 0100 = 2.2 dB 0101 = 3.0 dB 0110 = 4.0 dB 0111 = 5.0 dB					
0x5C4	De-emphasis setting for SERDOUT2±	0	0	0	0						

Reg Addr (Hex)	Register Name	Bit 7 (MSB)	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 (LSB)	Default	Notes
0x5C5	De-emphasis setting for SERDOUT3±	0	0	0	0	S	SERDOUT3± de-ei 0000 = 0001 = 0010 = 0011 = 0100 = 0101 = 0110 = 0111 =	0 dB 0.3 dB 0.8 dB 1.4 dB 2.2 dB 3.0 dB 4.0 dB	gs	0x00	

# APPLICATIONS INFORMATION POWER SUPPLY RECOMMENDATIONS

The AD9680 must be powered by the following seven supplies: AVDD1 = 1.25 V, AVDD2 = 2.5 V, AVDD3 = 3.3 V, AVDD1\_SR = 1.25 V, DVDD = 1.25 V, DRVDD = 1.25 V, and SPIVDD = 1.80 V. For applications requiring an optimal high power efficiency and low noise performance, it is recommended that the ADP2164 and ADP2370 switching regulators be used to convert the 3.3 V, 5.0 V, or 12 V input rails to an intermediate rail (1.8 V and 3.8 V). These intermediate rails are then postregulated by very low noise, low dropout (LDO) regulators (ADP1741, ADM7172, and ADP125). Figure 147 shows the recommended power supply scheme for the AD9680.

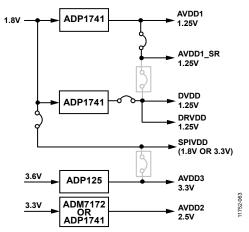


Figure 147. High Efficiency, Low Noise Power Solution for the AD9680

It is not necessary to split all of these power domains in all cases. The recommended solution shown in Figure 147 provides the lowest noise, highest efficiency power delivery system for the AD9680. If only one 1.25 V supply is available, route to AVDD1 first and then tap it off and isolate it with a ferrite bead or a filter choke, preceded by decoupling capacitors for AVDD1\_SR, DVDD, and DRVDD, in that order. This is shown as the optional path in Figure 147. The user can employ several different decoupling capacitors to cover both high and low frequencies. These capacitors must be located close to the point of entry at the PCB level and close to the devices, with minimal trace lengths.

## EXPOSED PAD THERMAL HEAT SLUG RECOMMENDATIONS

The exposed pad on the underside of the ADC must be connected to AGND to achieve the best electrical and thermal performance of the AD9680. Connect an exposed continuous copper plane on the PCB to the AD9680 exposed pad, Pin 0. The copper

plane must have several vias to achieve the lowest possible resistive thermal path for heat dissipation to flow through the bottom of the PCB. These vias must be solder filled or plugged. The number of vias and the fill determine the resulting  $\theta_{\text{JA}}$  measured on the board.

To maximize the coverage and adhesion between the ADC and PCB, partition the continuous copper plane by overlaying a silkscreen on the PCB into several uniform sections. This provides several tie points between the ADC and PCB during the reflow process, whereas using one continuous plane with no partitions only guarantees one tie point. See Figure 148 for a PCB layout example. For detailed information on packaging and the PCB layout of chip scale packages, see the AN-772 Application Note, *A Design and Manufacturing Guide for the Lead Frame Chip Scale Package (LFCSP)*.

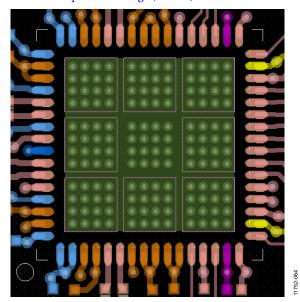


Figure 148. Recommended PCB Layout of Exposed Pad for the AD9680

#### AVDD1 SR (PIN 57) AND AGND (PIN 56 AND PIN 60)

AVDD1\_SR (Pin 57) and AGND (Pin 56 and Pin 60) can be used to provide a separate power supply node to the SYSREF± circuits of AD9680. If running in Subclass 1, the AD9680 can support periodic one-shot or gapped signals. To minimize the coupling of this supply into the AVDD1 supply node, adequate supply bypassing is needed.

## **OUTLINE DIMENSIONS**

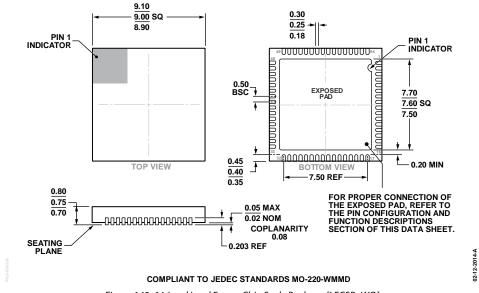


Figure 149. 64-Lead Lead Frame Chip Scale Package [LFCSP\_WQ] 9 mm × 9 mm Body, Very Thin Quad (CP-64-15) Dimensions shown in millimeters

#### **ORDERING GUIDE**

OND ENTITE COIDE			
Model <sup>1</sup>	Temperature Range	Package Description <sup>2</sup>	Package Option
AD9680BCPZ-1000	-40°C to +85°C	64-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-64-15
AD9680BCPZ-820	-40°C to +85°C	64-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-64-15
AD9680BCPZ-500	-40°C to +85°C	64-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-64-15
AD9680BCPZRL7-1000	-40°C to +85°C	64-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-64-15
AD9680BCPZRL7-820	-40°C to +85°C	64-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-64-15
AD9680BCPZRL7-500	-40°C to +85°C	64-Lead Lead Frame Chip Scale Package [LFCSP_WQ]	CP-64-15
AD9680-1000EBZ		Evaluation Board for AD9680-1000	
AD9680-820EBZ		Evaluation Board for AD9680-820	
AD9680-500EBZ		Evaluation Board for AD9680-500	

<sup>&</sup>lt;sup>1</sup> Z = RoHS Compliant Part.



<sup>&</sup>lt;sup>2</sup> The AD9680-1000, AD9680-820, and AD9680-500 evaluation boards are optimized for full analog input frequency range.

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<u>AD9680-1000EBZ</u> <u>AD9680BCPZ-1000</u> <u>AD9680BCPZRL7-1000</u> <u>AD9680BCPZ-500</u> <u>AD9680BCPZRL7-500</u> <u>AD9680BCPZRL</u>